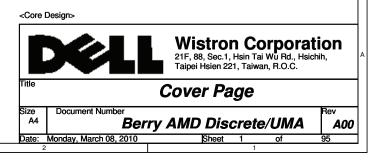
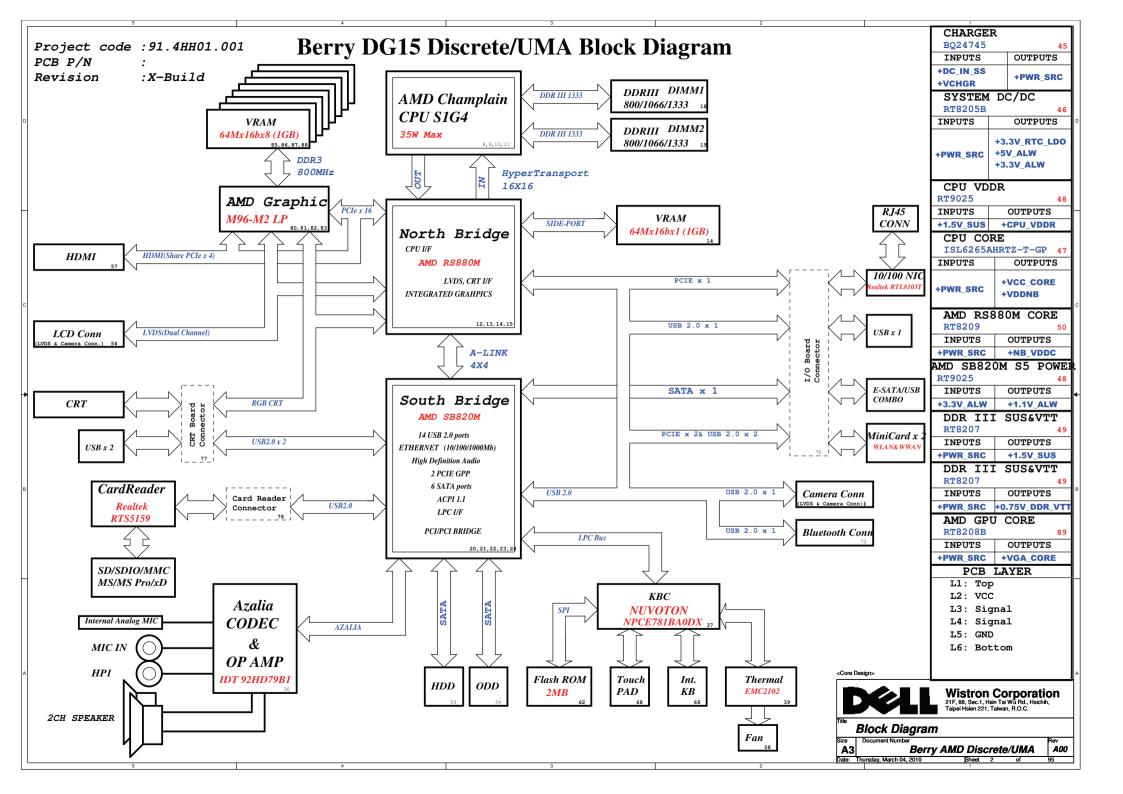
# Berry Discrete/UMA Schematics Document AMD Danube CPU S1g4 AMD GPU Madison-LP/M96-LP M2 RS880M + SB820M

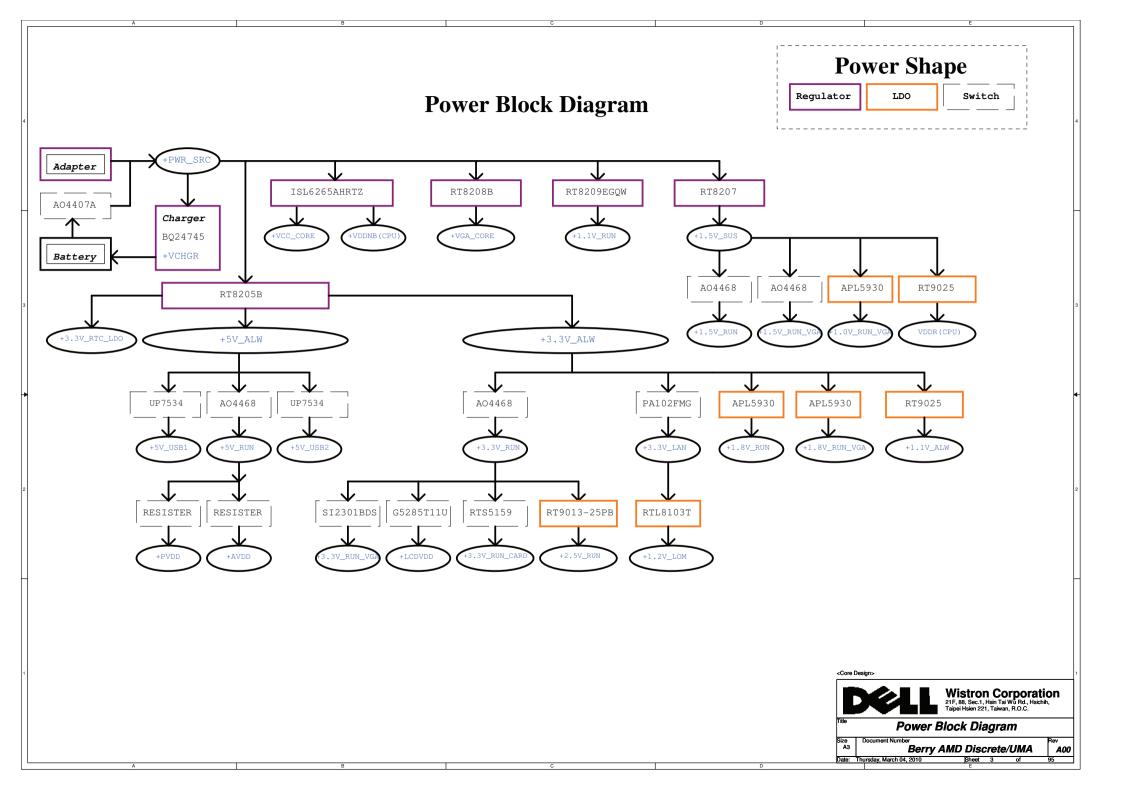
2010-03-08

**REV: A00** 

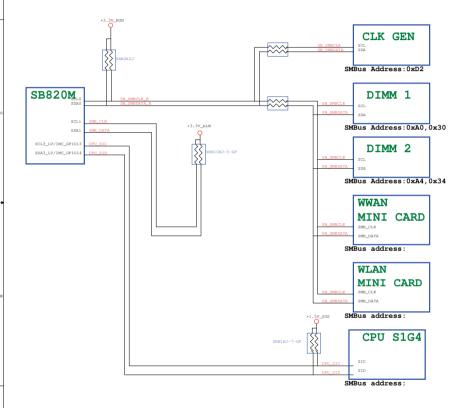
DY : Nopop Component



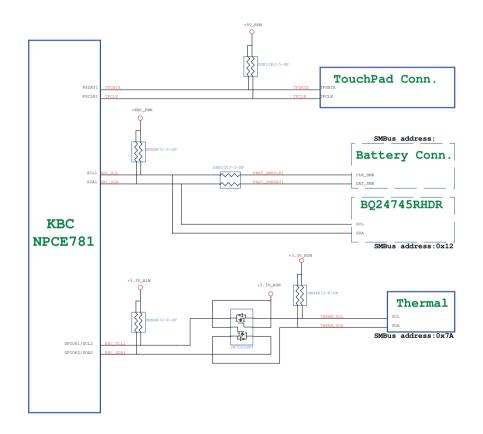




# SB820M SMBus Block Diagram

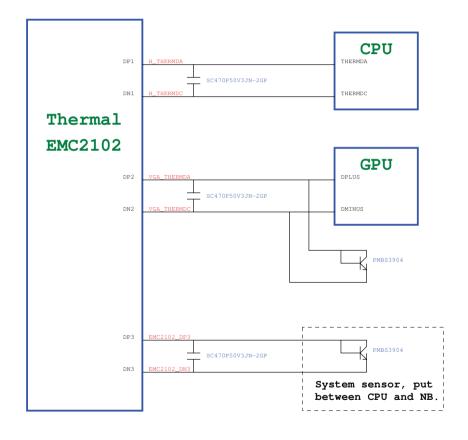


# KBC SMBus Block Diagram

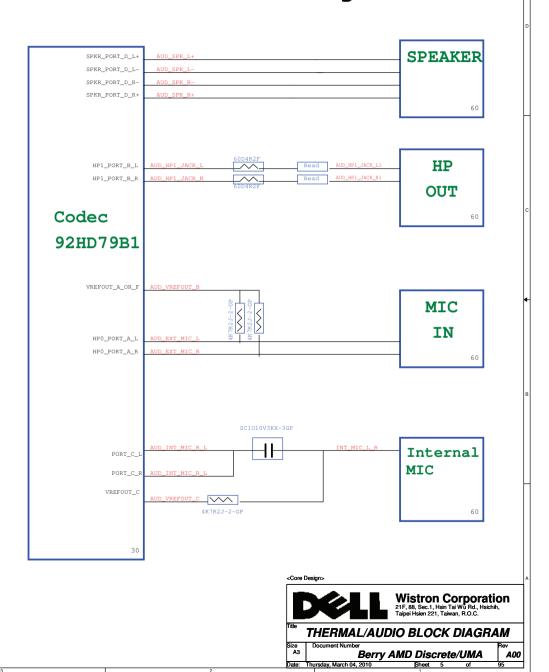




# Thermal Block Diagram



# Audio Block Diagram



### SB820M Strapping

Capture from 45484 Rev. 1.02 AMD SB8xx-Series Southbridge Design Guide

Name	Strap Name	Schematic Note			
LPCCLK0	ECEnableStrap	Embedded Controller (EC)  * 0 V - Disabled 3.3 V - Enabled			
		ROMTYPE_1 ROMTYPE_0 ROM TYPE 3.3V OV SPI ROM			
EC_PWM3	{ROMTYPE_1, ROMTYPE_0 }	3.3V 3.3V Reserved			
EC_PWM2		0V 0V Firmware Hub			
		0V 3.3V LPC ROM  * (supports both LPC and PMC ROM types)			
		Defines clock generator			
LPCCLK1	CLKGEN	* OV - External clock mode: Use 100-MHz PCIeR clock as reference clock and generate i nternal clocks only.			
		3.3V- Integrated clock mode: Use 25-MHz crystal clock and generate both internal and external clocks			
PCICLK1	BIF_GEN2_ COMPLIANCE_Strap	Set PCIe to Gen II mode  OV- Force PCIe interface at Gen I mode  * 3.3V- PCIe interfacce is at Gen II mode Not Applicable to SB820M but provision for pull-down is required.			
PCICLK2	BootFailTmrEn	Watchdog function  * OV- Disable the boot fail timer function 3.3V- Enable the boot fail timer function			
PCICLK3	Default Debug Straps  * 0V- Disable Debug Straps. 3.3V- Select external Debug Straps				
PCICLK4	CPU/NB HT Clock Selection  OV- Reserved.  * 3.3V- Required setting for integrated clock mode. configured for external clock general row mode.				
AZ_SDOUT	CoreSpeedMode	Slow down core clock for low power platform.  * 0V- Performance mode 3.3V- Low Power mode			

### RS880M Strapping

Capture from 46113\_rs880m\_ds\_nda\_1.03

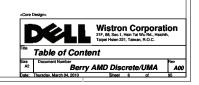
Name	Strap Function	Schematic Note	
DAC_VSYNC	STRAP_DEBUG_BUS_GPIO _ENABLE#	Enables debug bus access through memory I/O pads and GPIOs. 0: Enable * 1: Disable	
DAC_HSYNC	SIDE_PORT_EN#	Indicates if memory side-port is available or not 0: Available(UMA) 1: Not available(Discrete)	
SUS_STAT#	LOAD_EEPROM_STRAPS#	Selects loading of strap values from EEPROM.  0: 12C master can load strap values from EEPROM if connected, or use default values if EEPROM is not connected. Please refer to RS880M's reference schematics for system level implementation details.  * 1: Use default values	

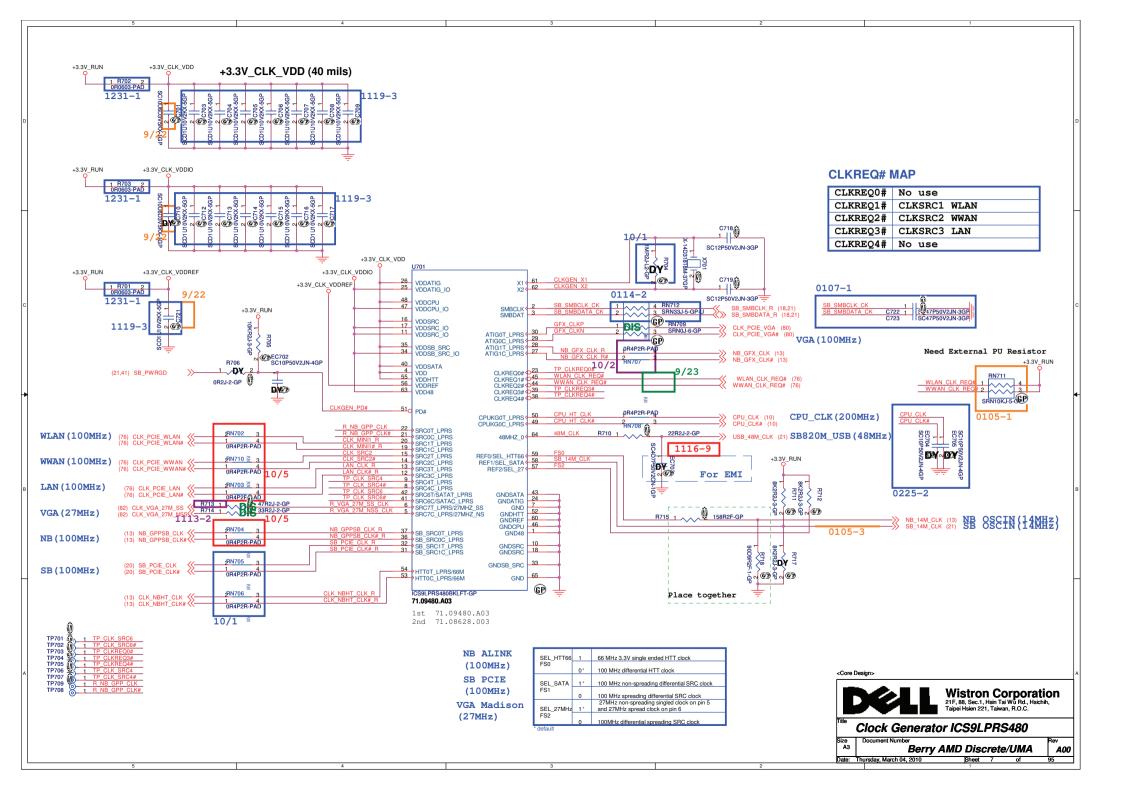
### USB Table

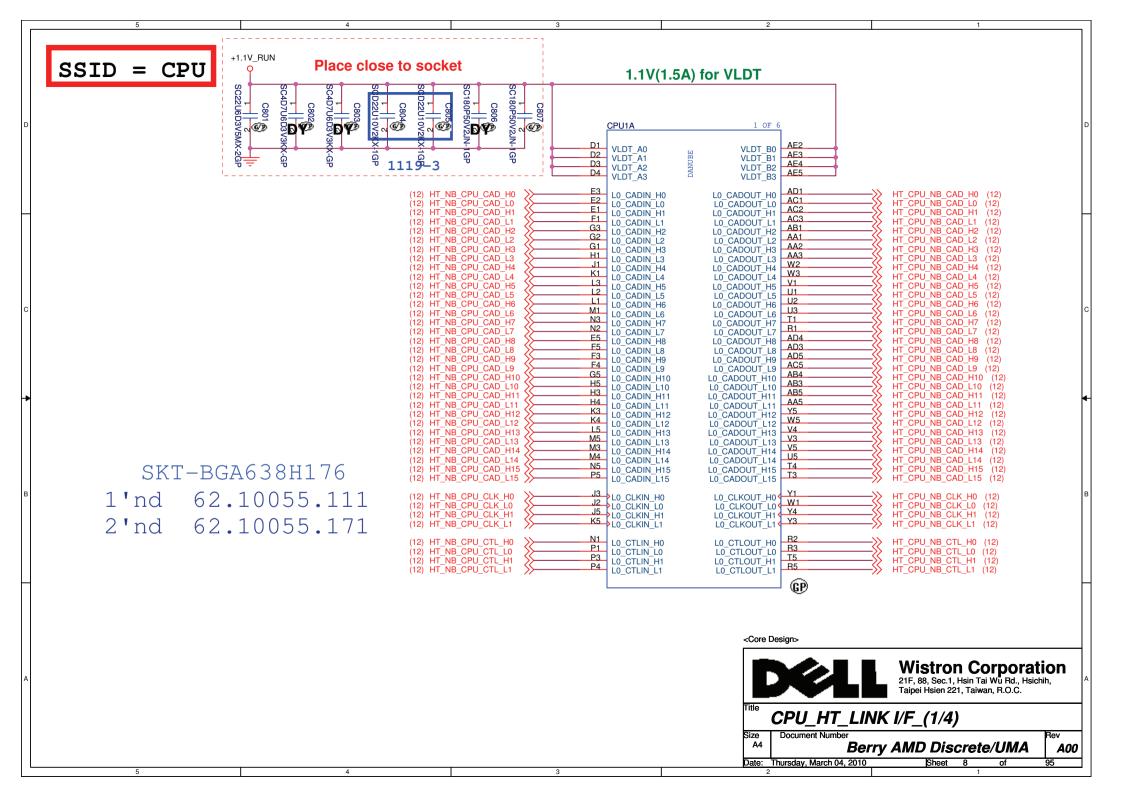
USB				
Pair	Device			
0	USB0 (I/O Board/ESATA)			
1	USB1 (I/O Board)			
2	USB2 (CRT Board)			
3	USB3 (CRT Board)			
4	WLAN USB			
5	WWAN USB			
6	RESERVED			
7	RESERVED			
8	RESERVED			
9	BLUETOOTH			
10	CARD READER			
11	CAMERA (LVDS CONN)			
12	RESERVED			
13	RESERVED			
_				

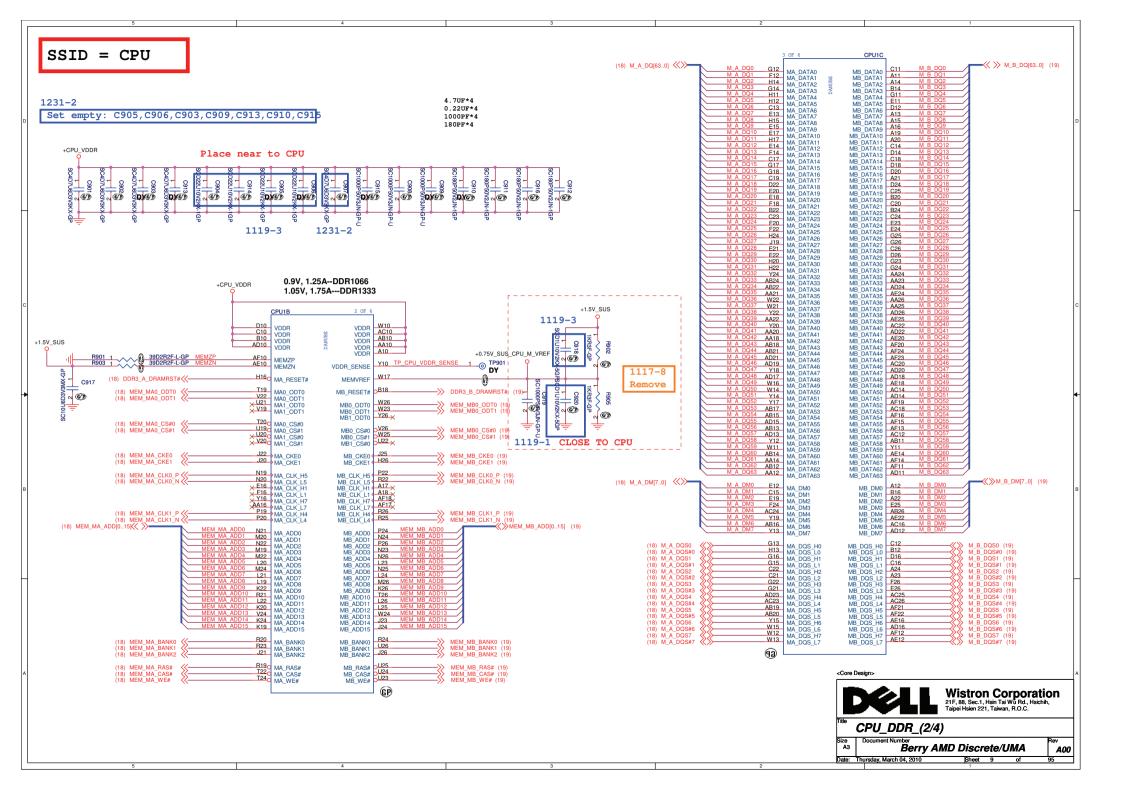
### PCIE Routing

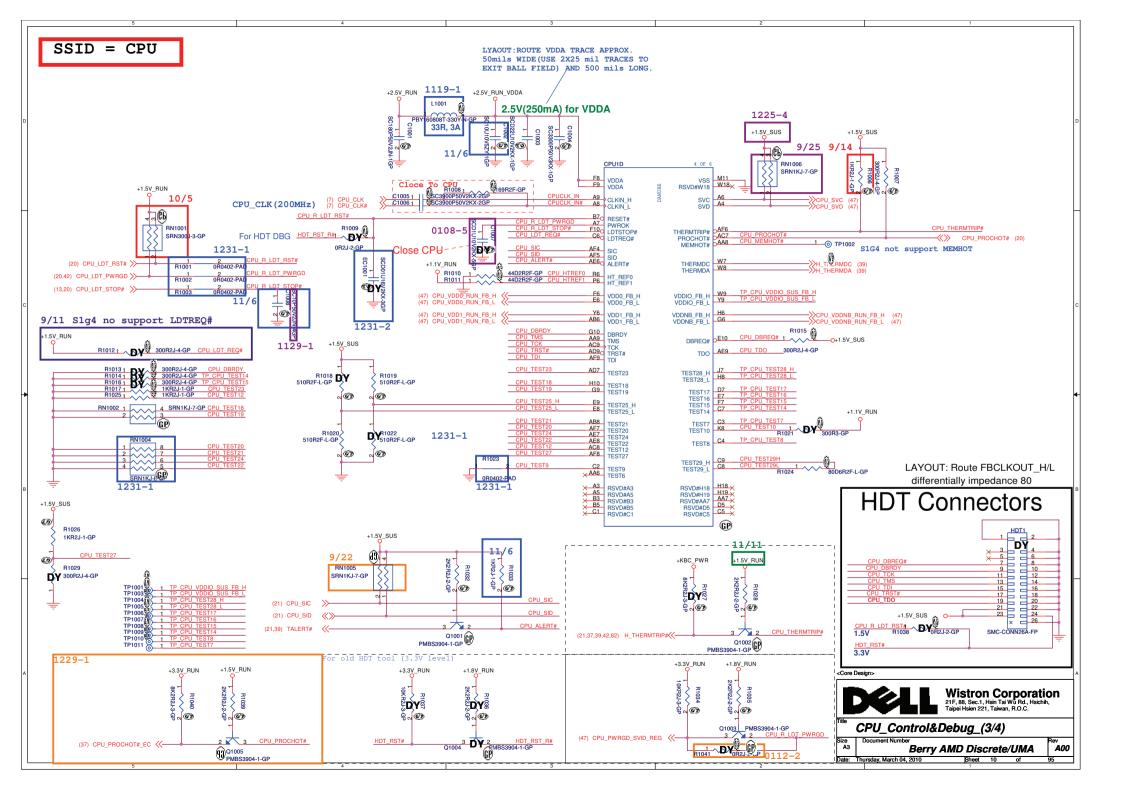
	RS880M		
LANE0	MiniCard WLAN		
LANE1	LAN		
LANE2	MiniCard WWAN		



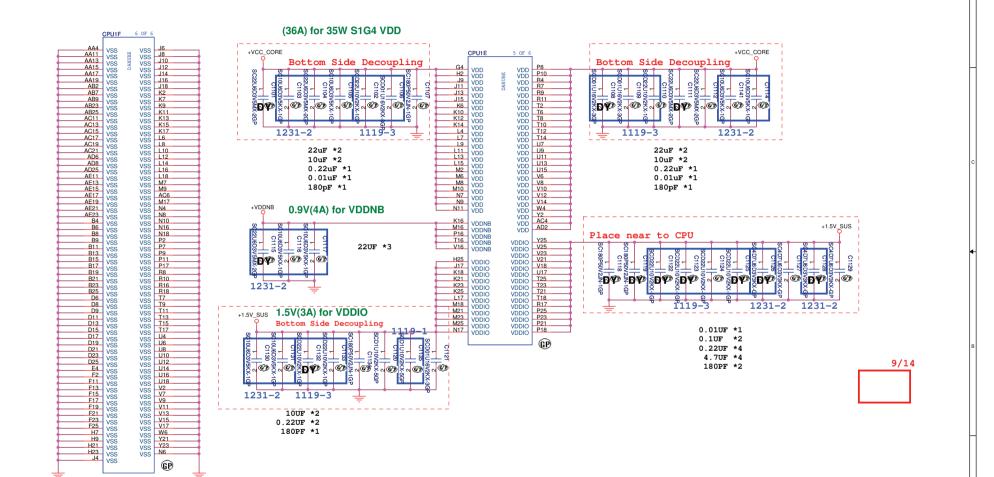


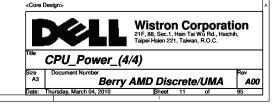


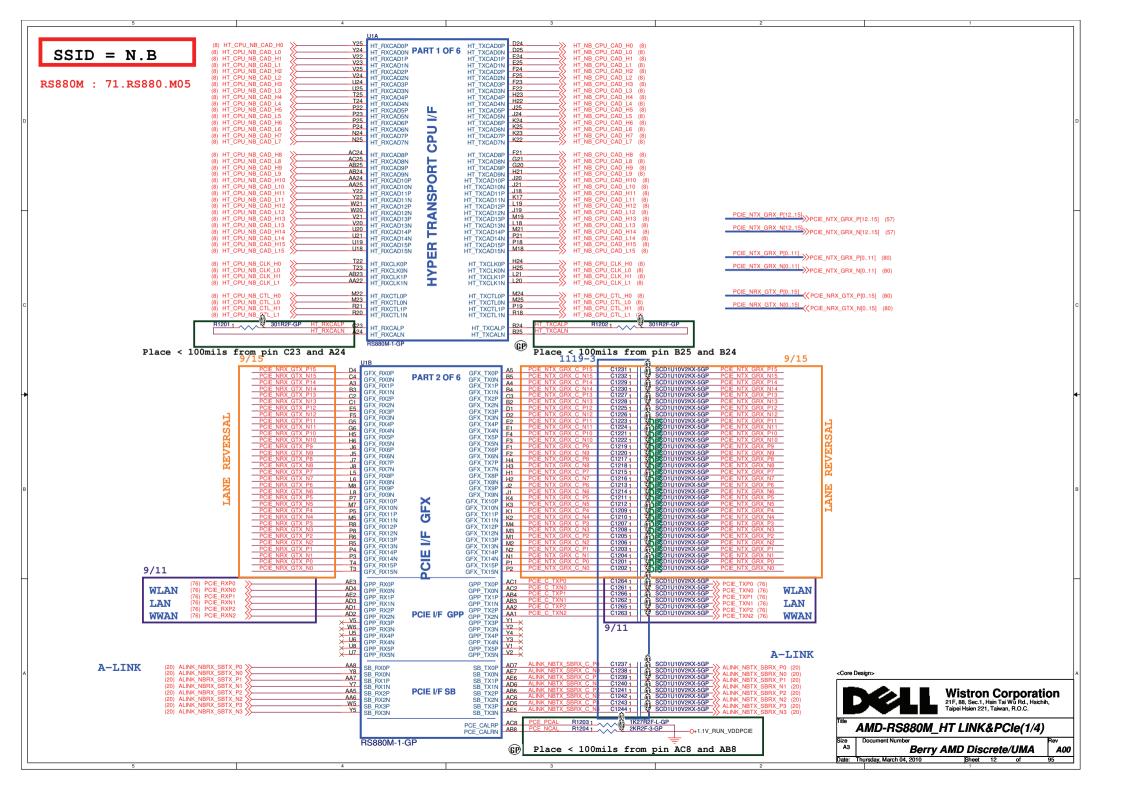


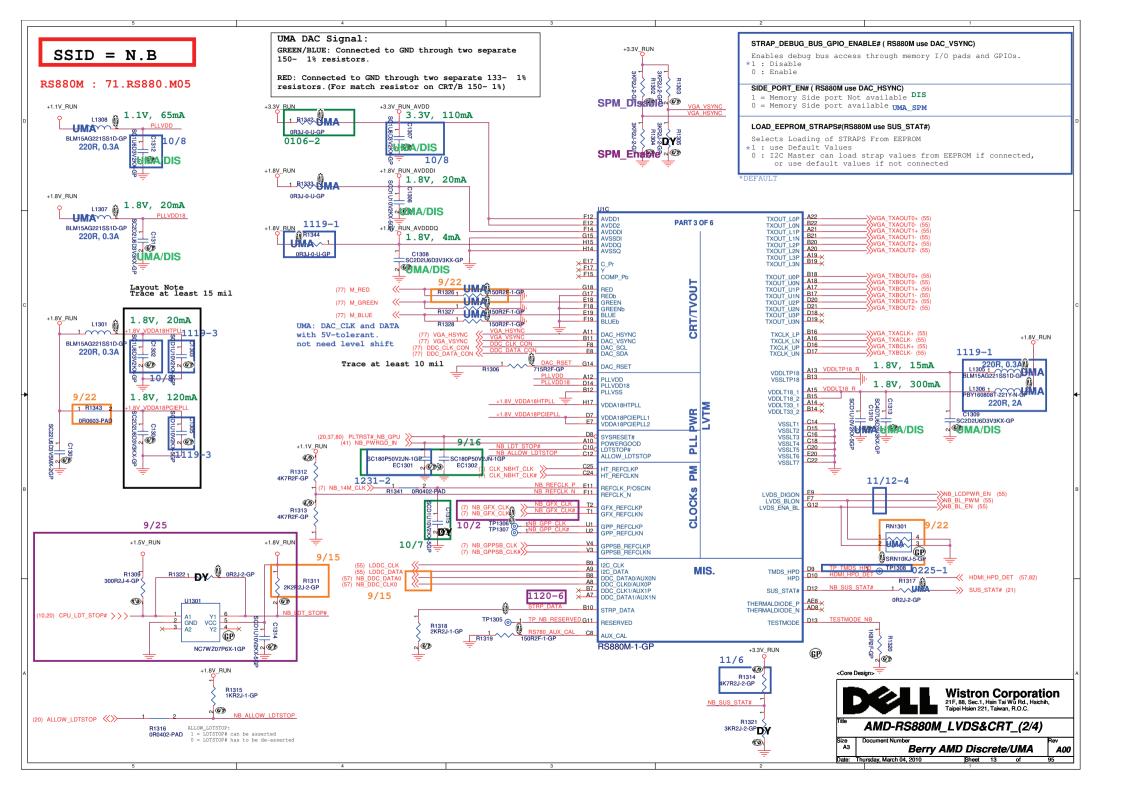


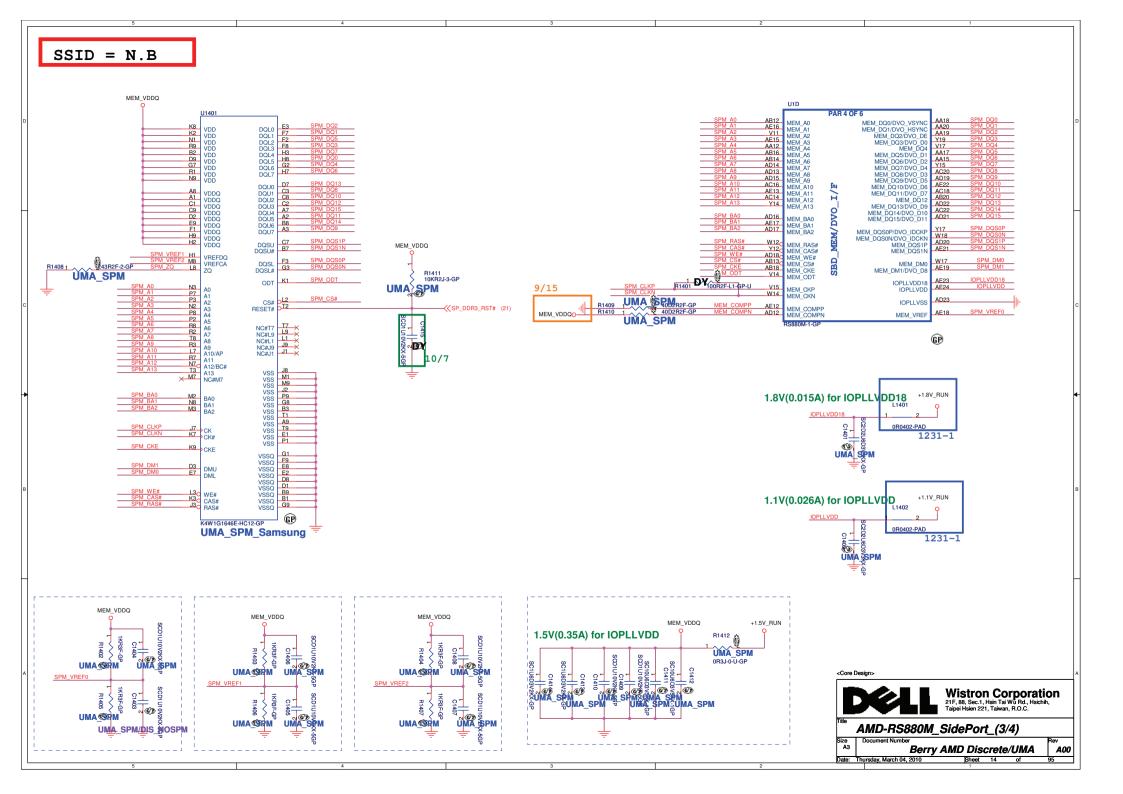
SSID = CPU



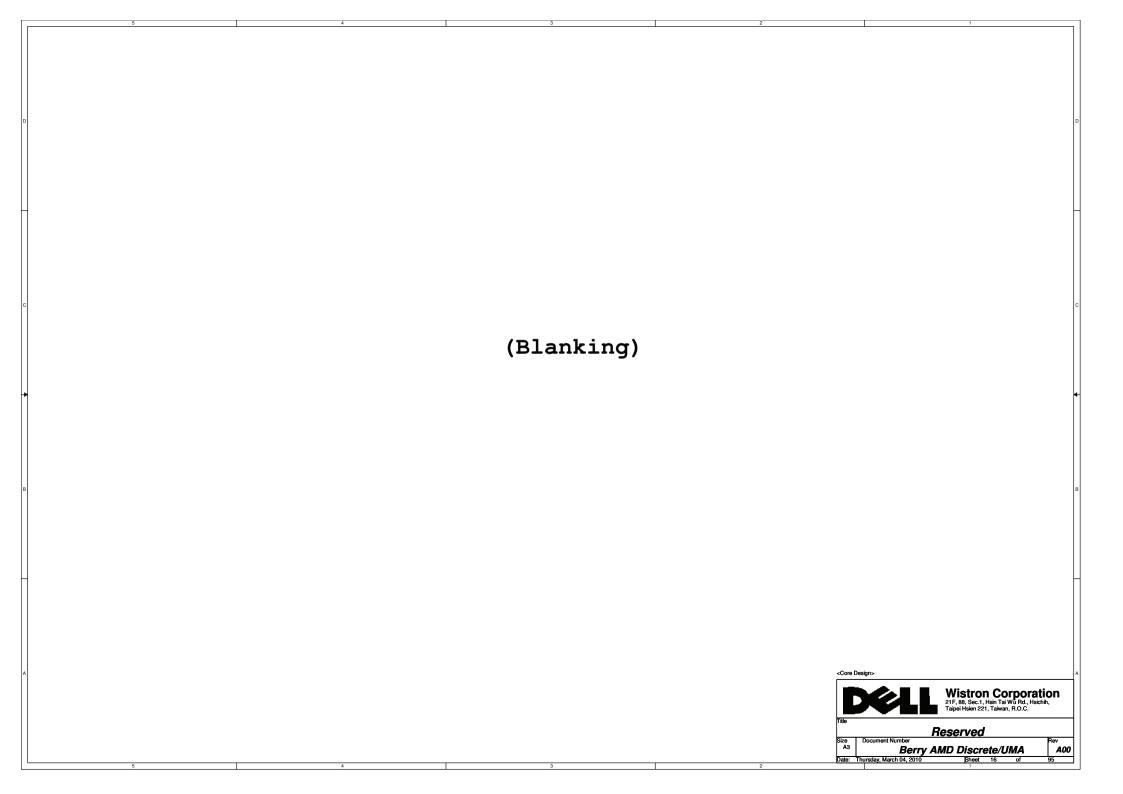


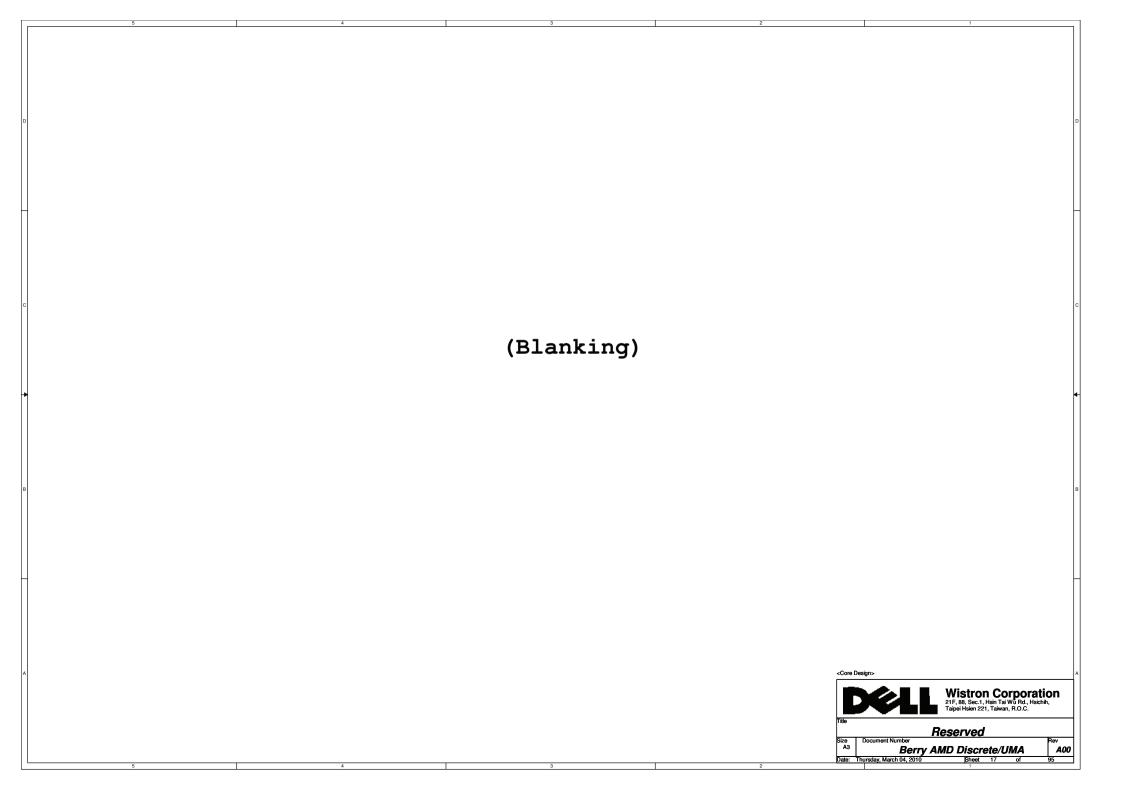


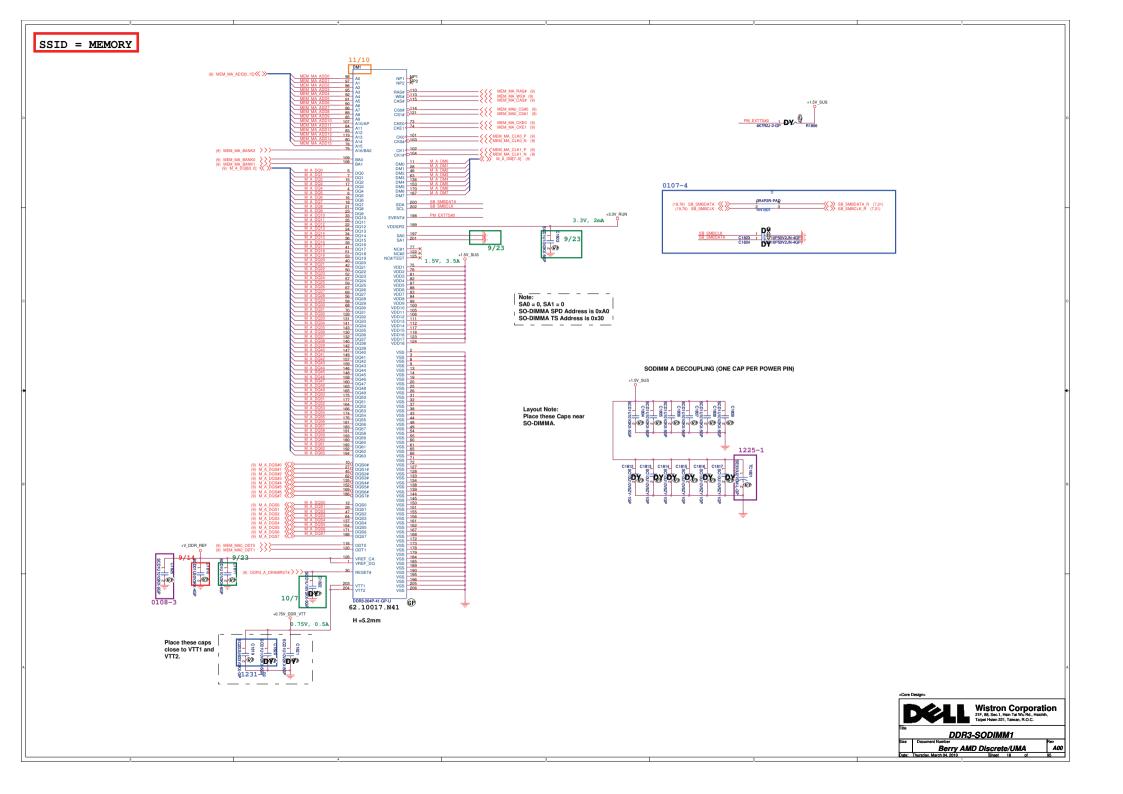


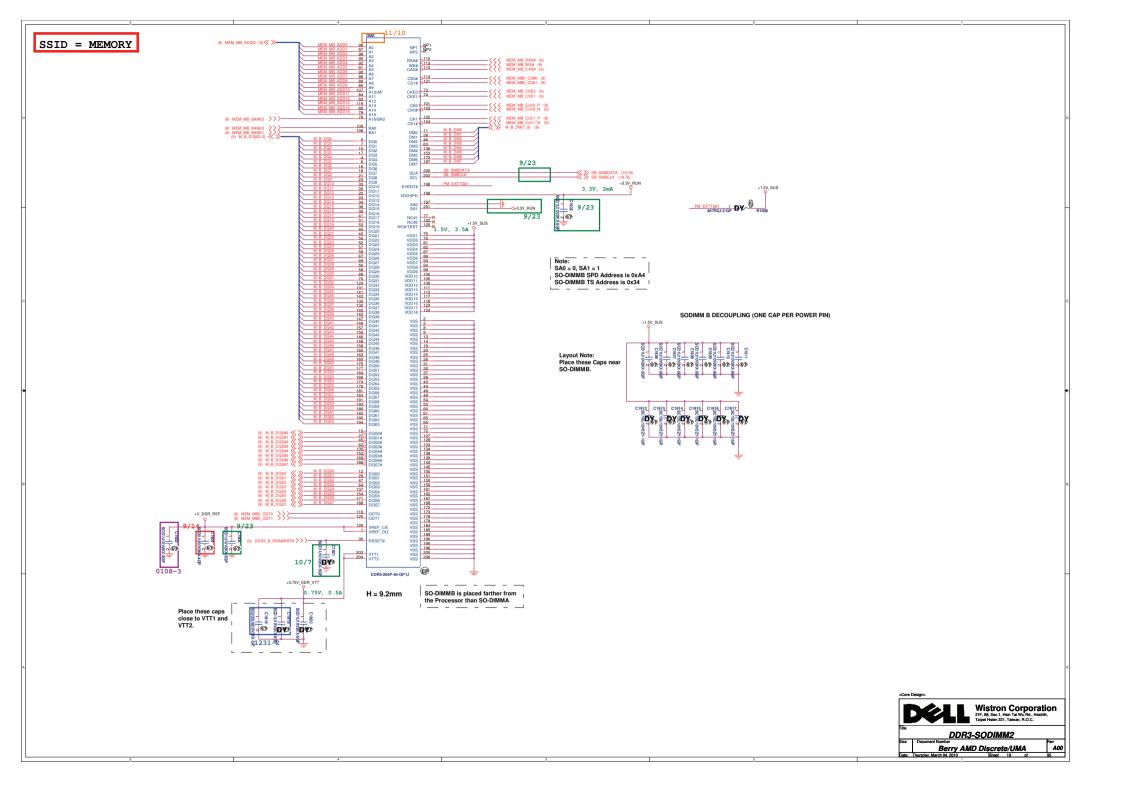


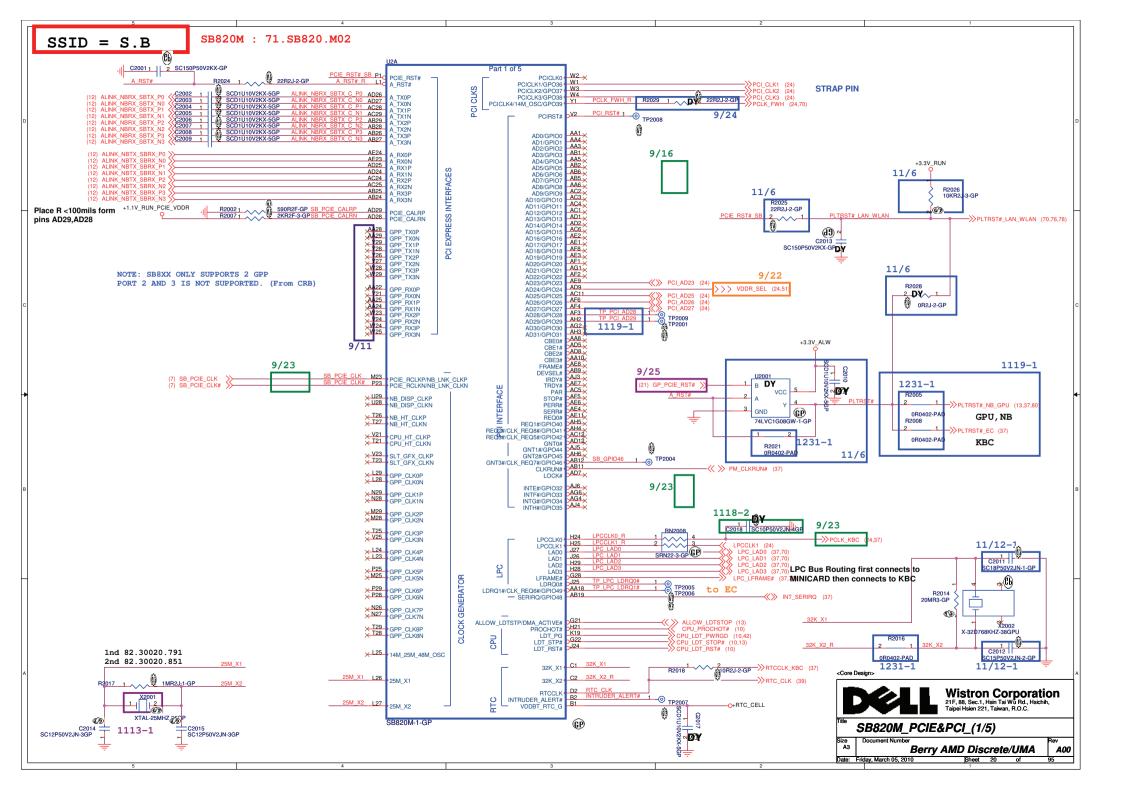
SSID = N.B1231-1 +1.1V RUN 40 mils; 1.1V(0.6A) for VDDHT R1501 U1F C1502 A C1506 VSSAPCIE1 1215-1 +1.1V\_RUN +1.1V\_RUN\_VDDPCIE **PART 6/6** 2 (0) (0) (0) (0) (0) OBOGOS-PA CTHA22 E22 G22 1.1V(2.5A) for VDDPCIE VSSAPCIE3 U1E 130 mils VSSAHT4 VSSAPCIF4 ĕD₩® ÉD₩® G24 G25 VDDHT VSSAHTE VSSAPCIE K16 **PART 5/6** VDDPCIE VSSAPCIES VSSAPCIE6 VDDHT G1502 (GP) /SSAHT6 L16 M16 01010 H10 VDDHT VDDPCIE /SSAHT7 VSSAPCIE7 VDDHT\_4 VDDPCIE /SSAHT8 VSSAPCIE8 P16 117 VDDHT VDDPCIE \$ \ @ /SSAHTO VSSAPCIE +1.1V\_RUN R16 T16 ŠĐ**V**® × √ @ ŠĐ**V**⊅ € ~ @® G1503 (GP) VDDPCIE VDDPCIE VSSAPCIE10 VSSAPCIE11 VDDHT\_ /SSAHT1 1.1V(0.7A) for VDDHTRX 124 VDDHT 7 GAP CLOSE-PWR-8-GP VSSAHT1 VDDPCIE VDDPCIE /SSAHT12 VSSAPCIE12 VSSAPCIE13 1231-2 G1504 GP /DDHTRX /SSAHT13 G19 F20 N22 C1513 \$\frac{1}{2}\$\frac{1}\$\frac{1}{2}\$\frac{1}{2}\$\frac{1}{2}\$\frac{1}{2}\$\frac{1}{2}\$\f GAP CLOSE-PWR-8-GP /DDHTRY VDDPCIE VSSAHT14 VSSAPCIE14 VSSAPCIE15 VSSAPCIE16 0R0603-PA DDHTRX\_ F21 19 \_GP R19 VDDHTRX 4 VDDPCIE VSSAHT16 D22 B23 R22 R24 VDDPCIE VDDPCIE VSSAPCIE17 VSSAPCIE18 /DDHTRX /SSAHT17 (C) × < © VDDHTRX VSSAHT18 A23 +NB VCORE R25 H20 VDDHTRX VDDPCIE VDDPCIE /SSAHT10 VSSAPCIE19 VSSAPCIE20 +NB\_VDDC 0.95~1.1V(12A) for VDDC 1122 VDDHTTX . VDDPCIE /SSAHT21 VSSAPCIE21 550 mils AD24 V19 VSSAPCIE22 +1.1V\_RUN 1.1V(0.4A) for VDDHTTX AC23 W22 R1503 VDDHTTX : VDDC ROUND VSSAPCIE23 VSSAHT23 AB2 J14 U16 C1526 A W24 VDDC\_ VDDC\_ VDDC\_ VDDC\_ C1520 (8) C1527 A 10/8 10/8 VSSAPCIE24 VSSAPCIE25 DDHTTX\_ SCD1U10V2KX /SSAHT24 C1 525 Ω AA21 W25 VDDHTTX VSSAHT25 Y20 W19 Y21 AD25 C1518 (6) J11 K15 M12 /DDHTTX /SSAHT26 VSSAPCIE26 /DDHTTX VSSAHT20 VSSAPCIE2 0R0603-PAI **©** VDDC\_ VDDC\_ VDDC\_ VDDC\_ VDDC\_ VDDC\_ VDDC\_ VDDC\_ ≨DVØ §DYØ VDDHTTX 8 VSSAPCIE28 L14 L11 DDHTTX\_ VSSAPCIE29 VSSAPCIE30 **©** Š**D¥**® Š**D**₩® × ~ © POWER T17 M14 W8 VDDHTTX 10 <u>5</u> M13 M15 1231-2 N13 P12 VSSAPCIE31 VSSAPCIE32 VDDHTTX 11 P17 VDDHTTX\_11 AA4 /SS14 M17 N12 P15 R11 AB5 AB1 VDDHTTX 13 VSS15 VSSAPCIE33 +1.8V\_RUN 10/5 VSSAPCIE34 1.8V(0.7A) for VDDA18PCIE P11 SBD MEM ENABLE R14 T12 AR7 VDDA18PCIE VDDC VDDC VDDC R1506 +1.5V\_RUN VSS17 VSSAPCIE35 40 mils AC3 AC4 VDDA18PCIE\_2 VDDA18PCIE\_3 VSSAPCIE36 VSSAPCIE37 K10 P14 1.5V(0.1A) for VDD\_MEM U14 PBY160808T-221Y-N-GP VSS19 C1529 (8) M10 L10 15 mils 0R3J-0-U-GP U11 U15 VDDC VDDC VSSAPCIE38 VSSAPCIE39 C1532 VDDA18PCIE 4 220R. 2A VDDA18PCIE\_ COSUMA SPH UMA VSS21 V12 W11 Wg UMA SPM9/11 AR2 VDDA18PCIE VDDC\_ VDDC\_ VSS22 VSSAPCIF40 1119-1 , (C) DDA18PCIE Š**D**₩® §**D**₩® × €® 800 € T10 1112 W15 VDDA18PCIF 8 VDDC: VSS24 AC12 AA14 R10 AE14 D11 VDDA18PCIE\_9 VDDA18PCIE\_10 VDDC\_ J16 VDDC 2 VSS26 VSS2 AA9 G8 E14 VDDA18PCIE\_1: VDDA18PCIE\_1: /\$\$27 AB9 AB11 VDD\_MEM1 VSS4 VSS5 AD9 AA11 AR15 F15 VDDA18PCIF 13 AB17 AB19 Y11 AD10 J15 J12 VDDA18PCIE\_1 VDD\_MEM3 VDD\_MEM4 +1.8V RUN U10 1.8V(0.01A) for VDD18 VDDA18PCIE 15 VSS31 VSS7 AE20 AB21 K14 M11 VDD\_MEM5 VSS32 VSS33 VSS34 +3.3V BUN VDD\_MEM6 VDD18 1 G9 3.3V(0.06A) for VDD33 K11 L15 VSS10 VDD18 AE11 VDD18\_MEM1 H11 15 mils VDD33\_ AD11 VDD18\_MEM2 H12 VDD33\_2 (F) C1535 × √ @⊅ (P Layout Note Š**D**₩® 1231-2 R1502 +1.8V RUN 1.8V(0.025A) for VDD18 15 mils UMA' C1542 0B3J-0-U-GF 1117-2 SUMM/DIS +1.1V RUN +NB VDDC 0104-1 R1507 PRY160808T-330Y-Layout Note R1508 <Core Design> BY160808T-330Y-R1509 **Wistron Corporation** PBY160808T-330Y-N 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. R1510 (6) R1511 AMD-RS880M\_PWR&GD\_(4/4) Size A3 Berry AMD Discrete/UMA A00 Date: Thursday, March 04, 2010 Sheet 15

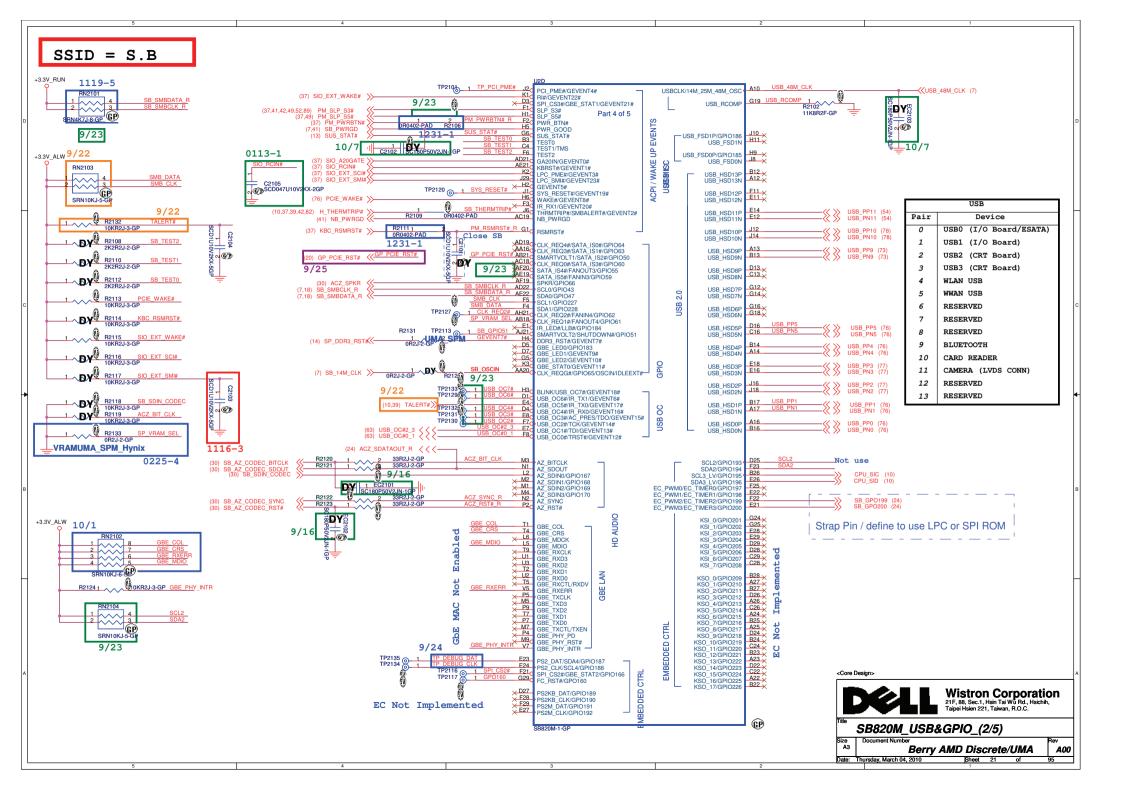




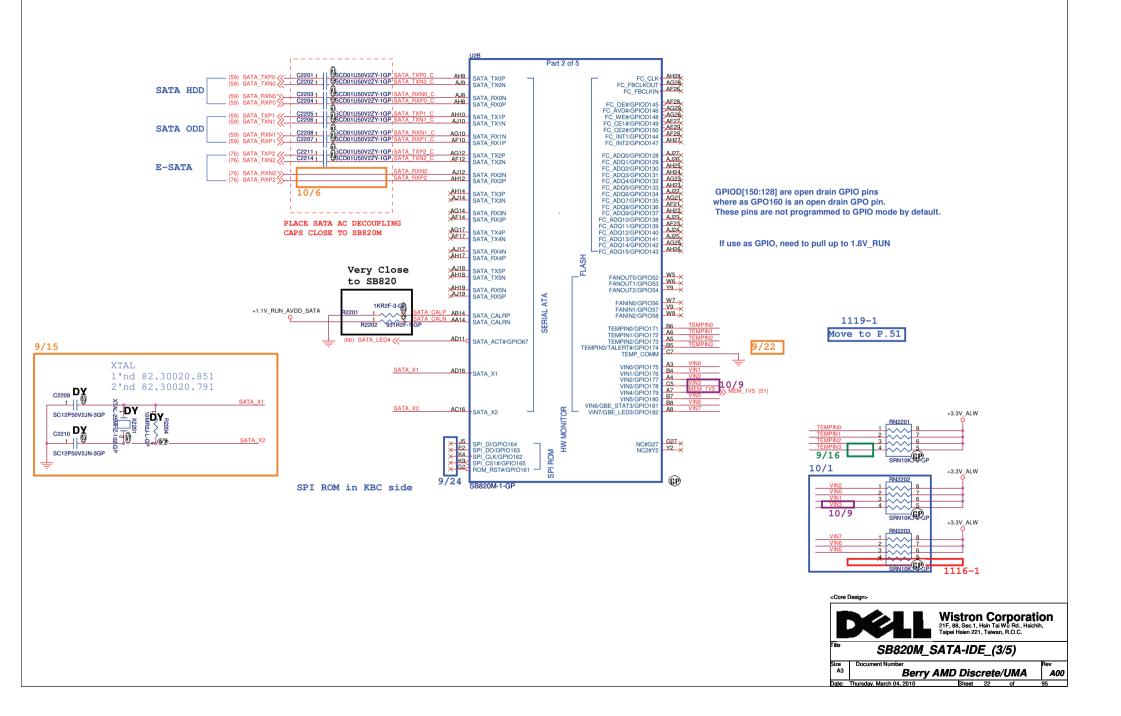


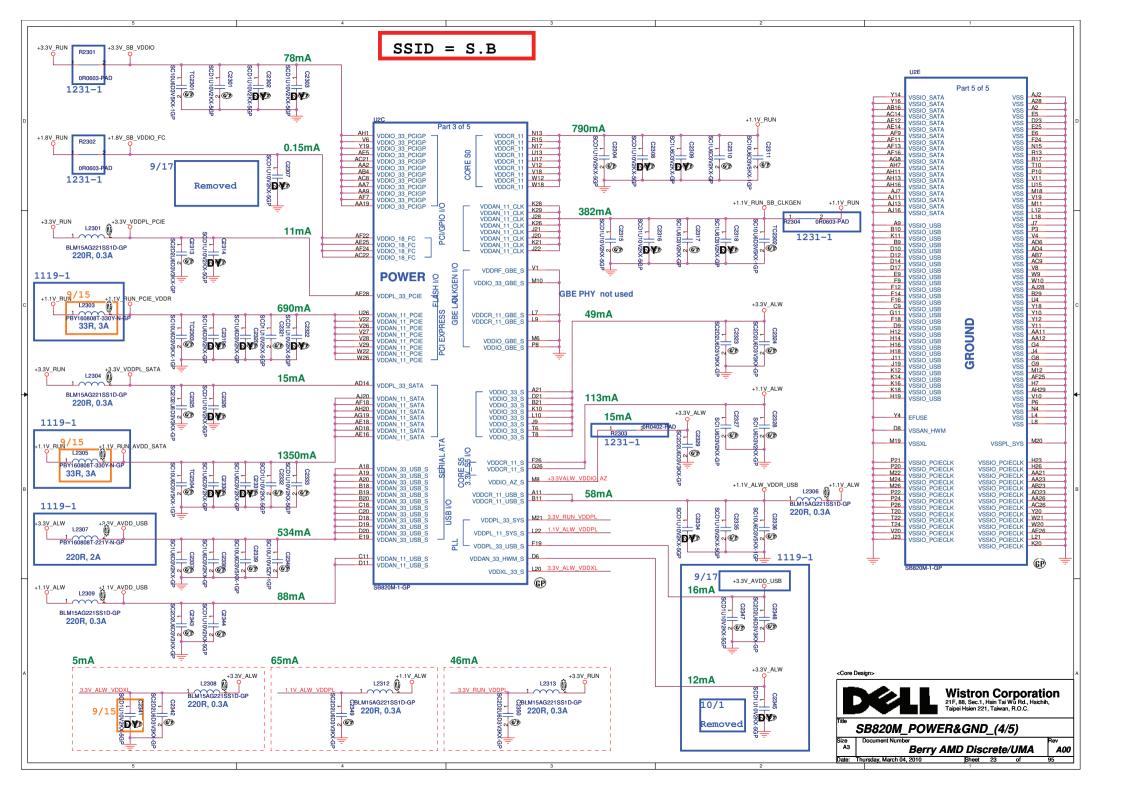






SSID = S.B





SSID = S.B

### **REQUIRED STRAPS**

PCLK KBC

(PCI\_CLK3)

USE

**DEBUG** 

STRAPS

**IGNORE** 

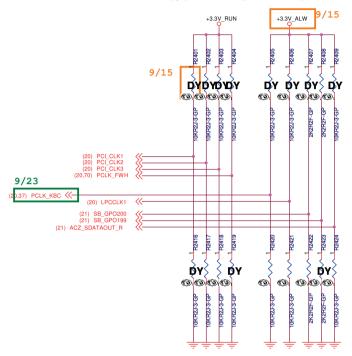
**DEBUG** 

STRAPS

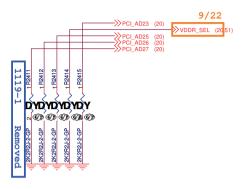
Fusion

**CLOCK** mode

DEFAULT



# **DEBUG STRAPS**



### **REQUIRED SYSTEM STRAPS** AZ SDOUT#

**LOW POWER** 

PERFORMANCE

MODE

MODE

**PULL** 

HIGH

**PULL** 

LOW

PCI\_CLK1

PCIE GEN2

DEFAULT

PCIE GEN1

Allow

Force

PCI\_CLK2

WatchDOG

ENABLED

WatchDog

DISABLED

(NB\_PWRGD)

(NB\_PWRGD)

	PCLK_FWH (PCI_CLK4)	LPCCLK0	LPCCLK1	SB_GPO200 , SB_GPO199 ROM TYPE:
	non_Fusion CLOCK mode	ENABLE EC	CLKGEN ENABLED (Use Internal)	H, H = Reserved H. L = SPI ROM
	DEFAULT	DISABLE EC	DEFAULT CLKGEN	H, L = SPI HOW  L, H = LPC ROM DEFAULT

L, L = FWH ROM

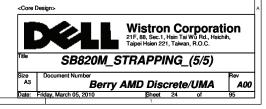
DISABLED

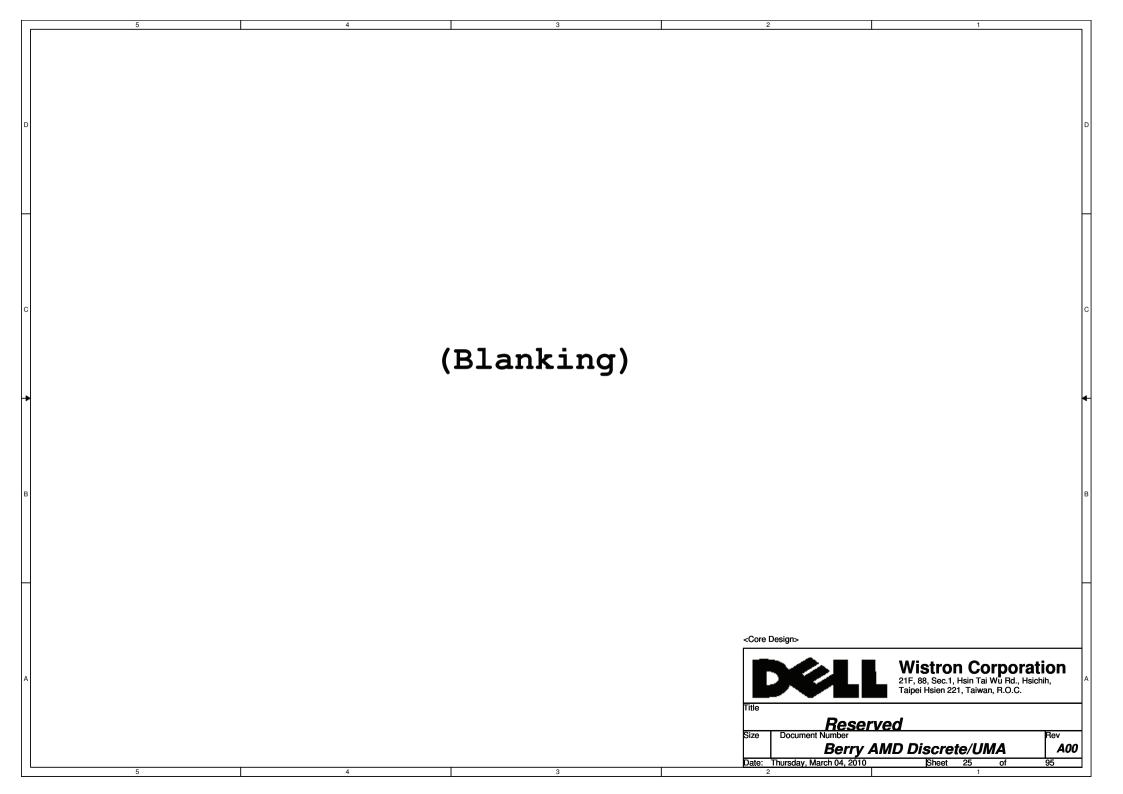
(Use External)

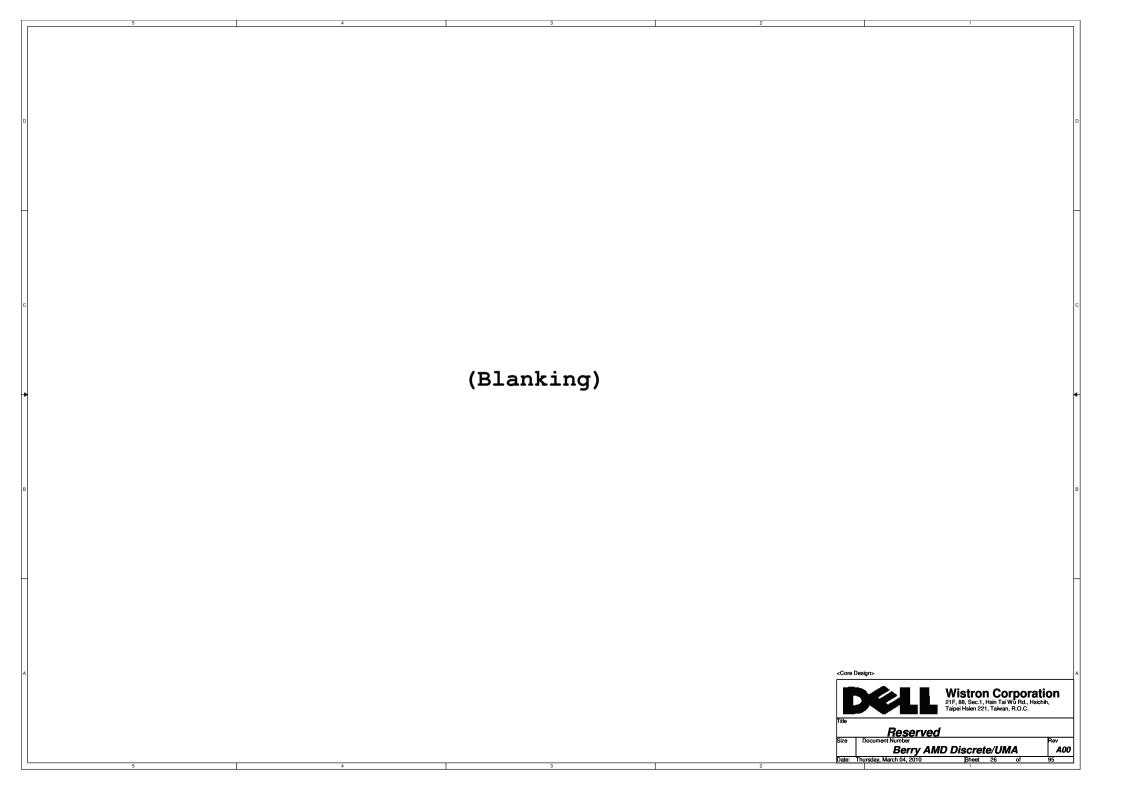
### **USE this pin to determine INT/EXT CLK**

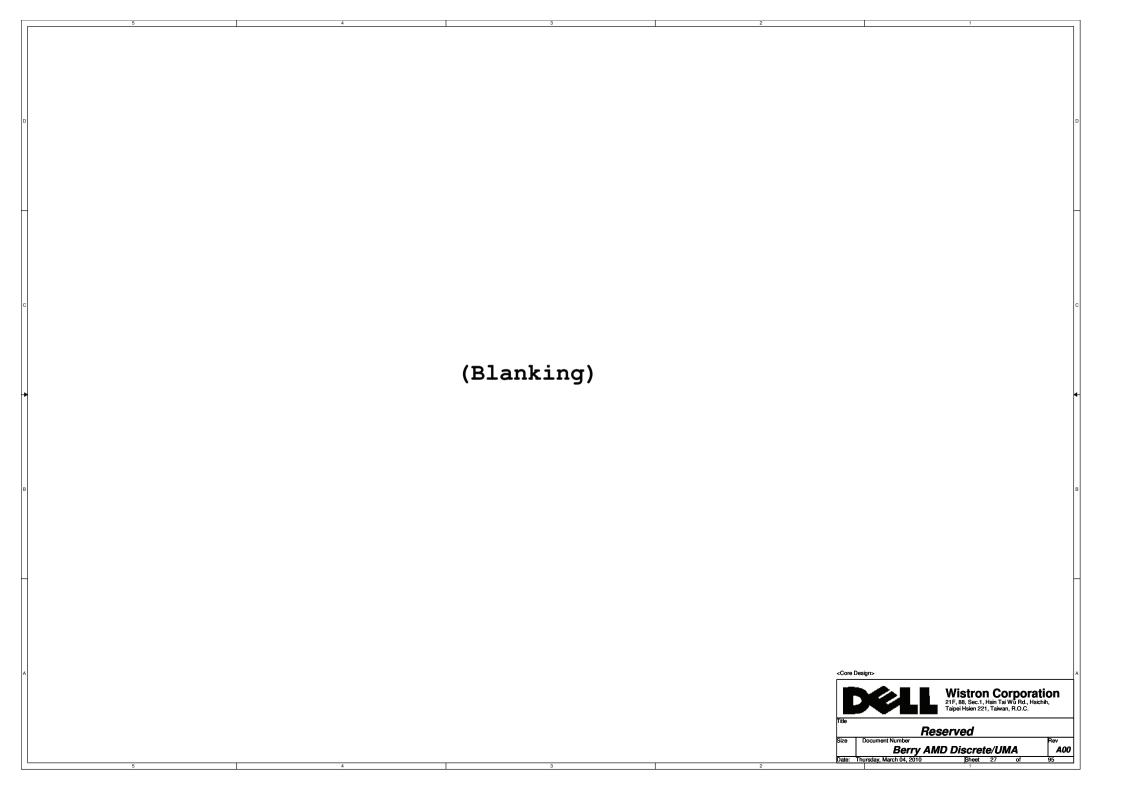
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL (DEFAULT)	Disable ILA AUTORUN (DEFAULT)	USE FC PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Disable PCI MEM BOOT (DEFAULT)
PULL LOW	BYPASS PCI PLL	Enable ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	Enable PCI MEM BOOT

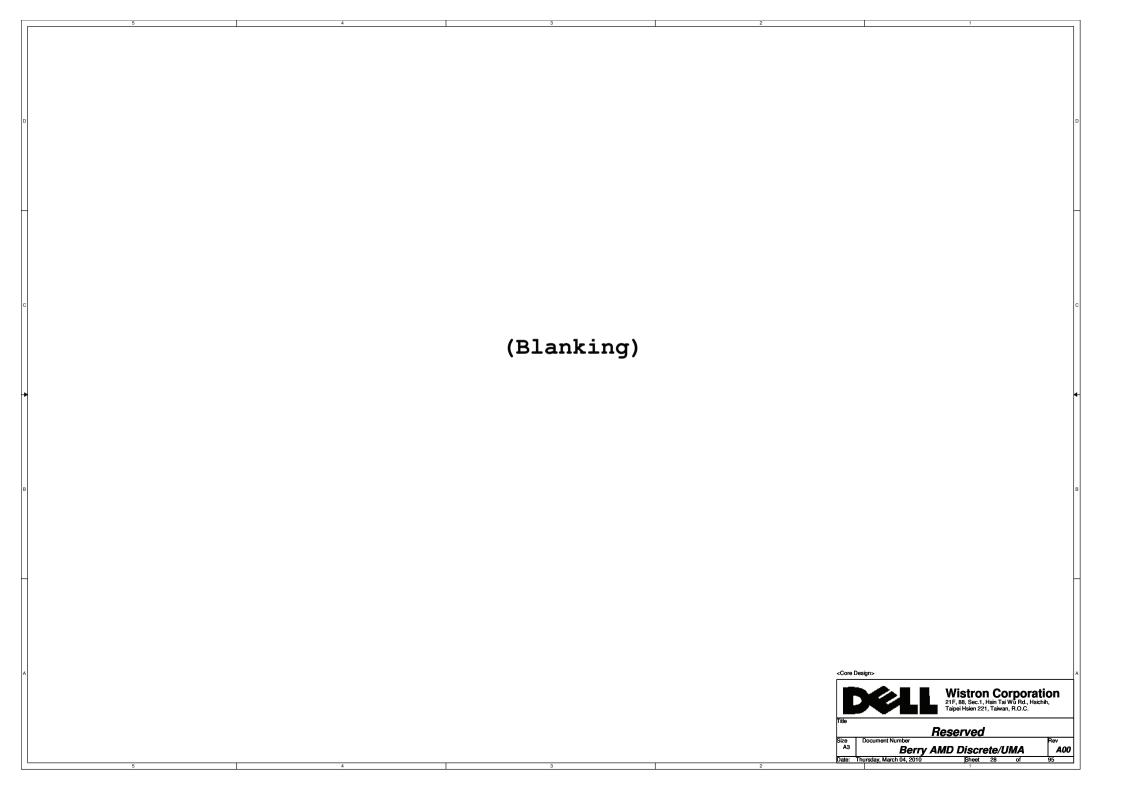
Note: SB820M has 15K internal PU FOR PCI\_AD[27:23]

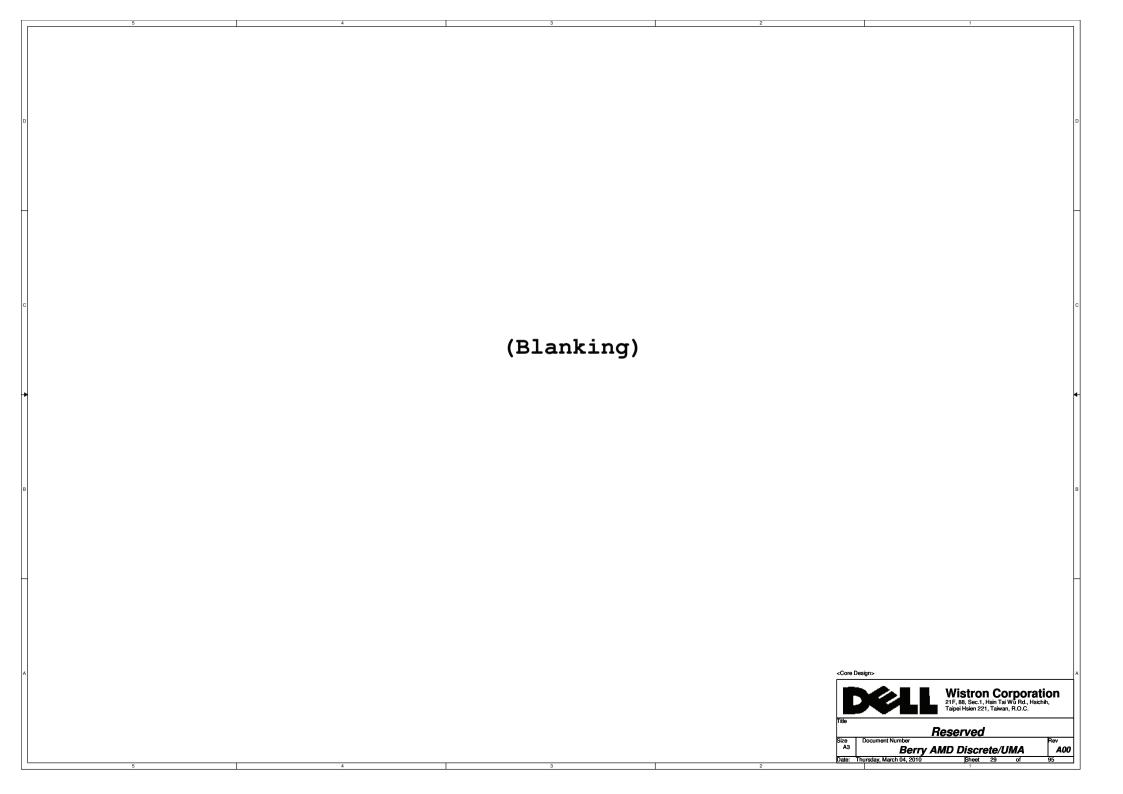


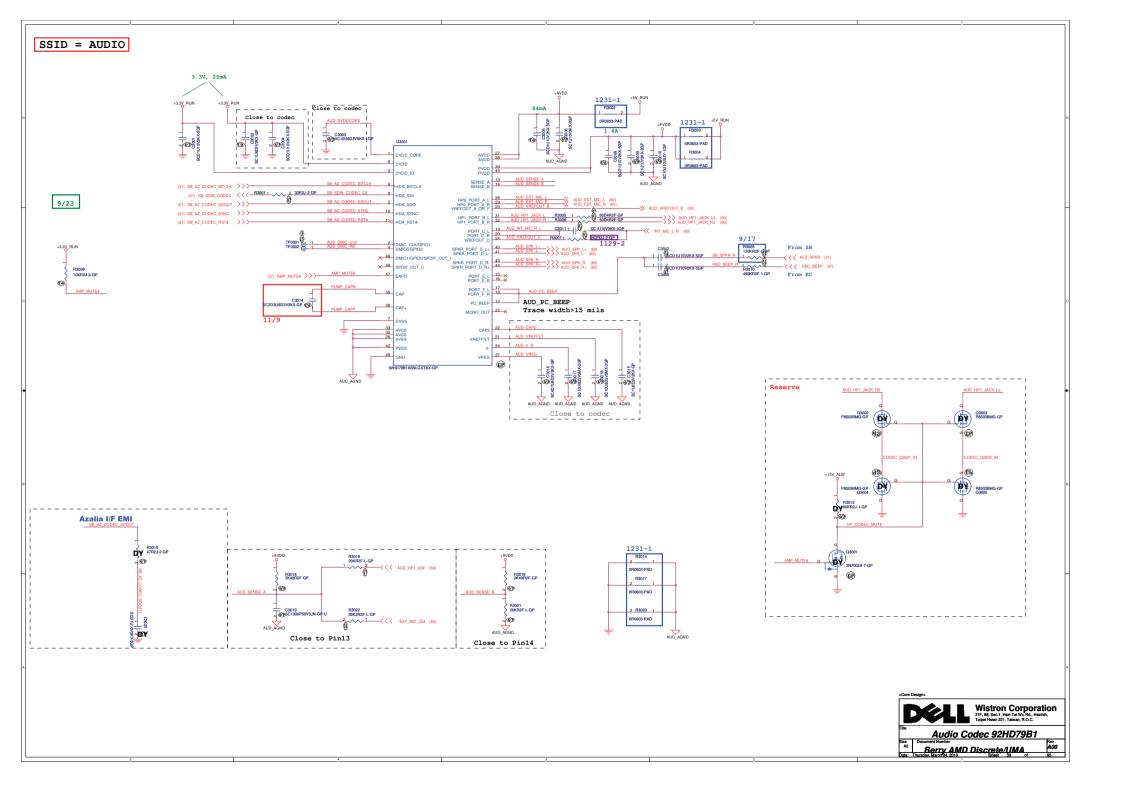


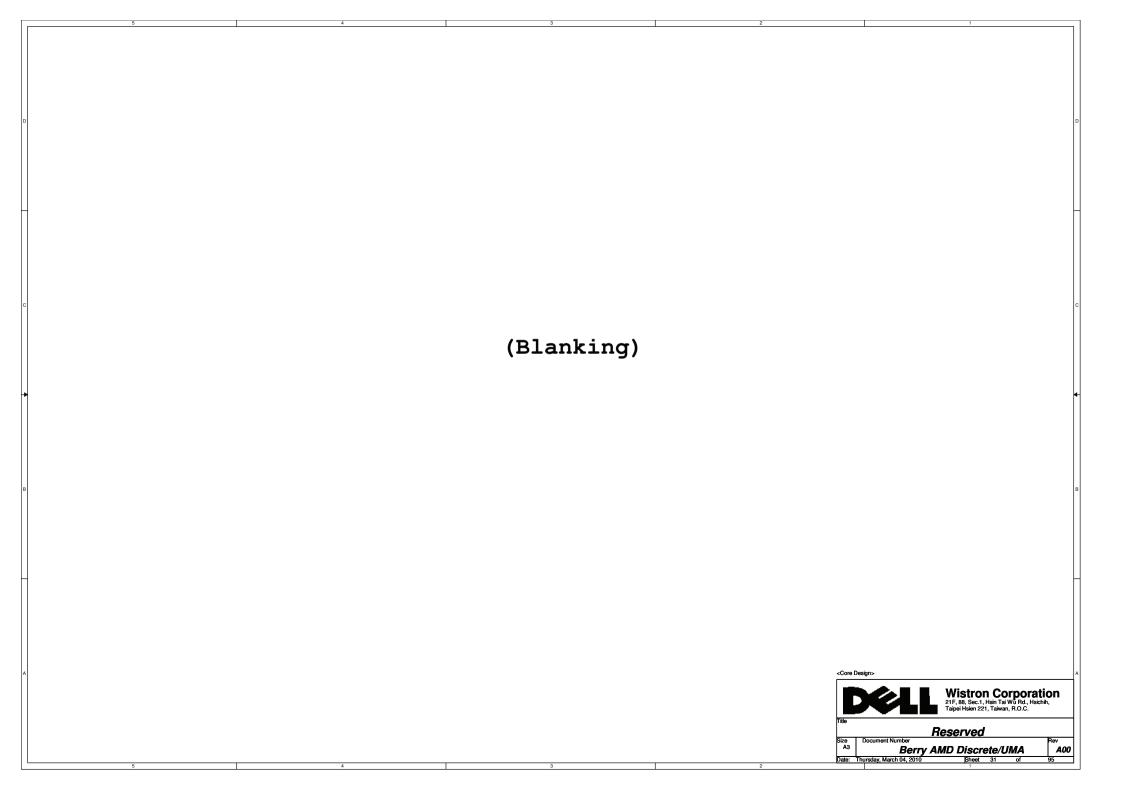


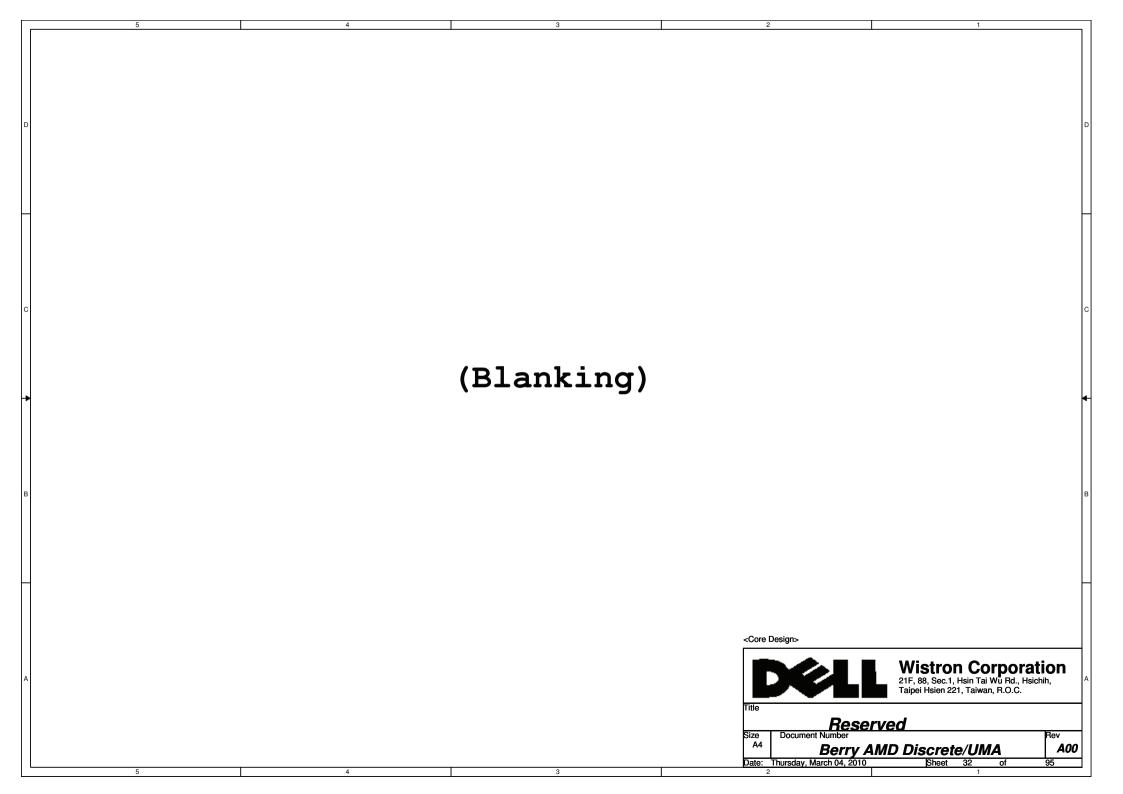


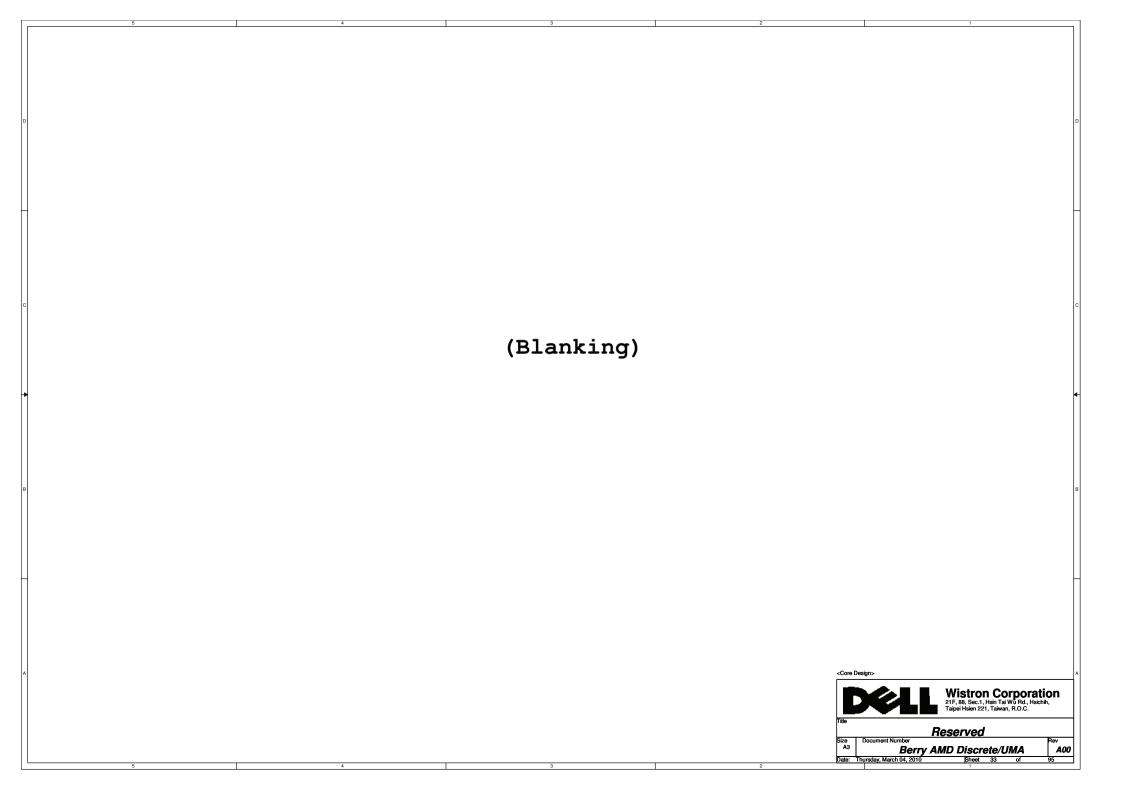


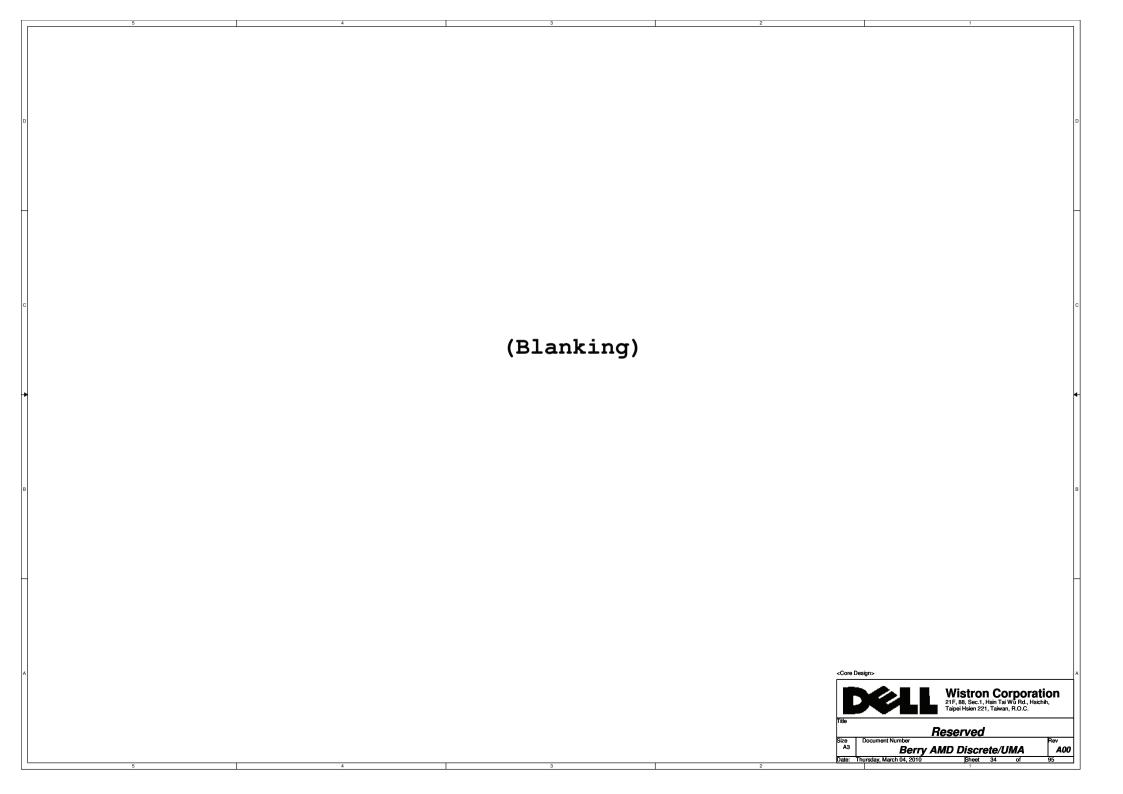


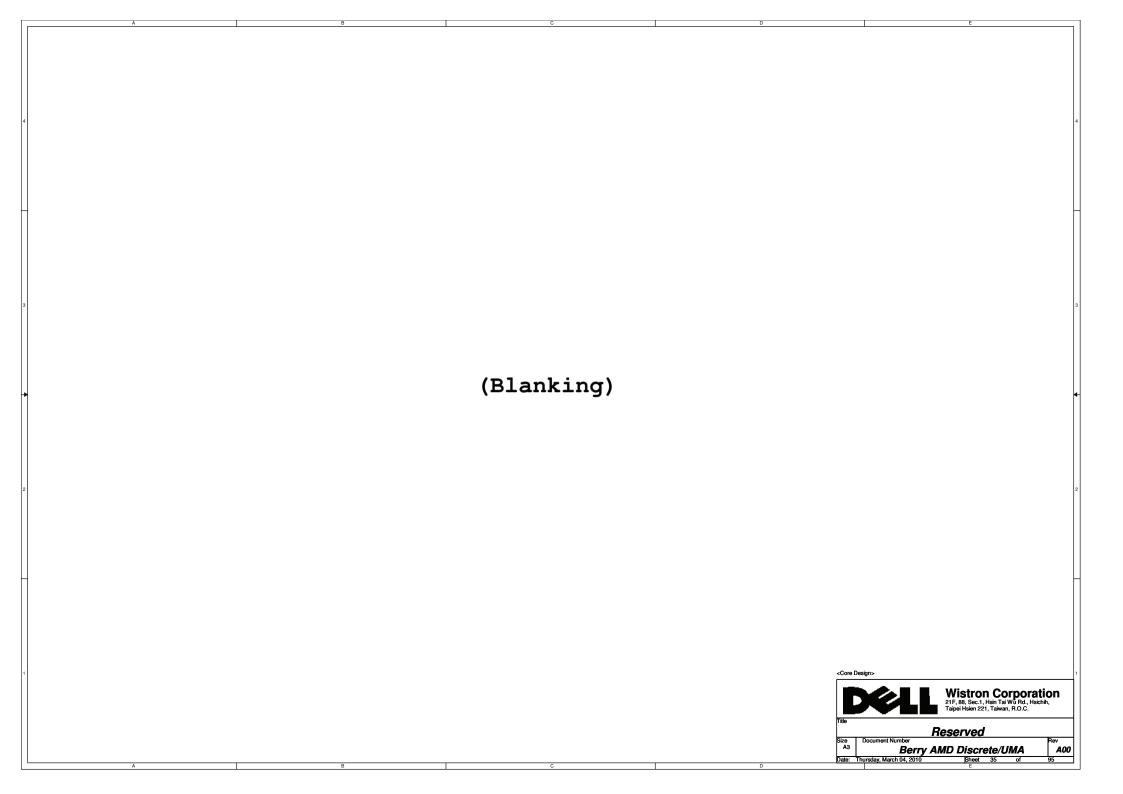


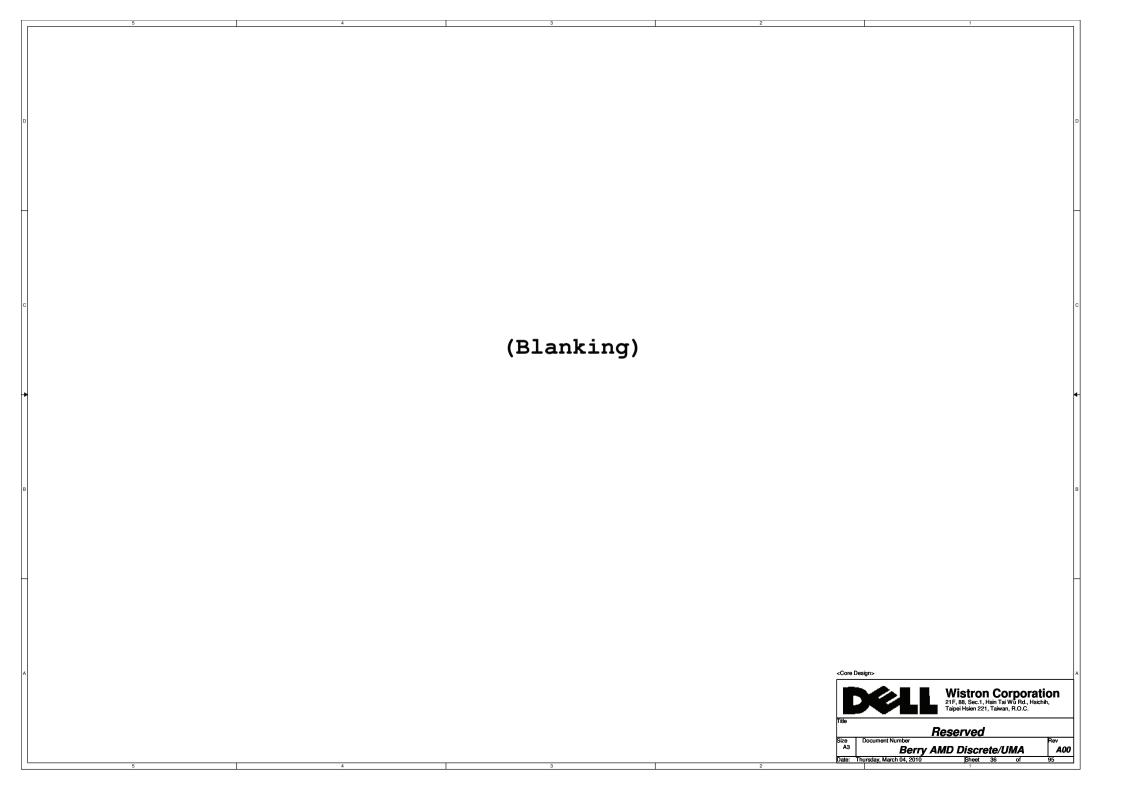


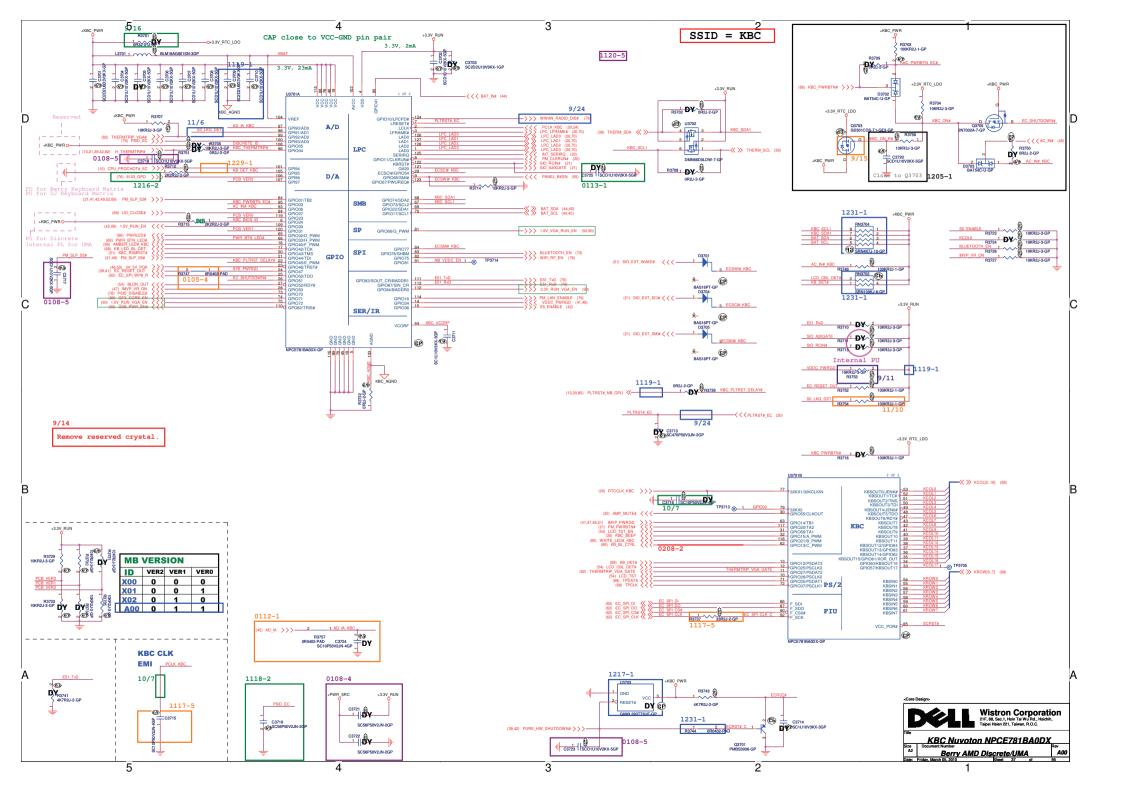


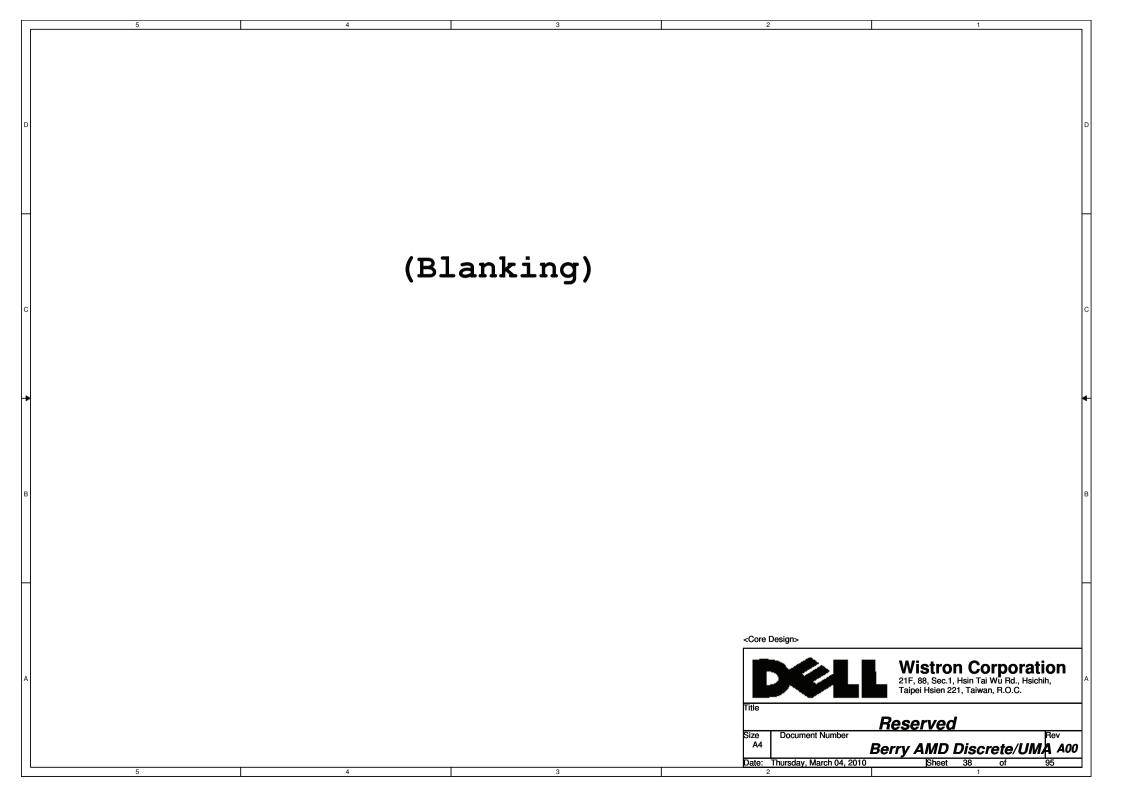


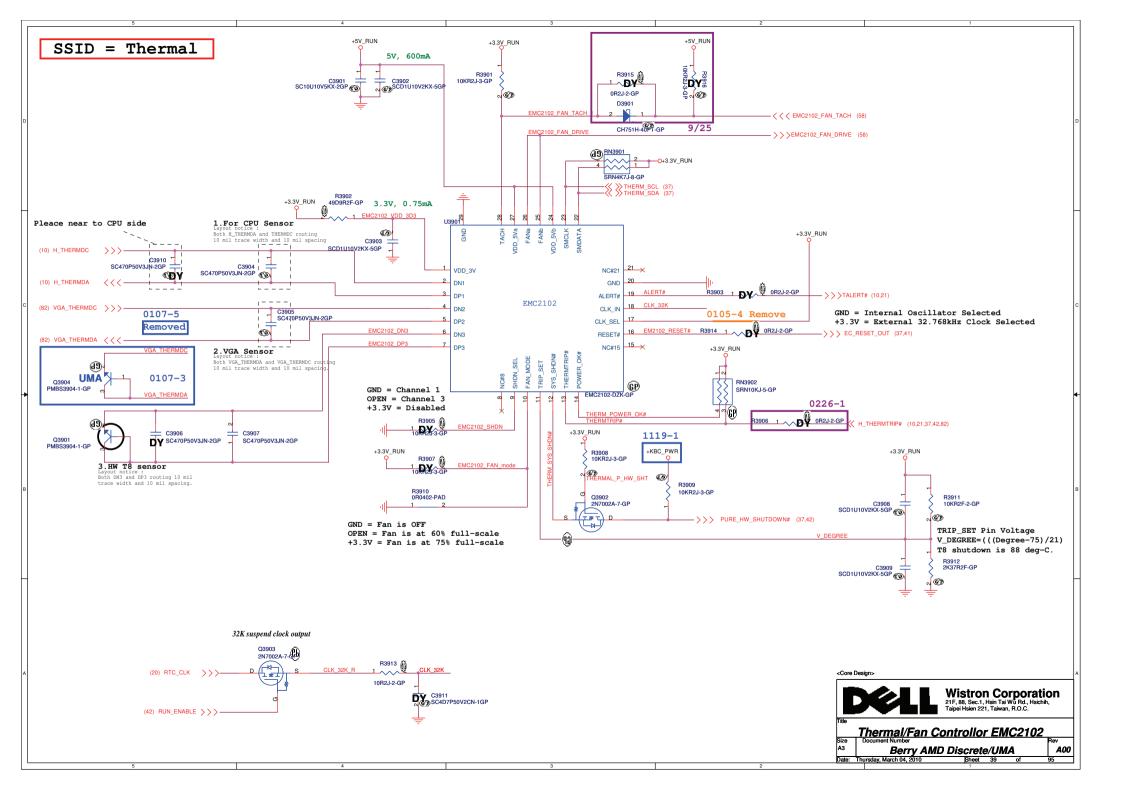


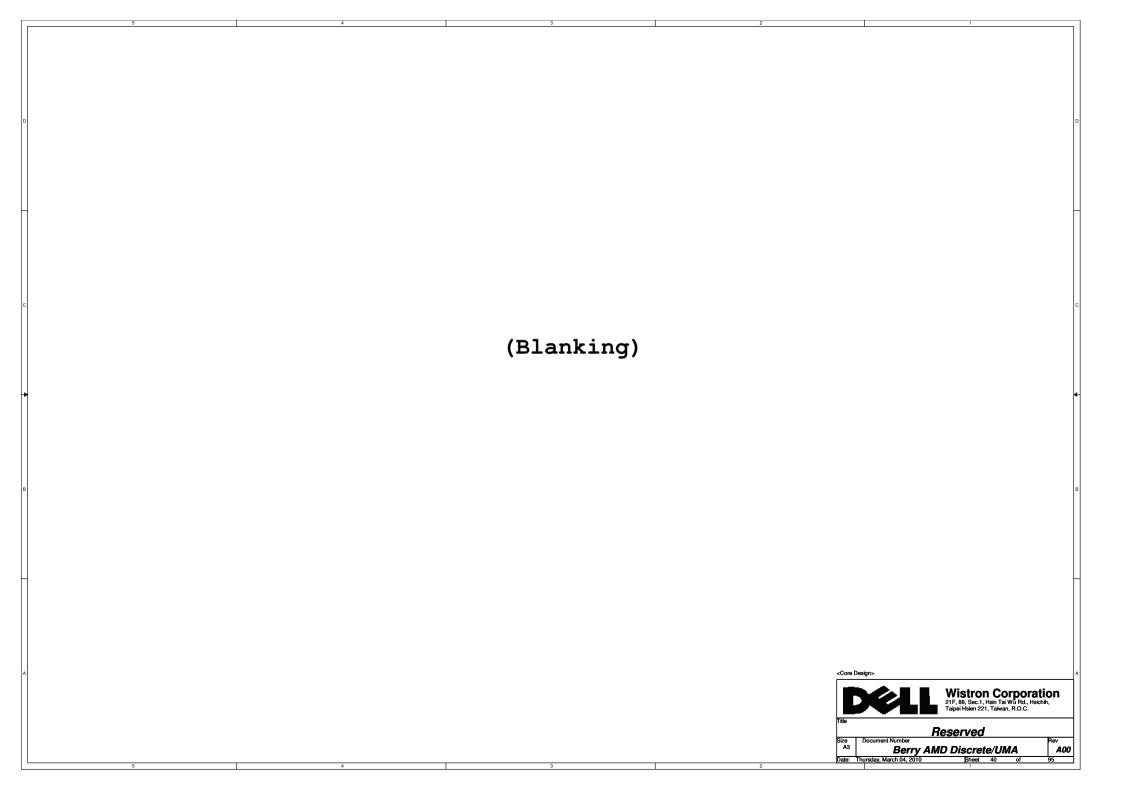


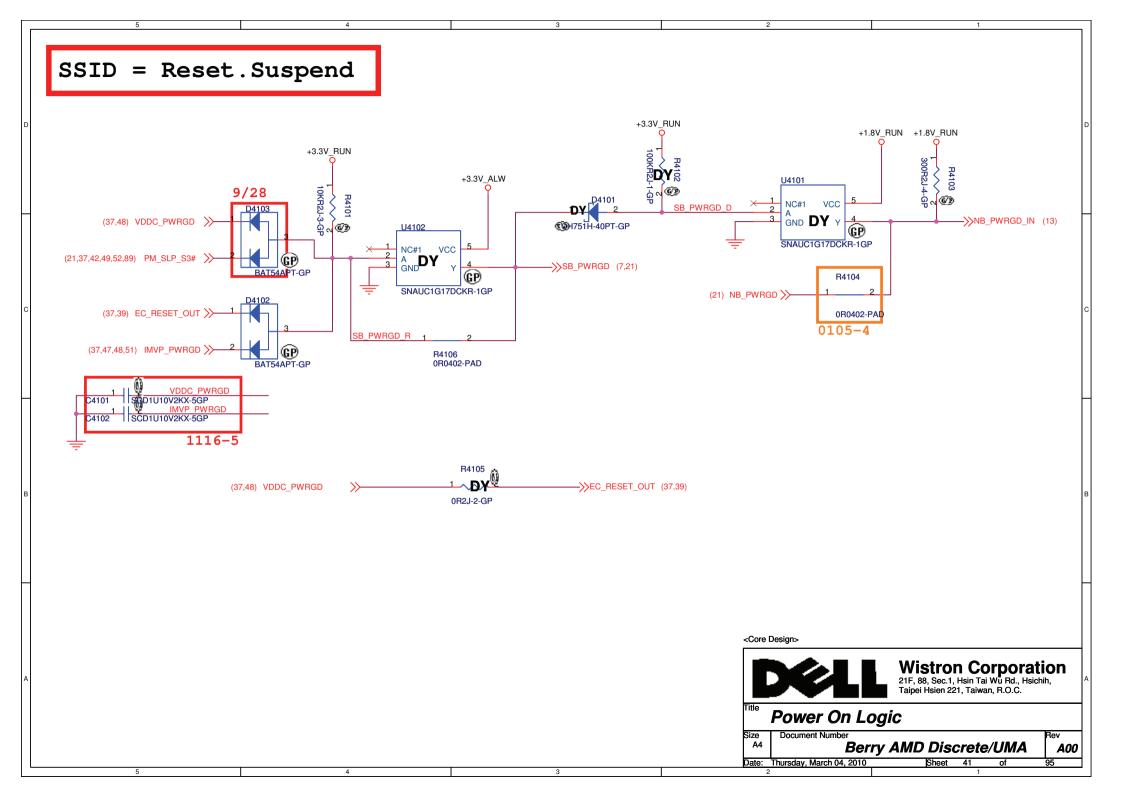


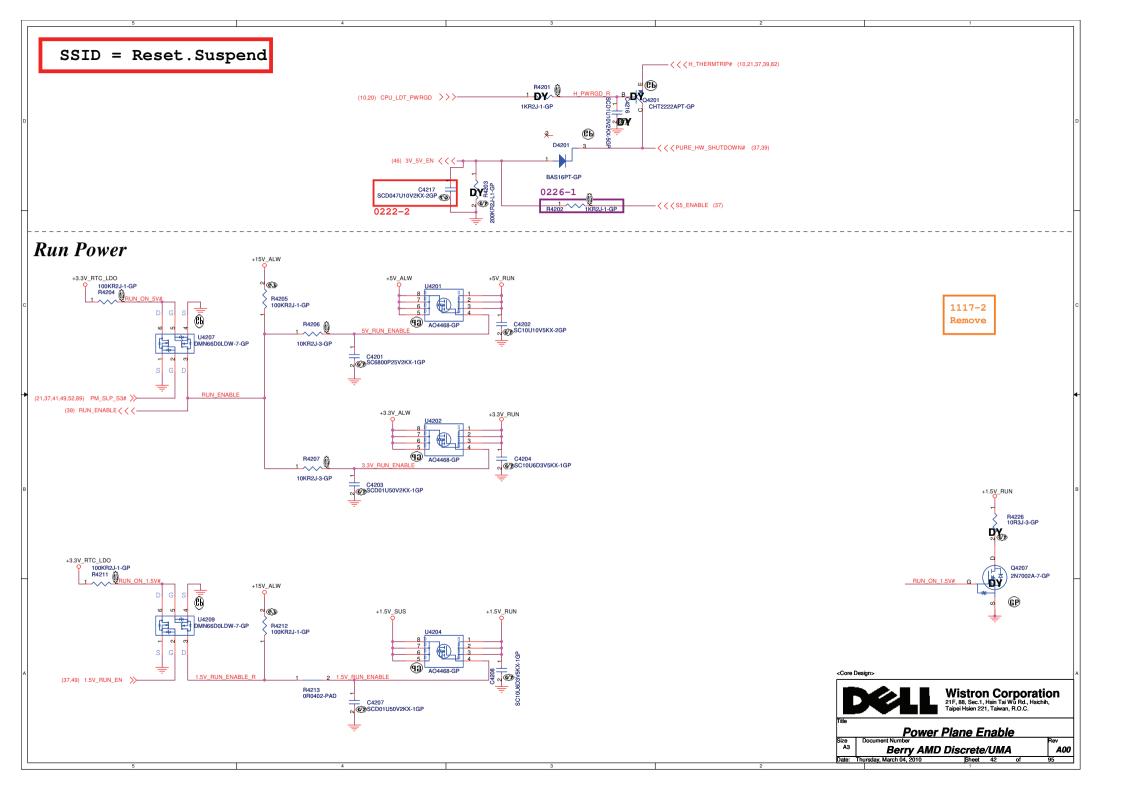


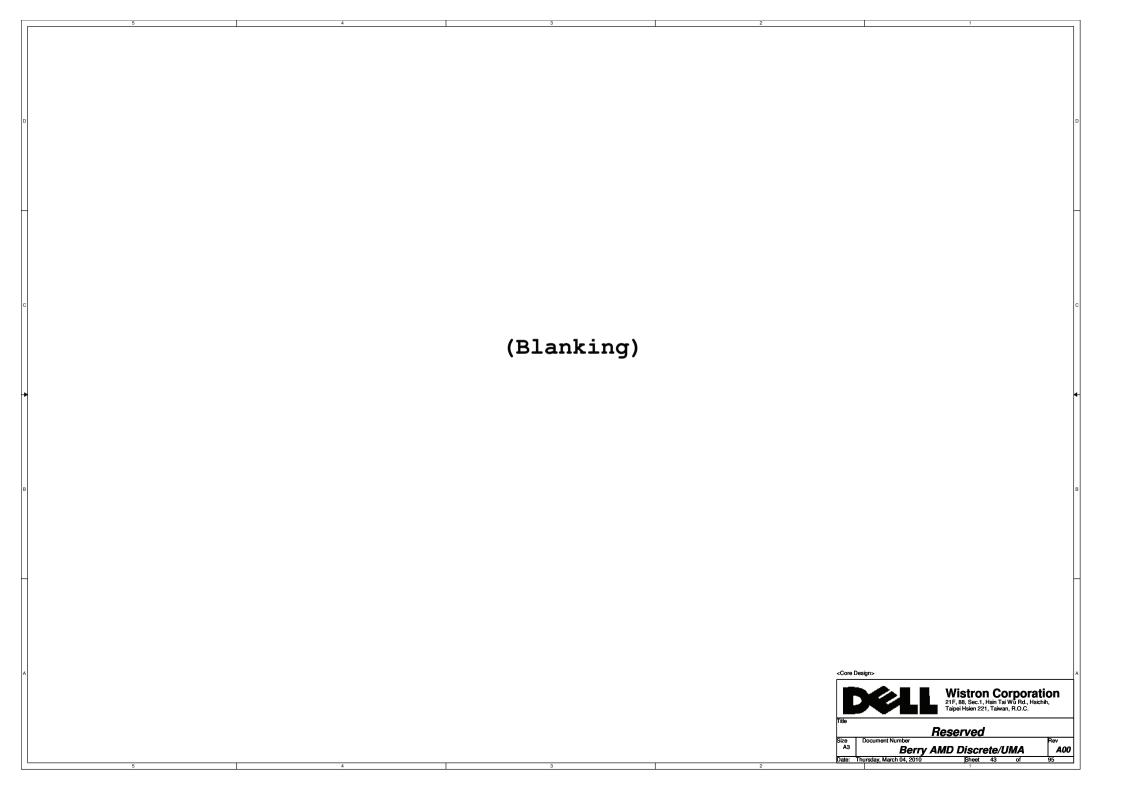


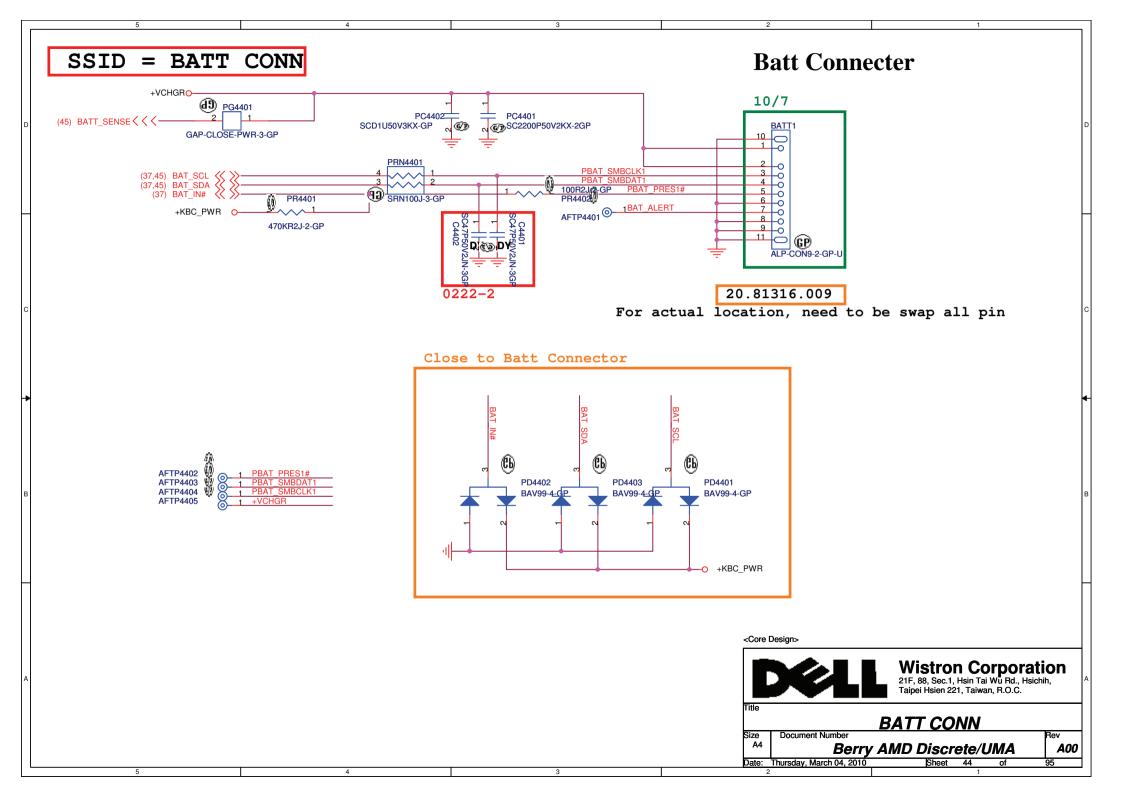


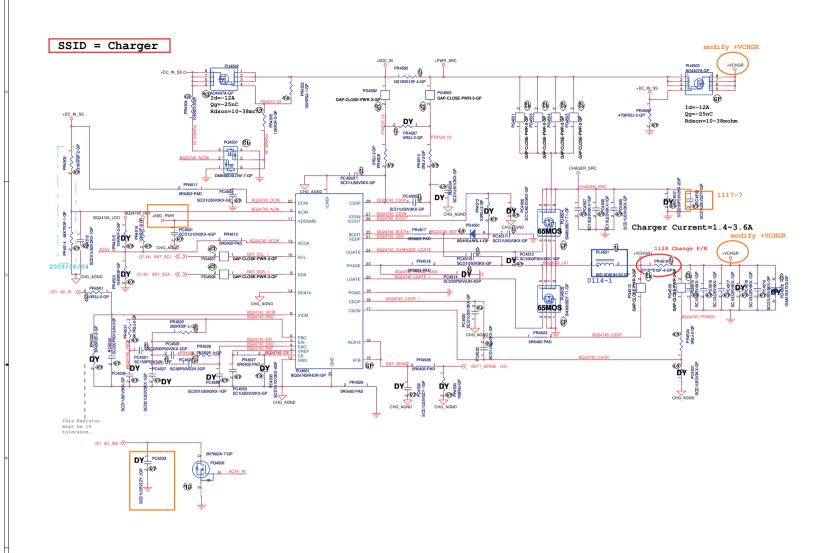


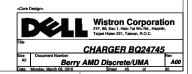


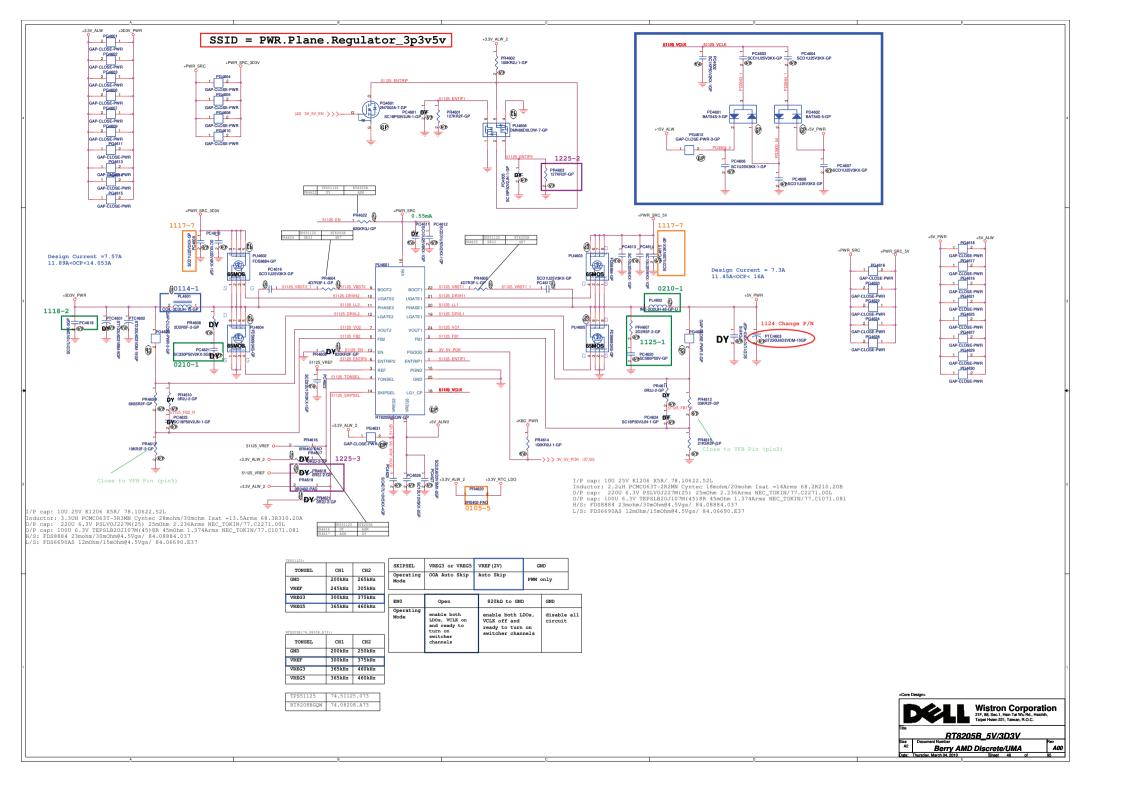


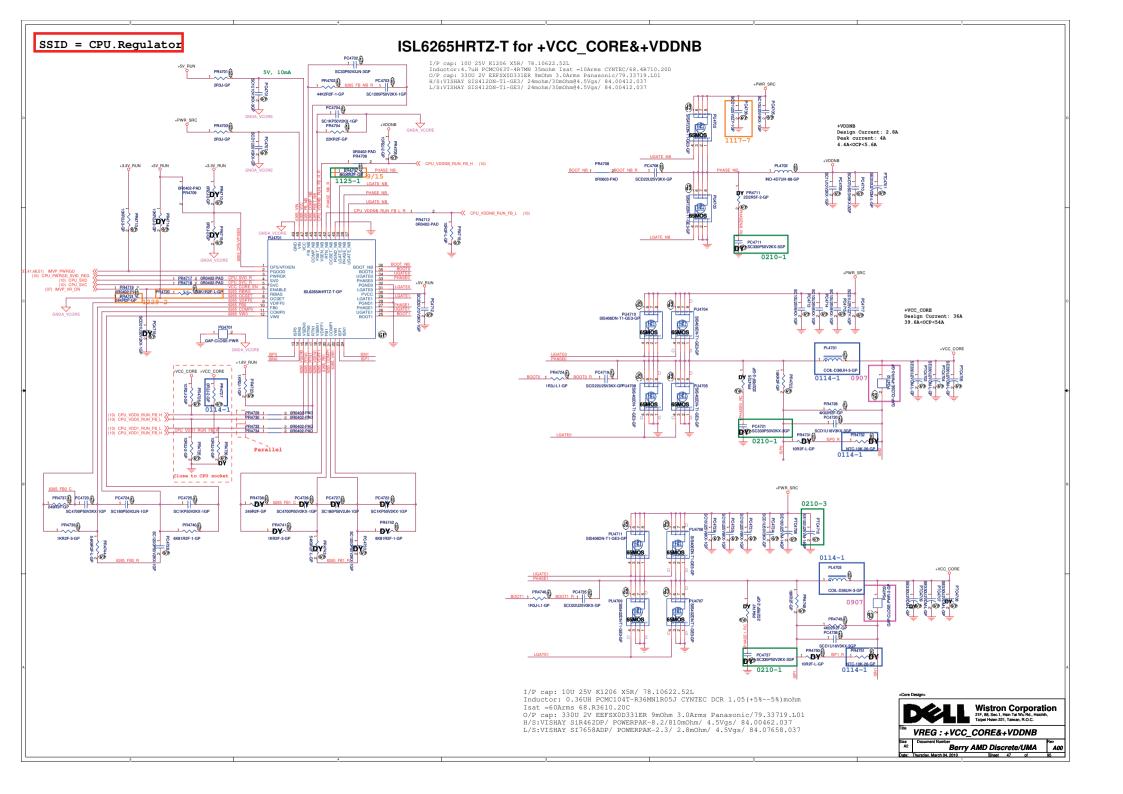


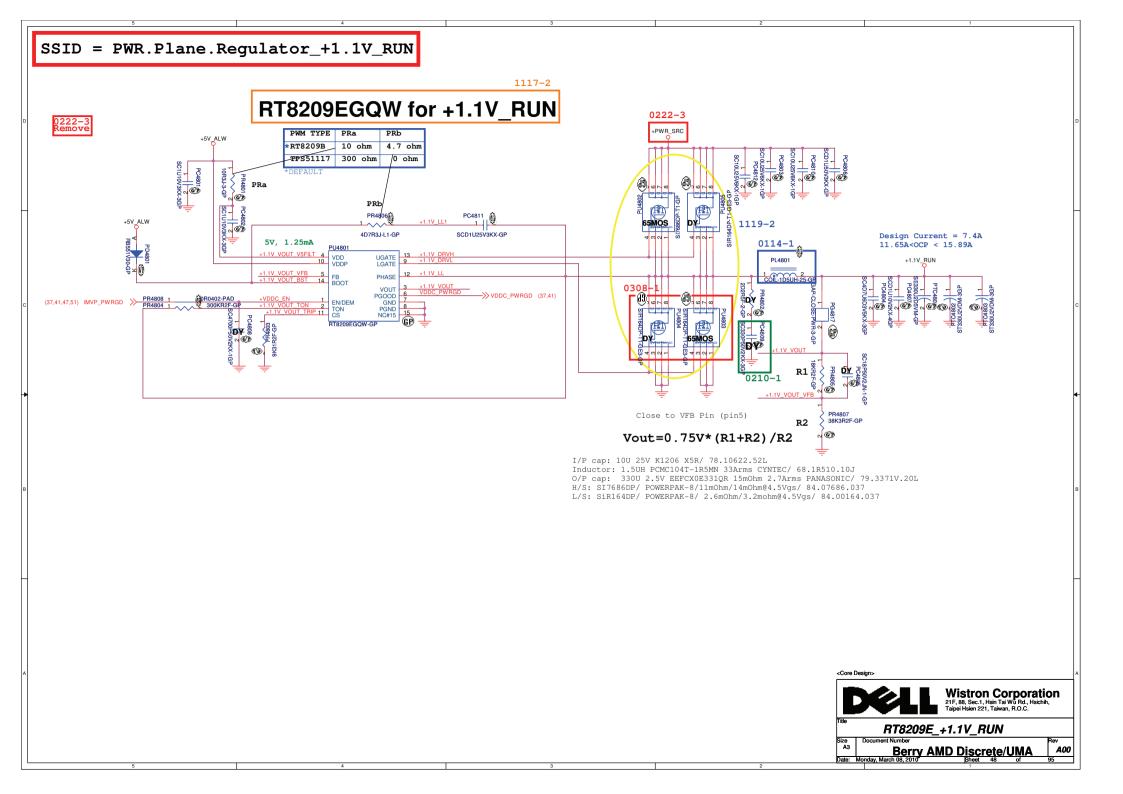


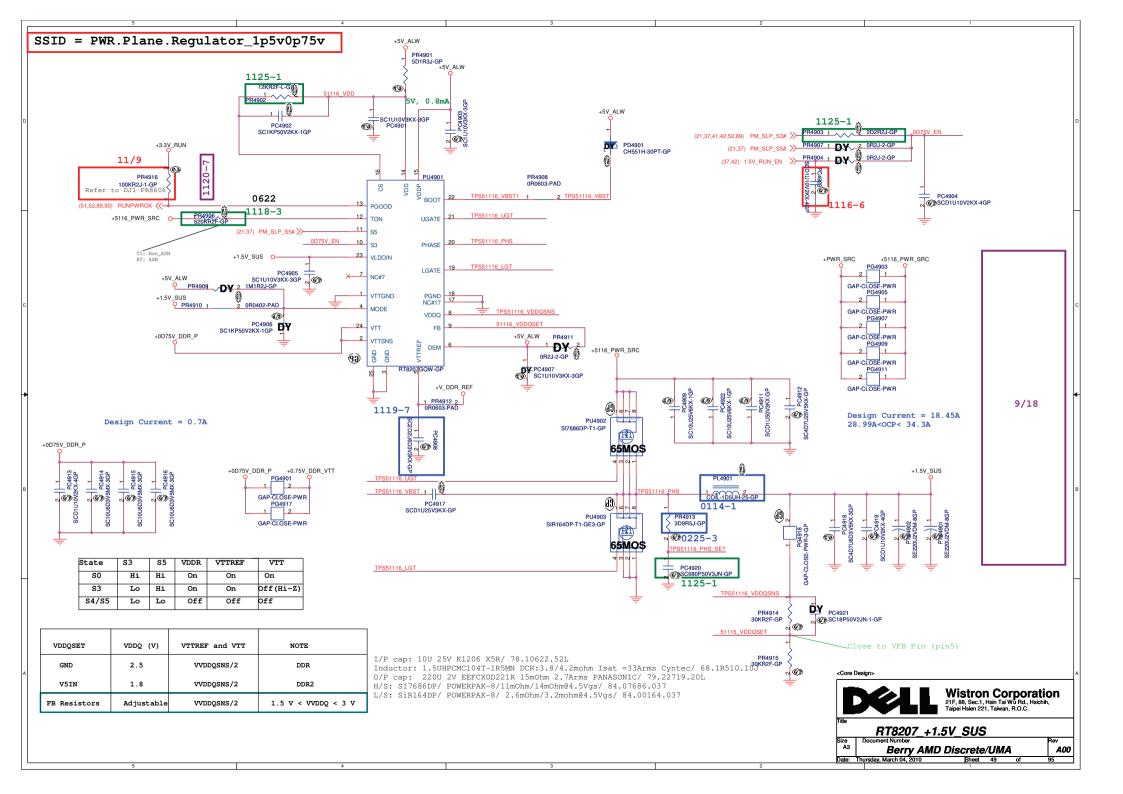






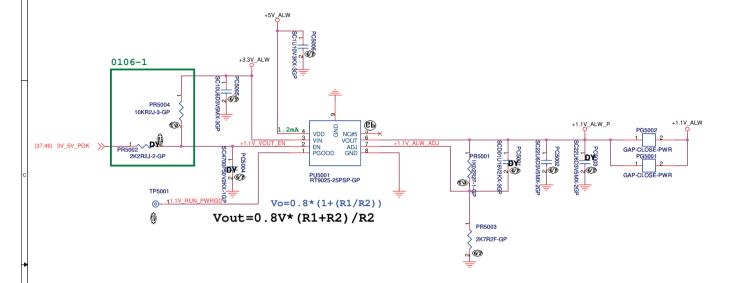


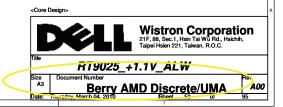


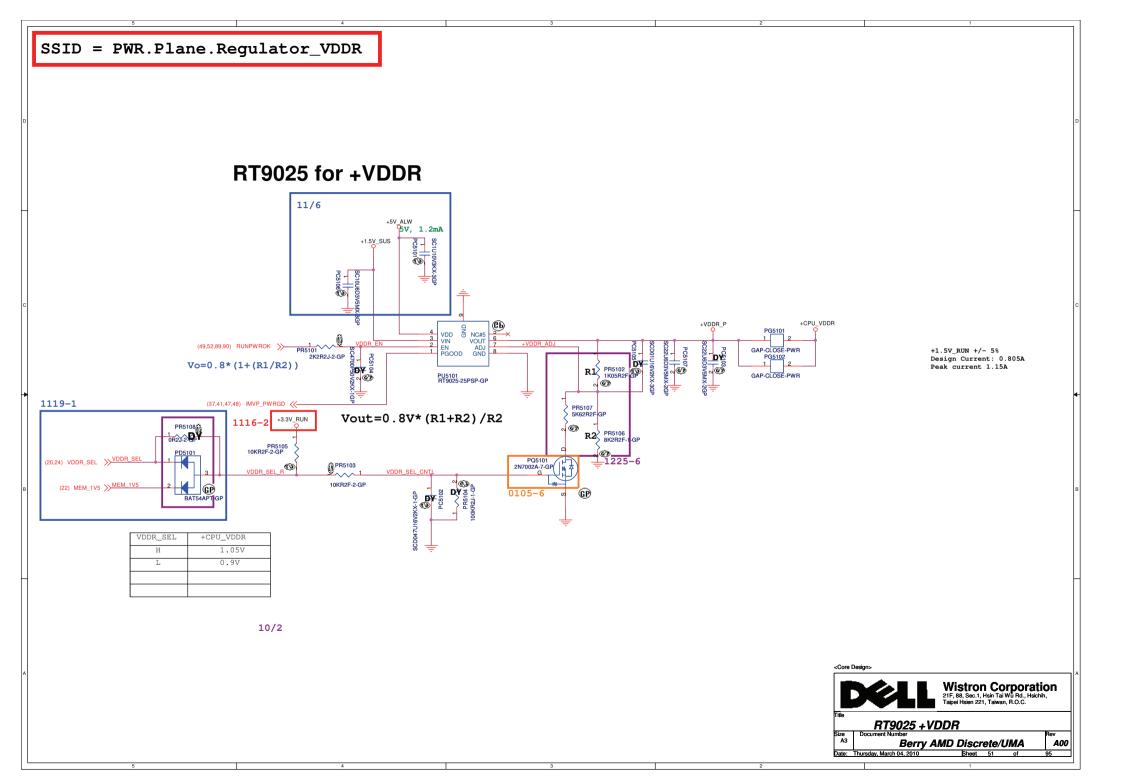


SSID = PWR.Plane.Regulator\_+1.1V\_ALW

# RT9025 for +1.1V\_ALW

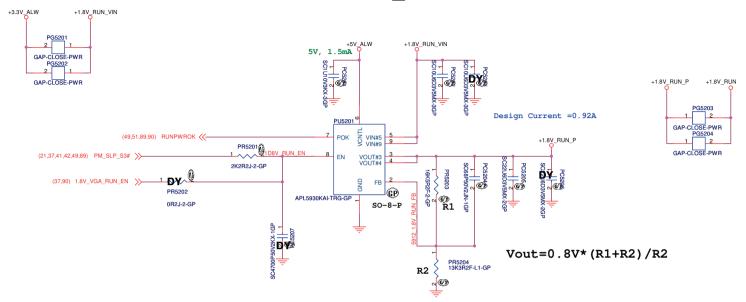




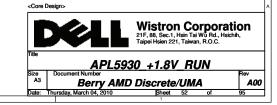


SSID = PWR.Plane.Regulator\_1p8v

## **APL5930 for +1.8V\_RUN**



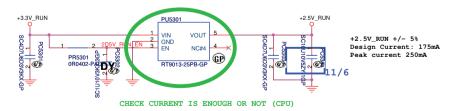
SSID = PWR.Plane.Regulator\_1p8v

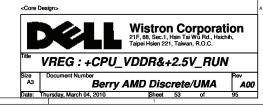


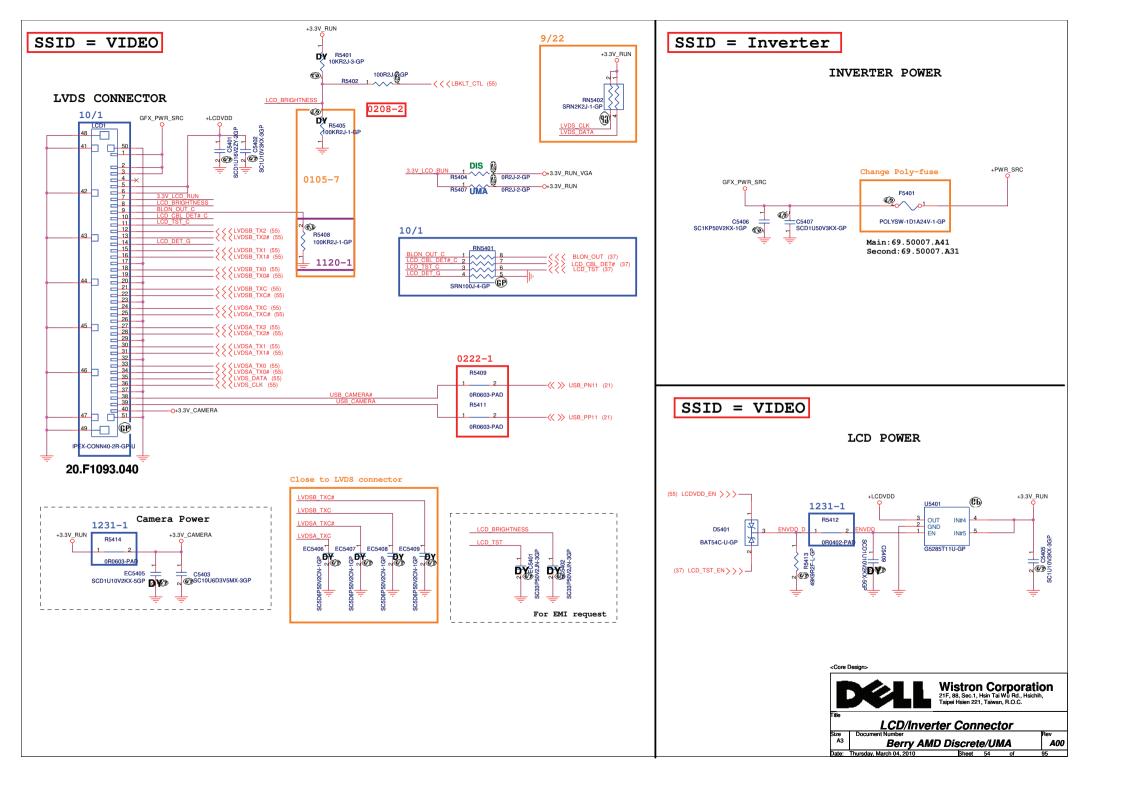
SSID = PWR.Plane.Regulator\_0P9v

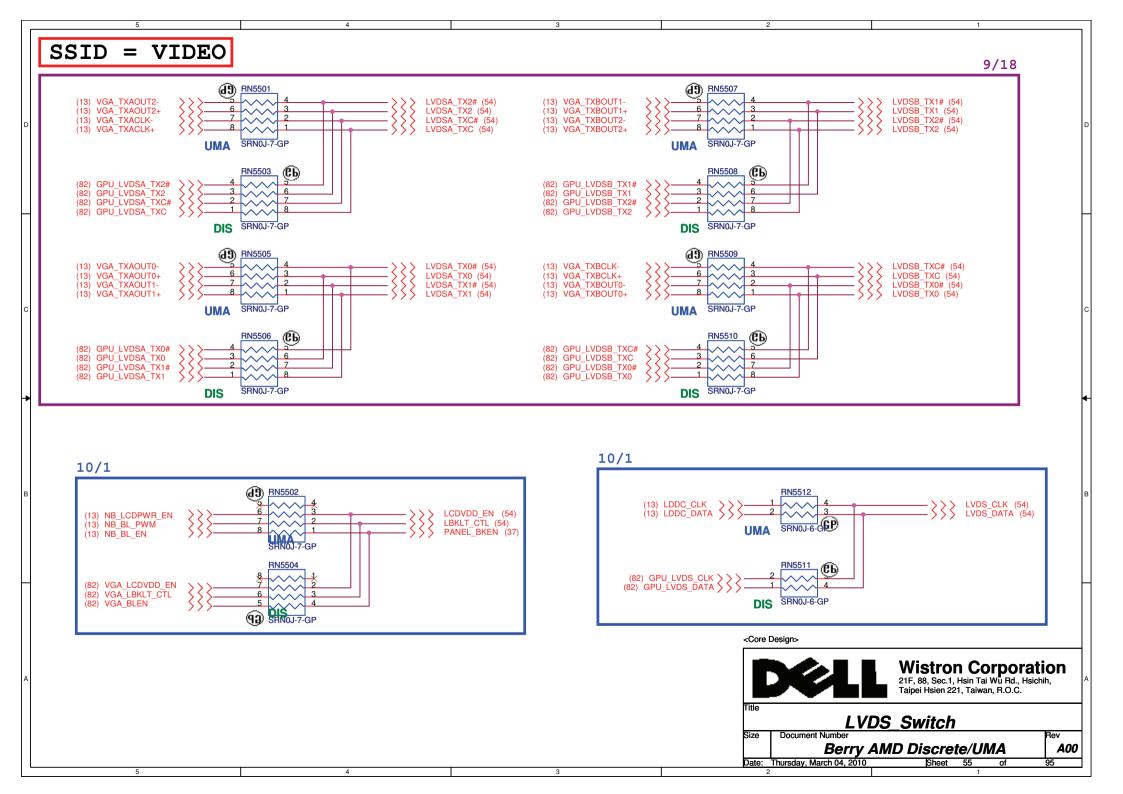
SSID = PWR.Plane.Regulator\_2p5v

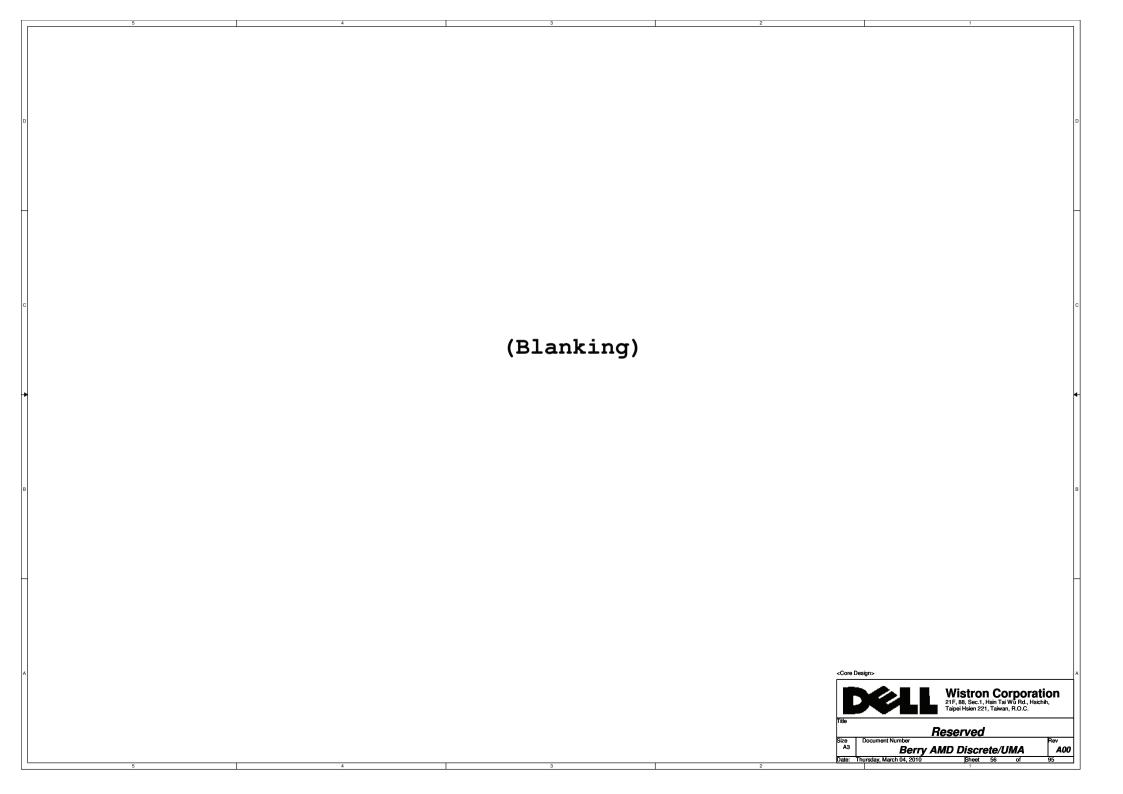
## RT9013-25PB for +2.5V\_RUN

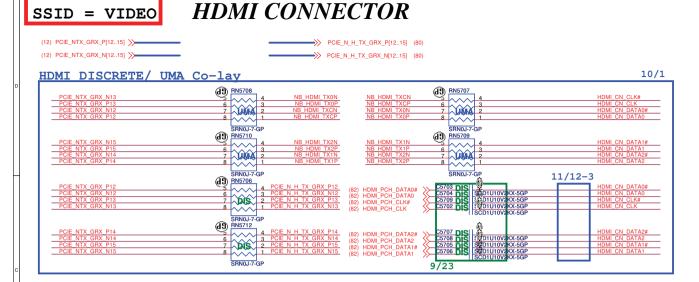


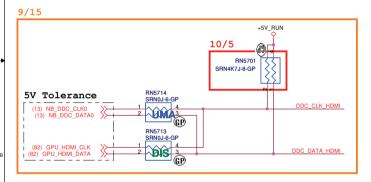


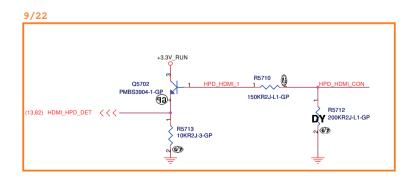


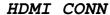


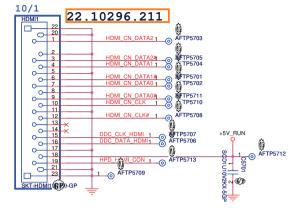


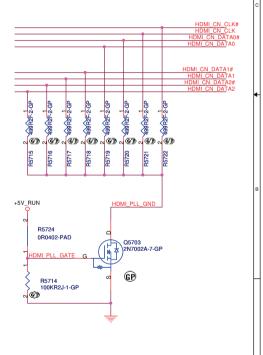














HDMI Level Shifter/Connector
Size A3 Document Number
Berry AMD Discrete/UMA

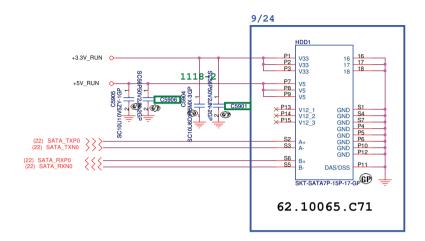
A00

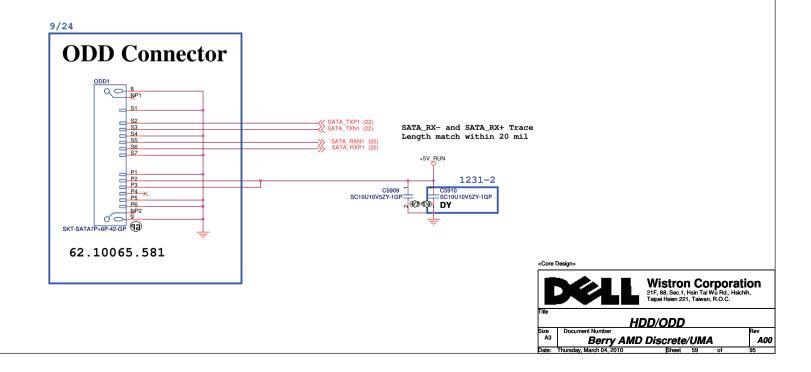
Date: Thursday, March 04, 2010 Sheet 57

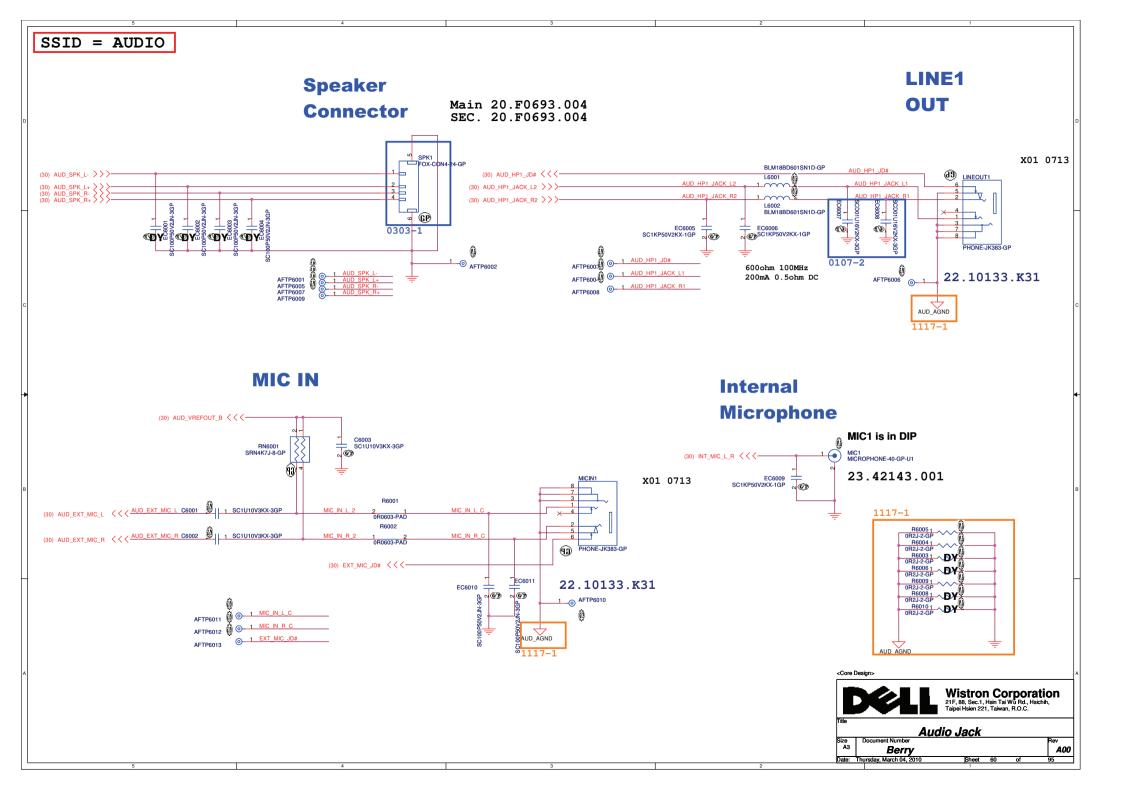
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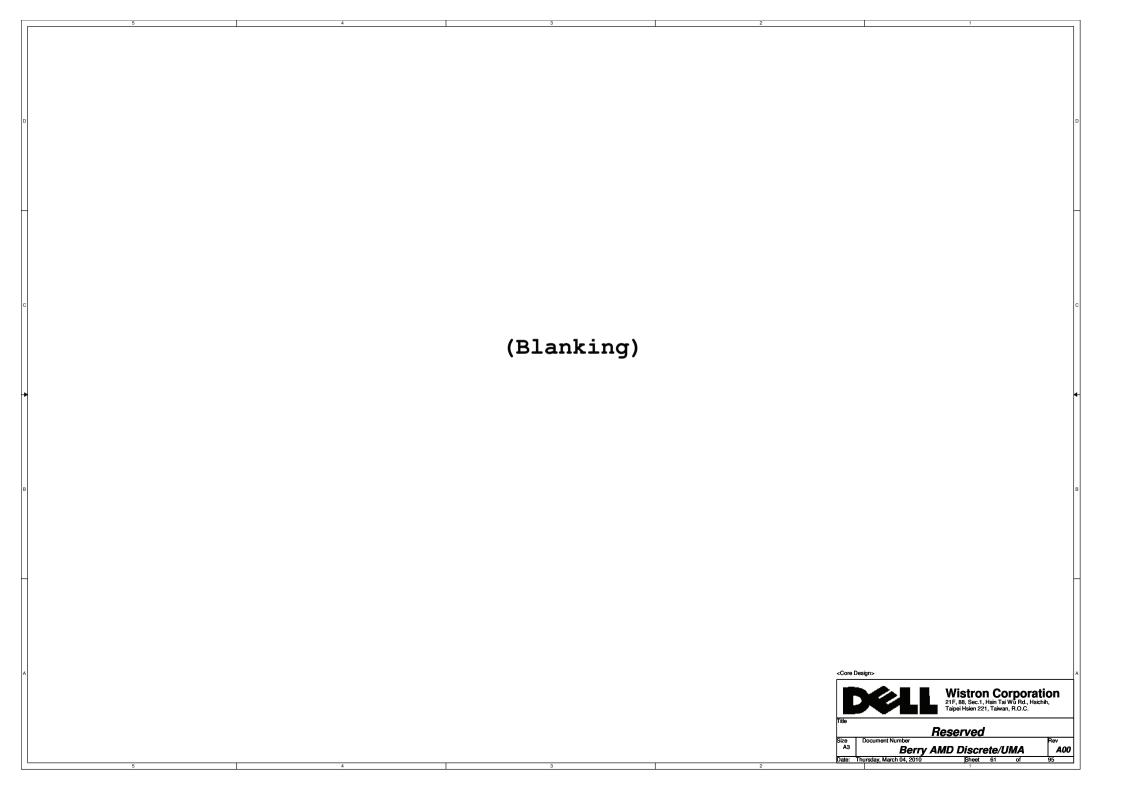
SSID = User.Interface SSID = Thermal **Fan Connector** \*Layout\* 15 mil (39) EMC2102\_FAN\_DRIVE >>> EMC2102\_FAN\_DRIVE FOX-CON3-6-GP-U AFTP5803 (i) O 1 EMC2102\_FAN\_DRIVE 20.D0210.103 20.F1293.003 D5801 CH551H-30PT-GP C5801 SC10U10V5ZY-1GP Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wü Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. ITP/Fan Connector Berry AMD Discrete/UMA A00 SSID = SATA

## **SATA HDD Connector**



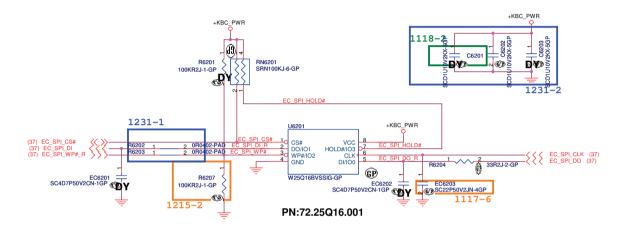




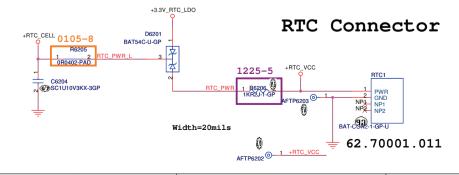


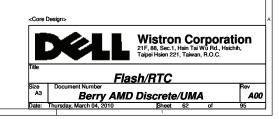
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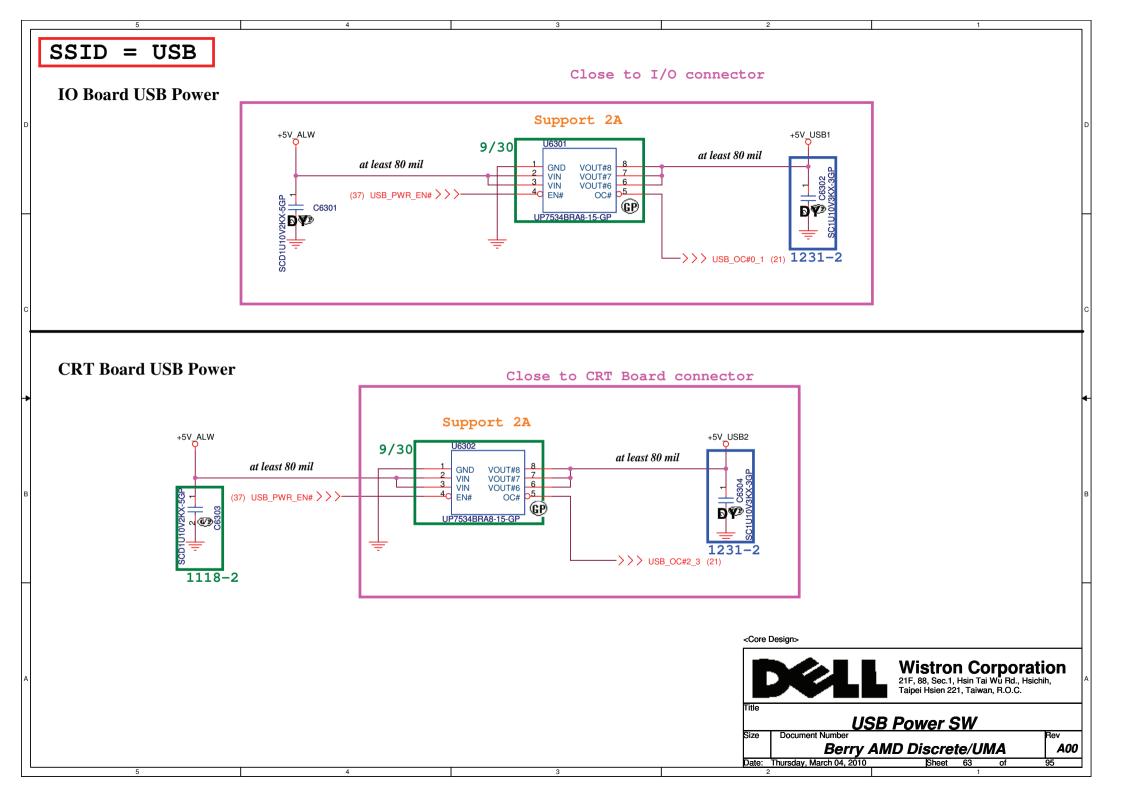
### SPI FLASH ROM (16M bits) for KBC

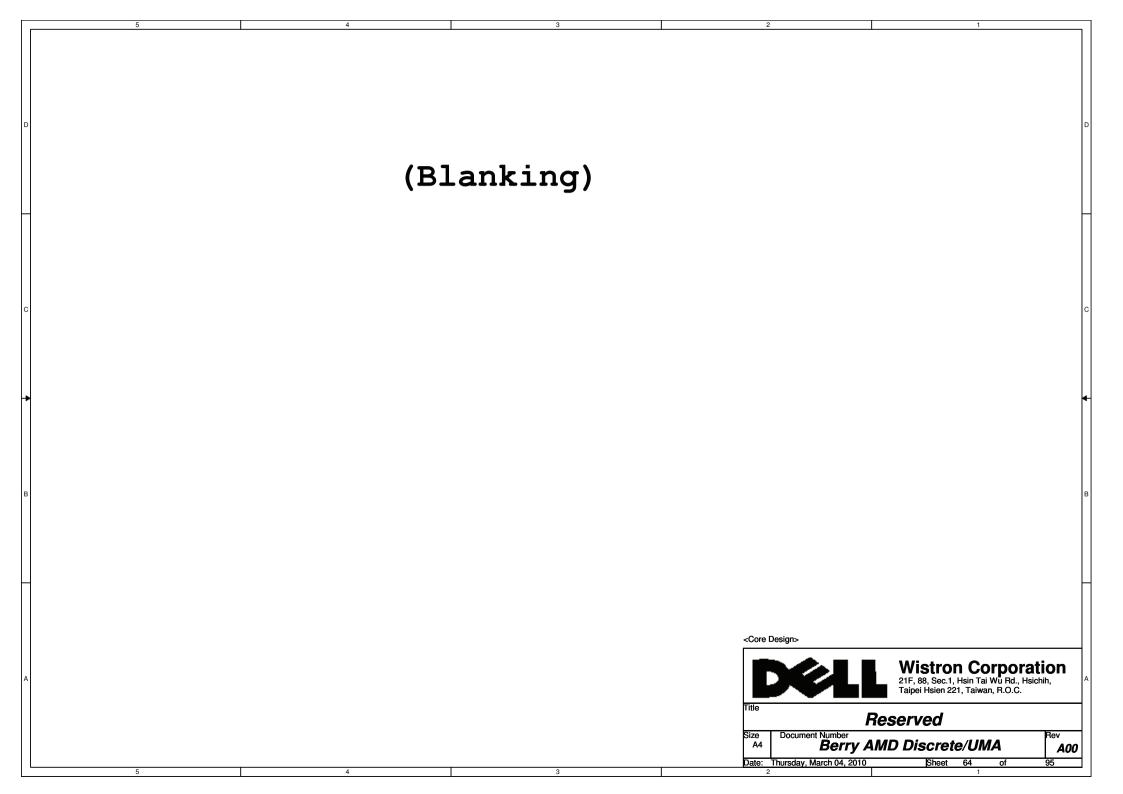


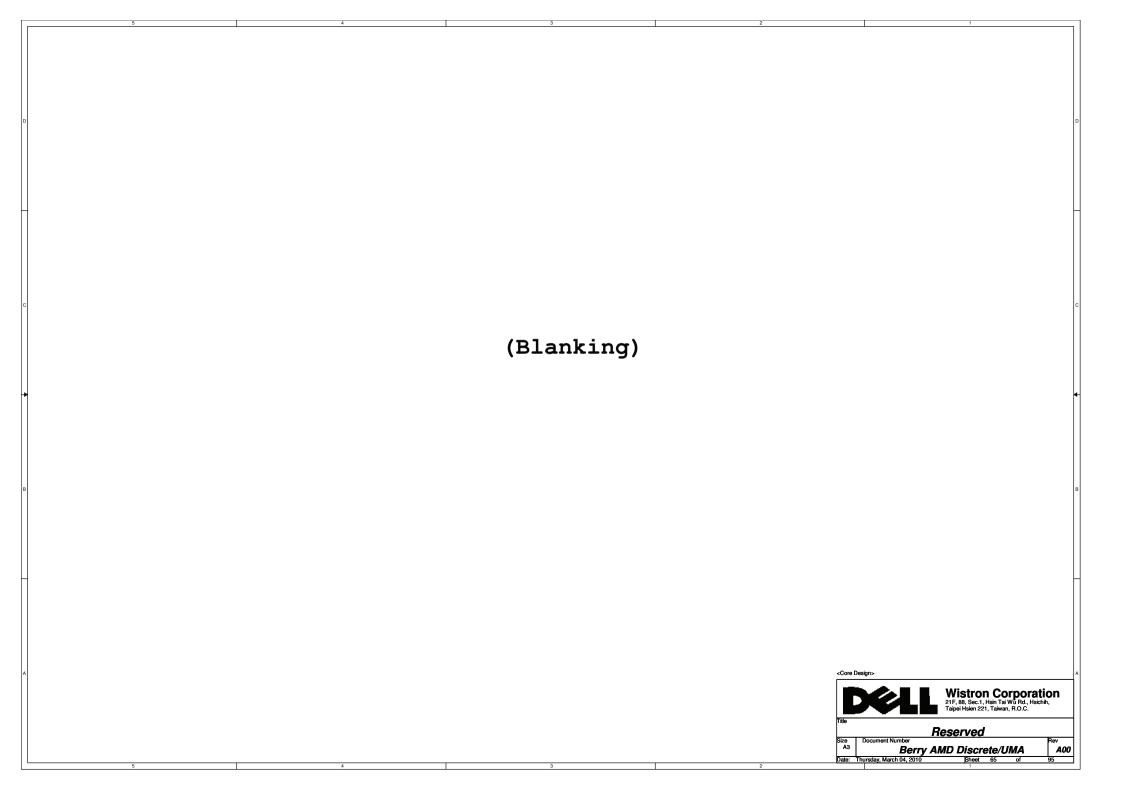


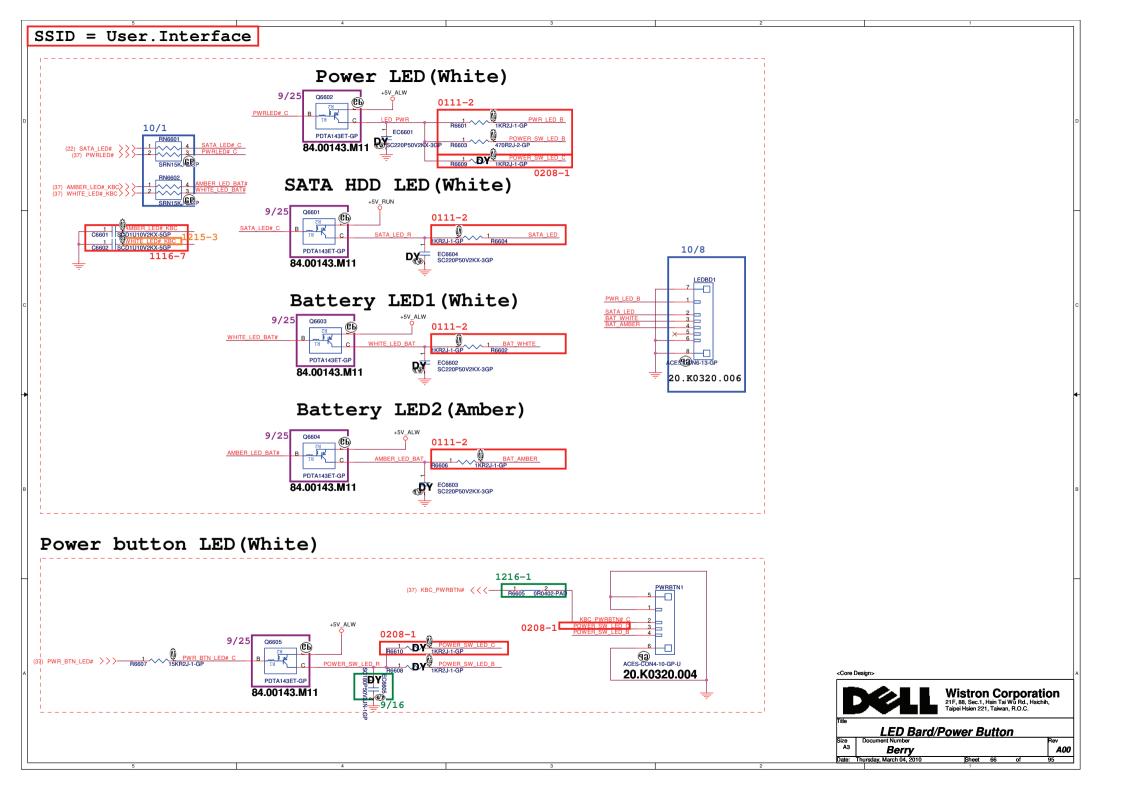


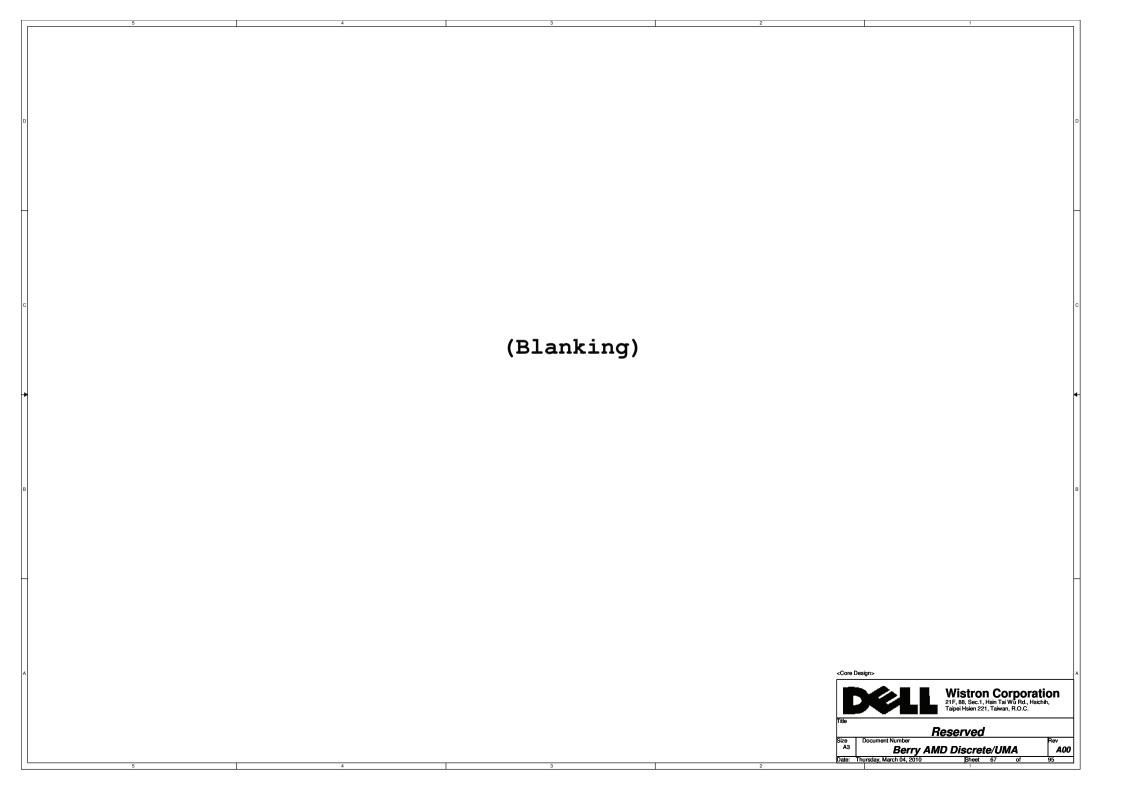






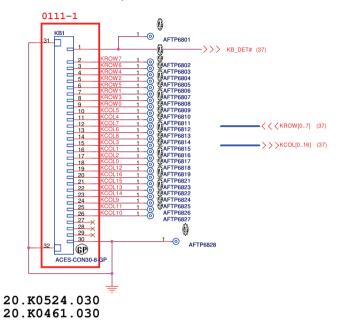






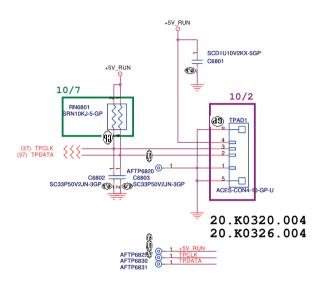


### **Internal KeyBoard Connector**

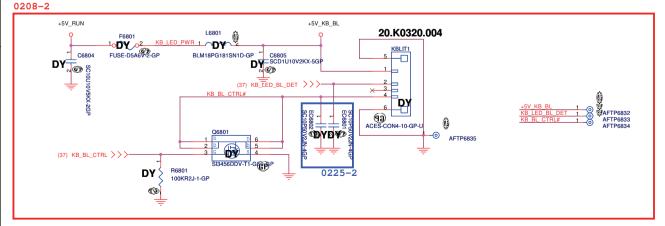


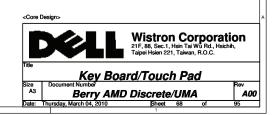
#### SSID = Touch.Pad

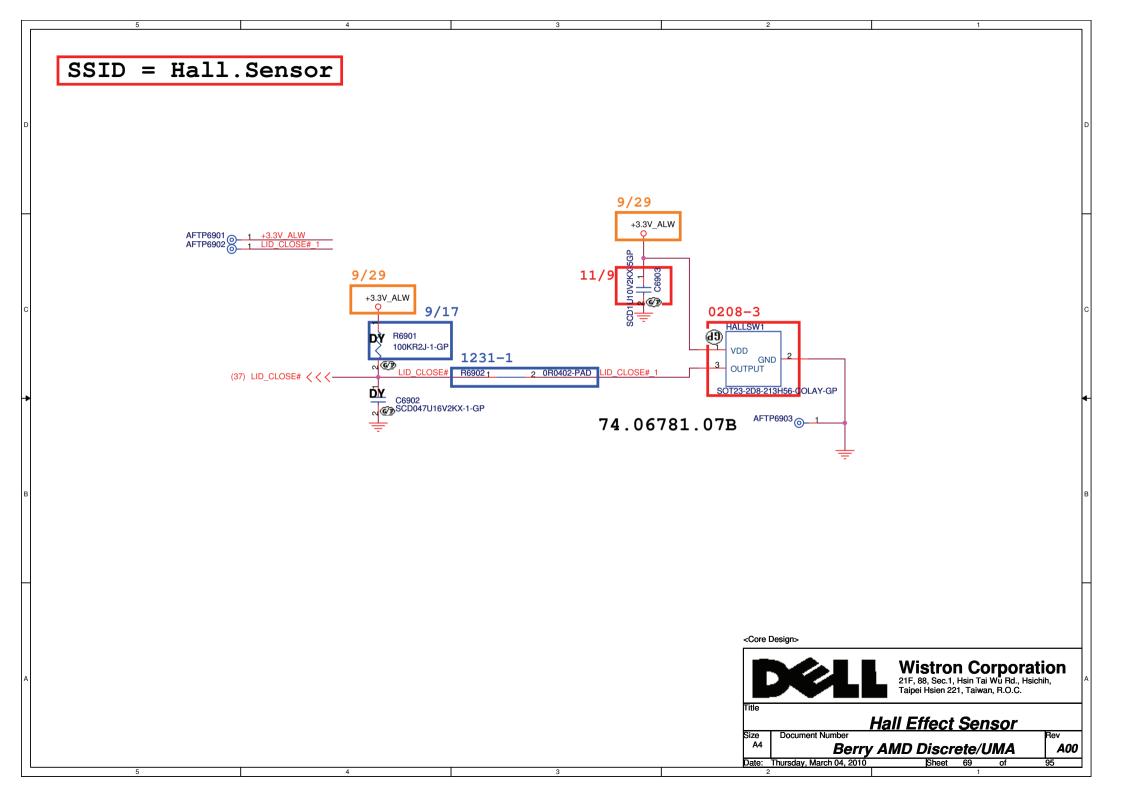
#### TouchPad Connector

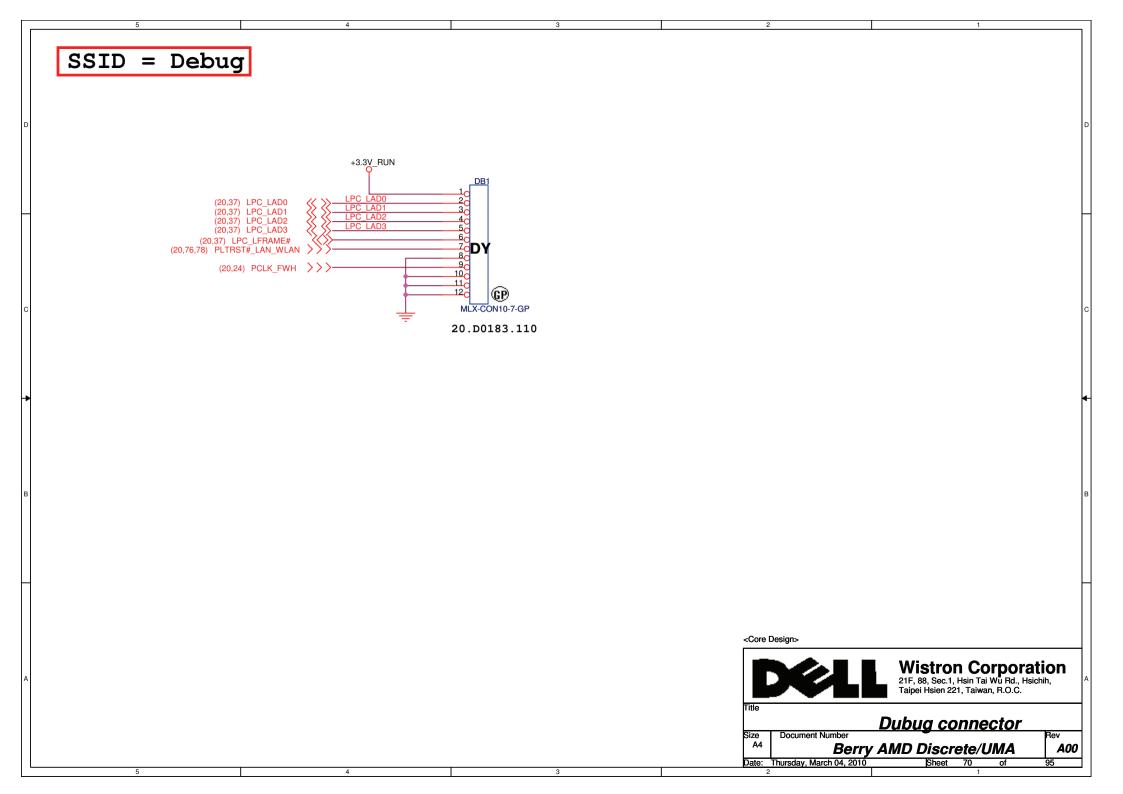


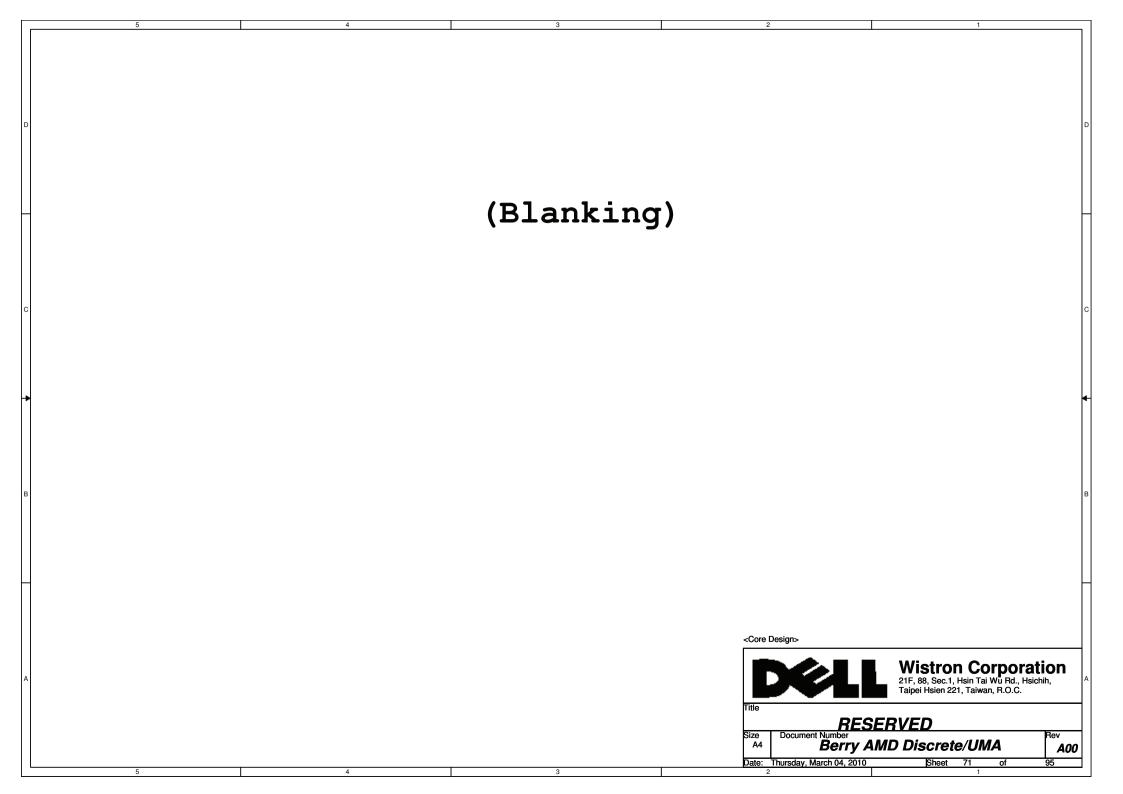
### KB Backlight Connector

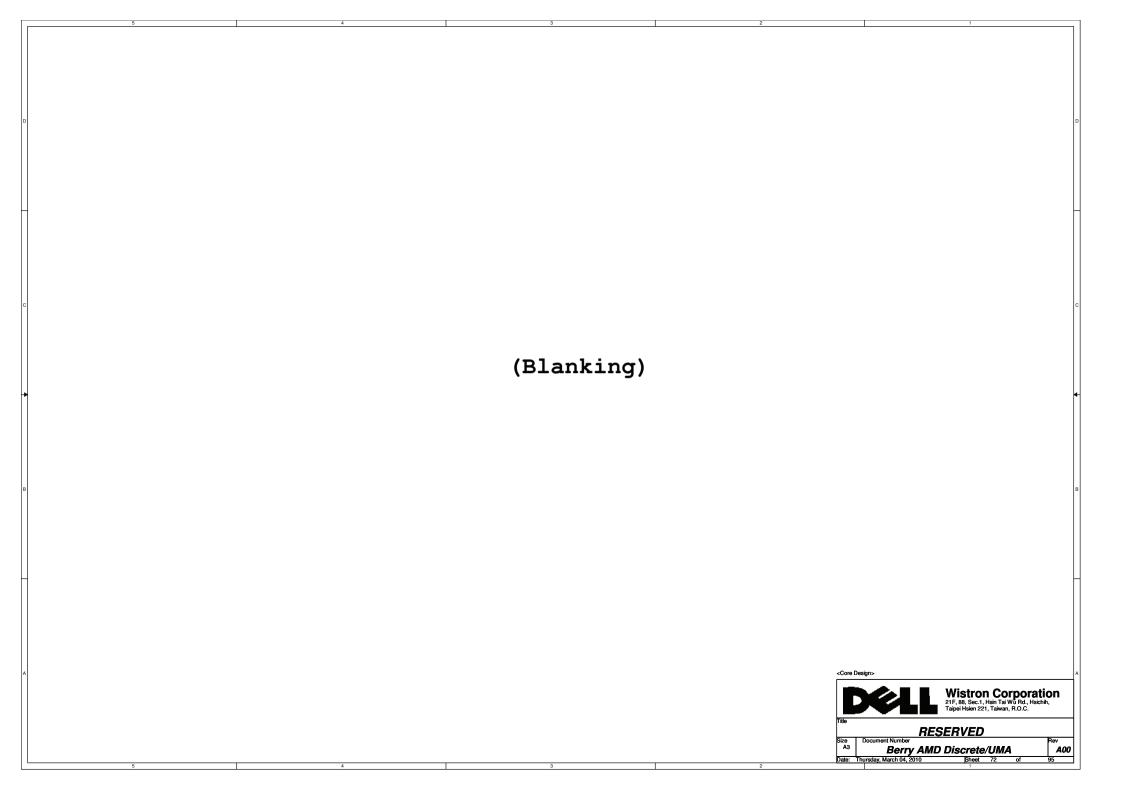


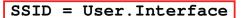




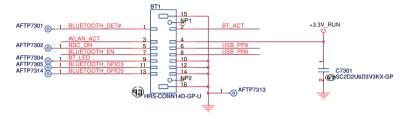


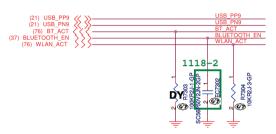




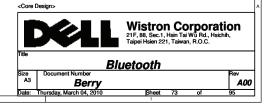


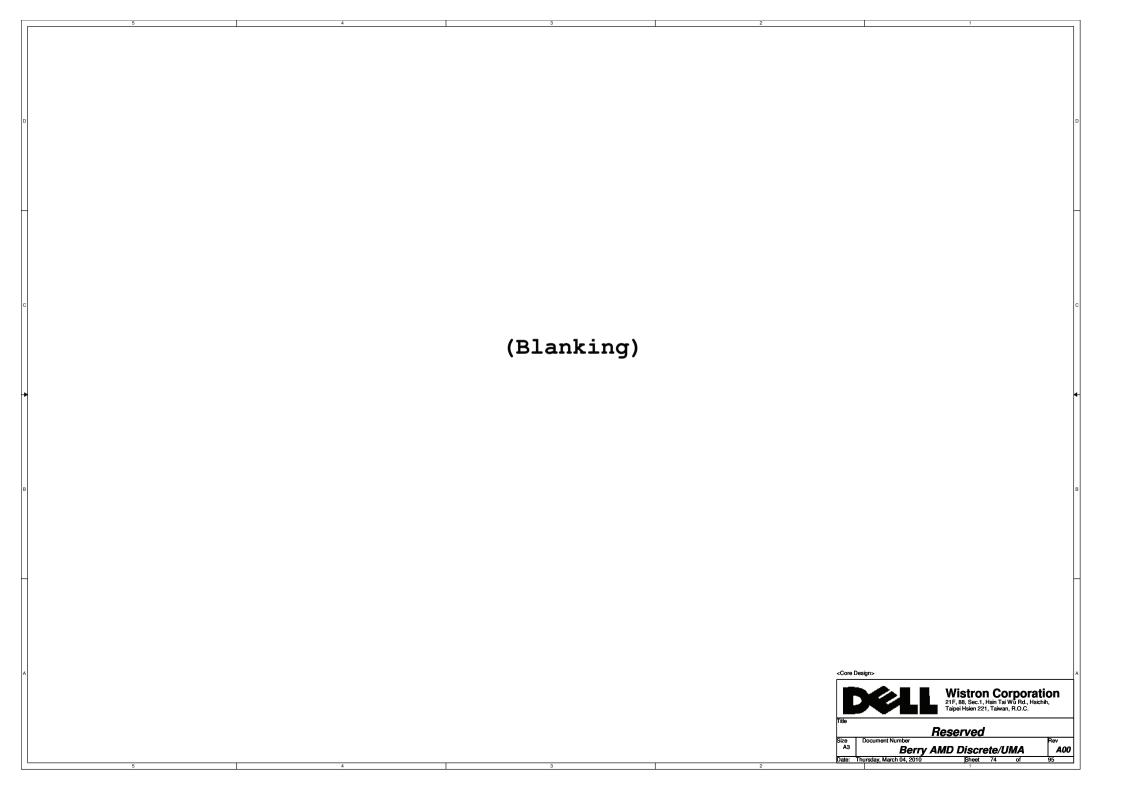
#### Bluetooth Module conn.

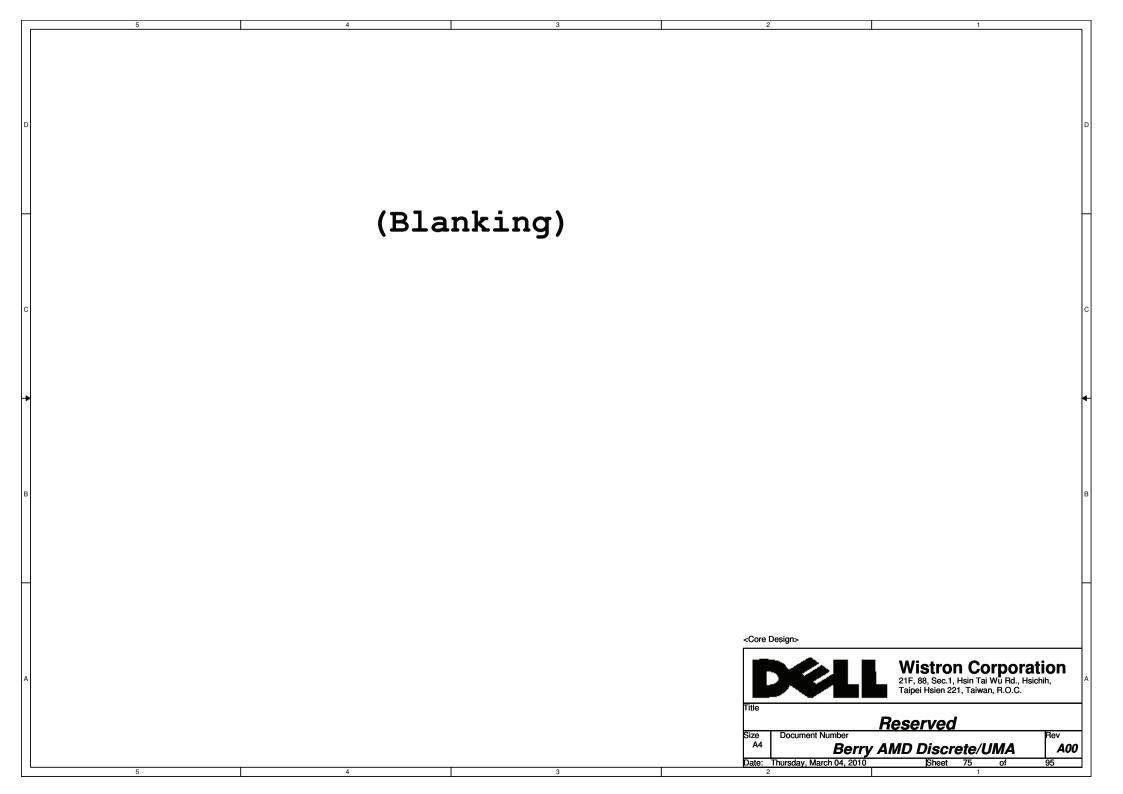


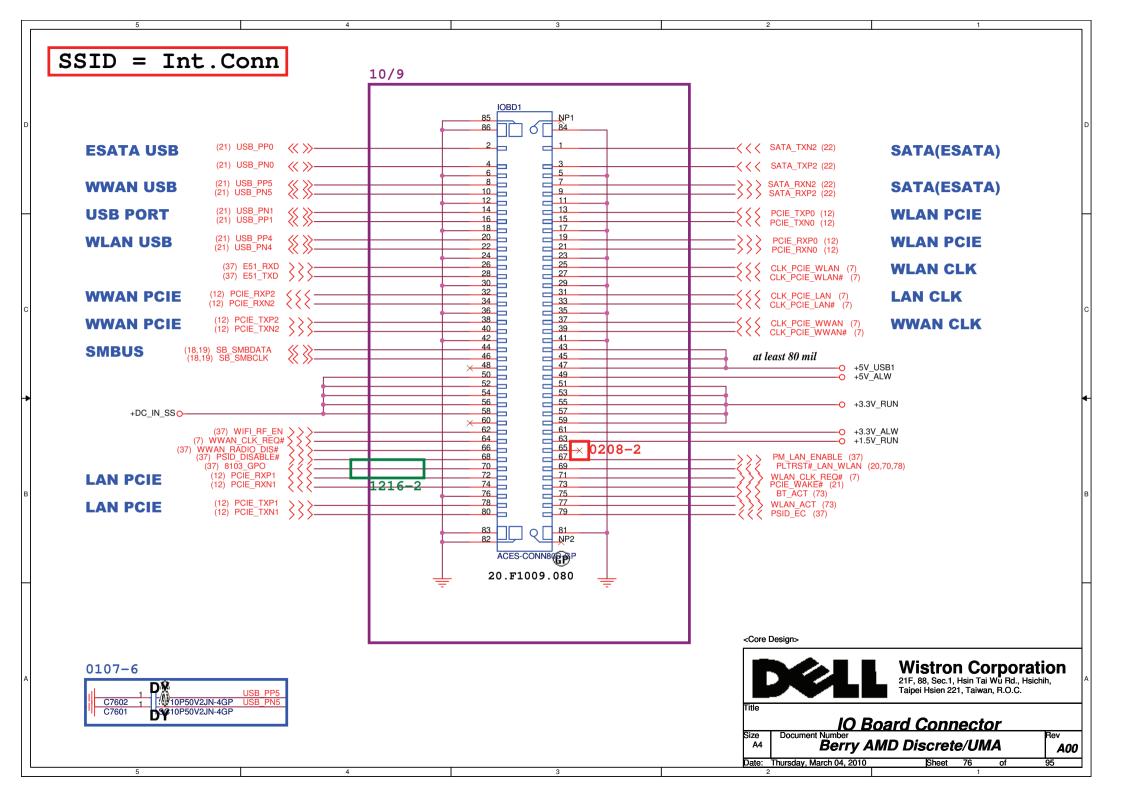


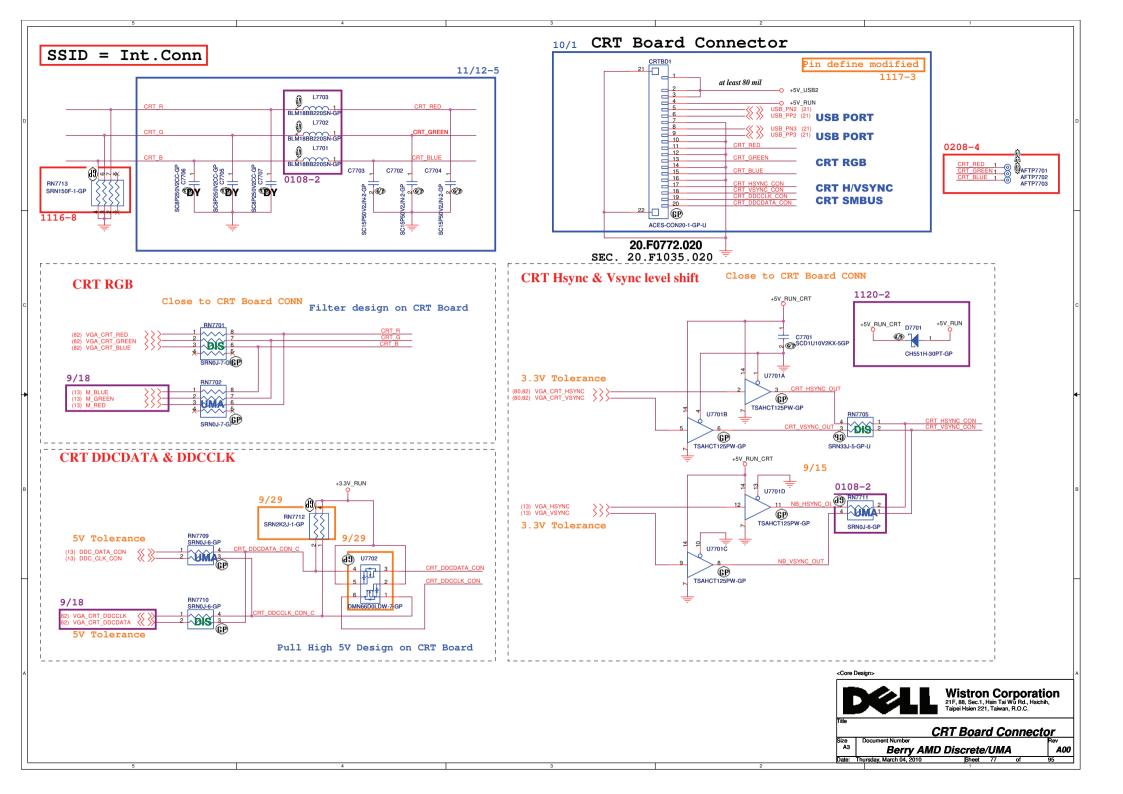
AFTP7316 AFTP7317 AFTP7315 AFTP7318 AFTP7319 AFTP7320	1 1 1 1 1	WLAN_ACT BLUETOOTH_EN BT ACT +3.3V RUN USB_PP9 USB_PN9
AFTP7319 AFTP7320	1	USB_PP9

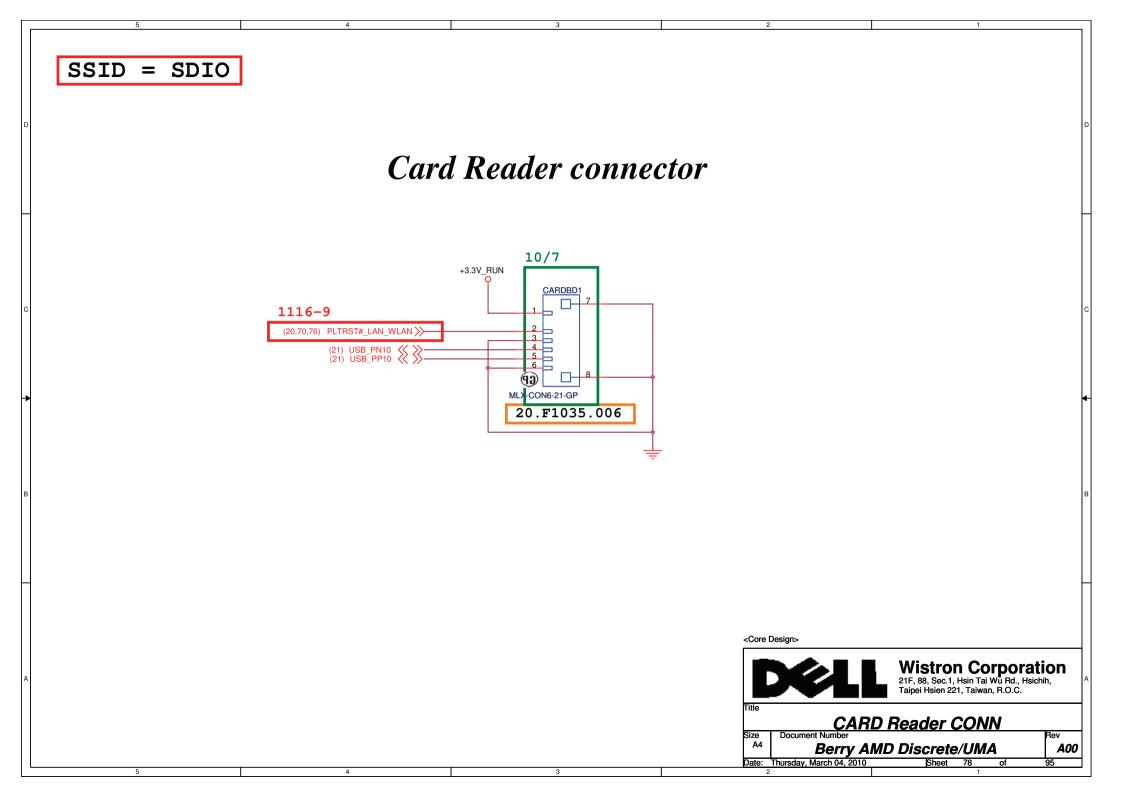


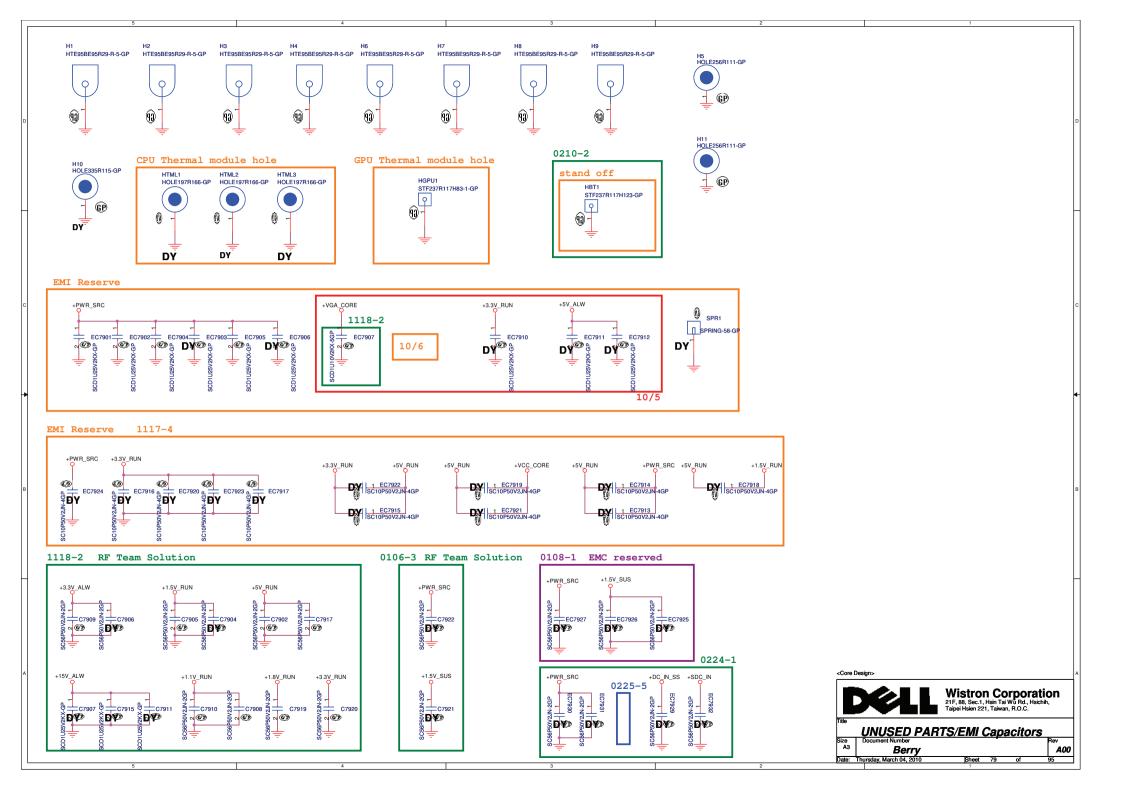


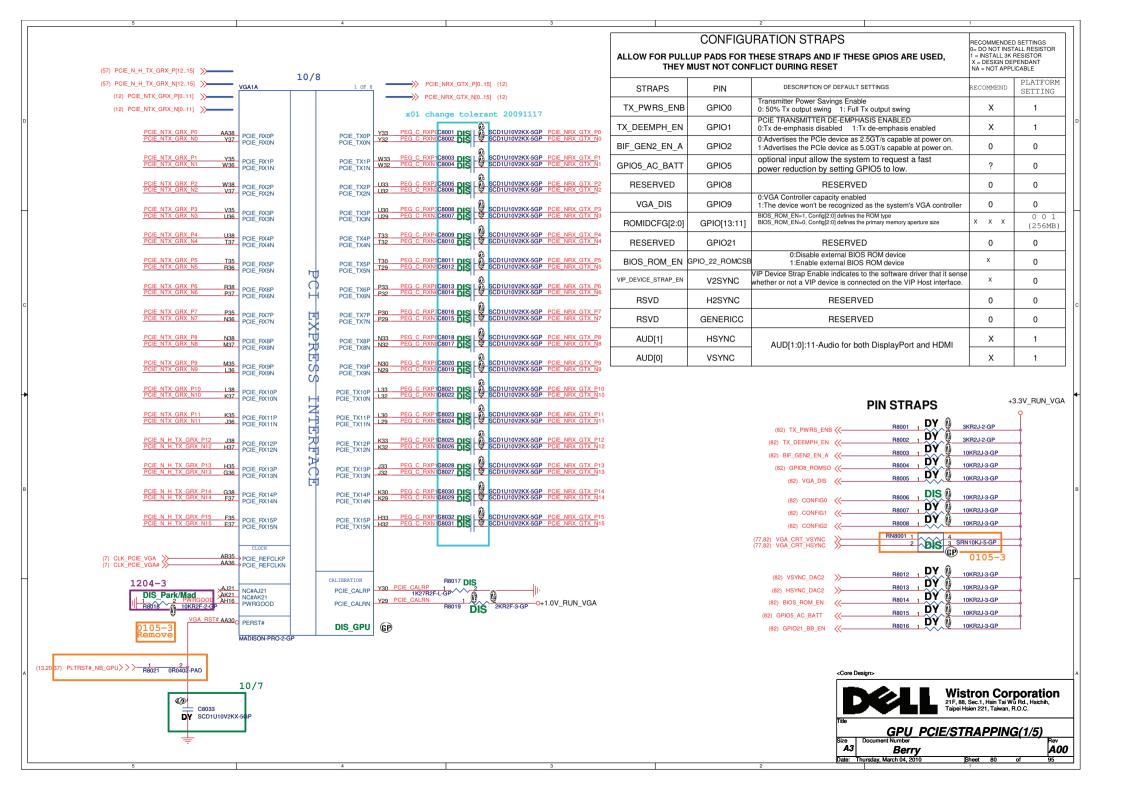


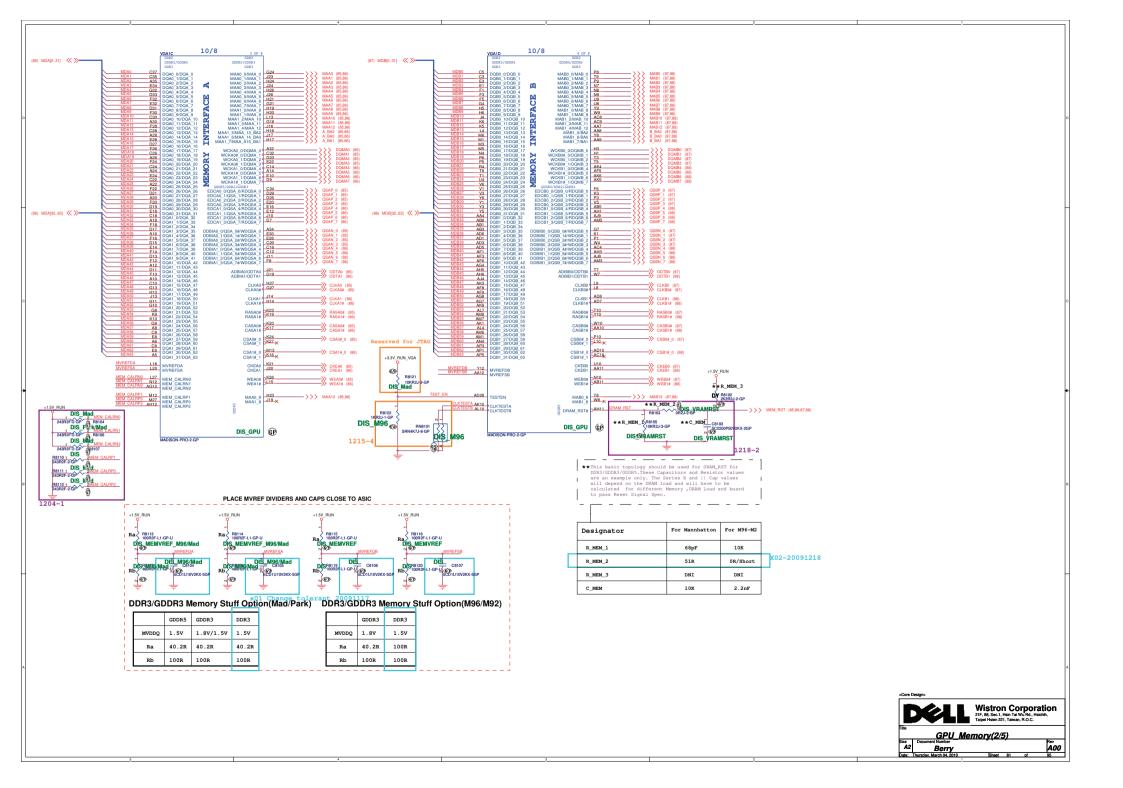


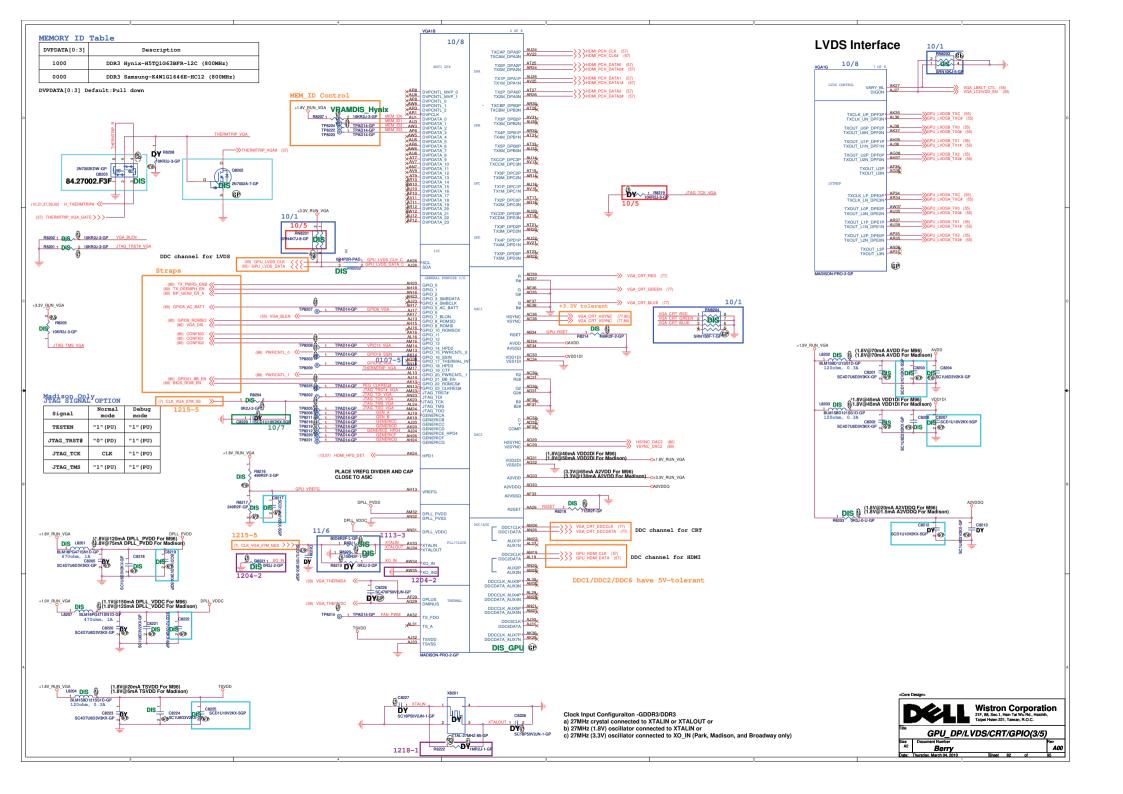


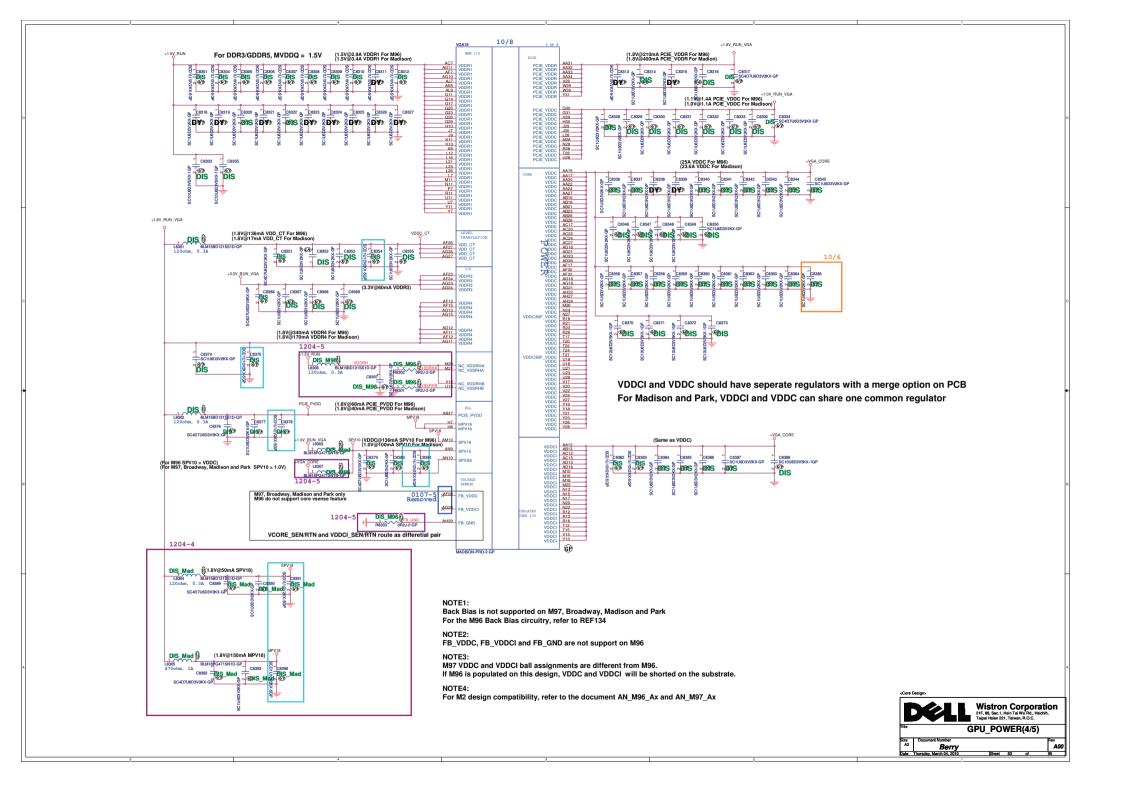


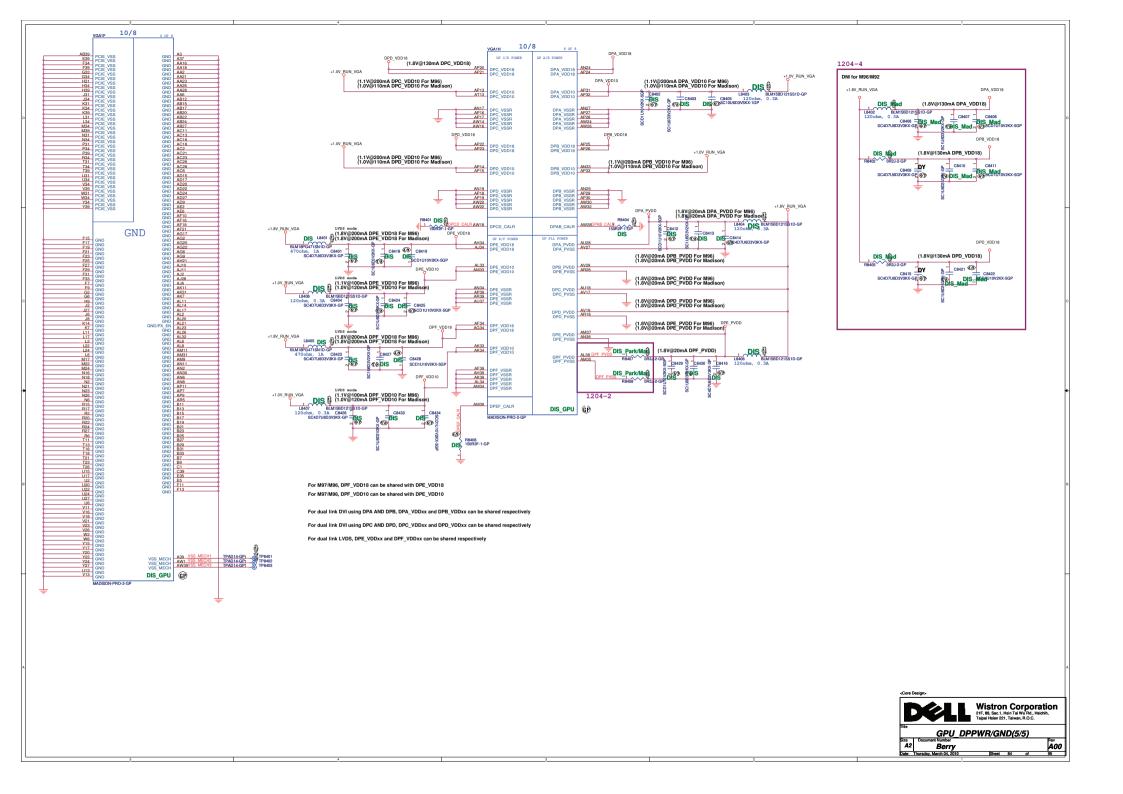


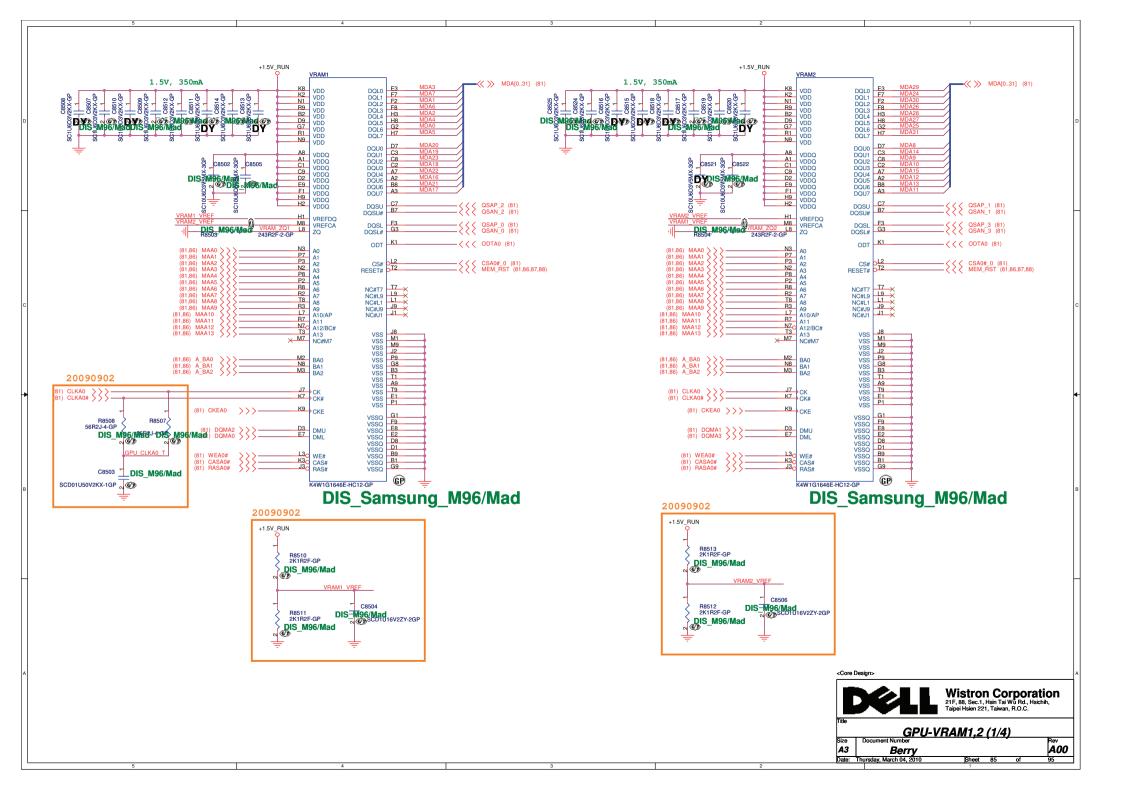


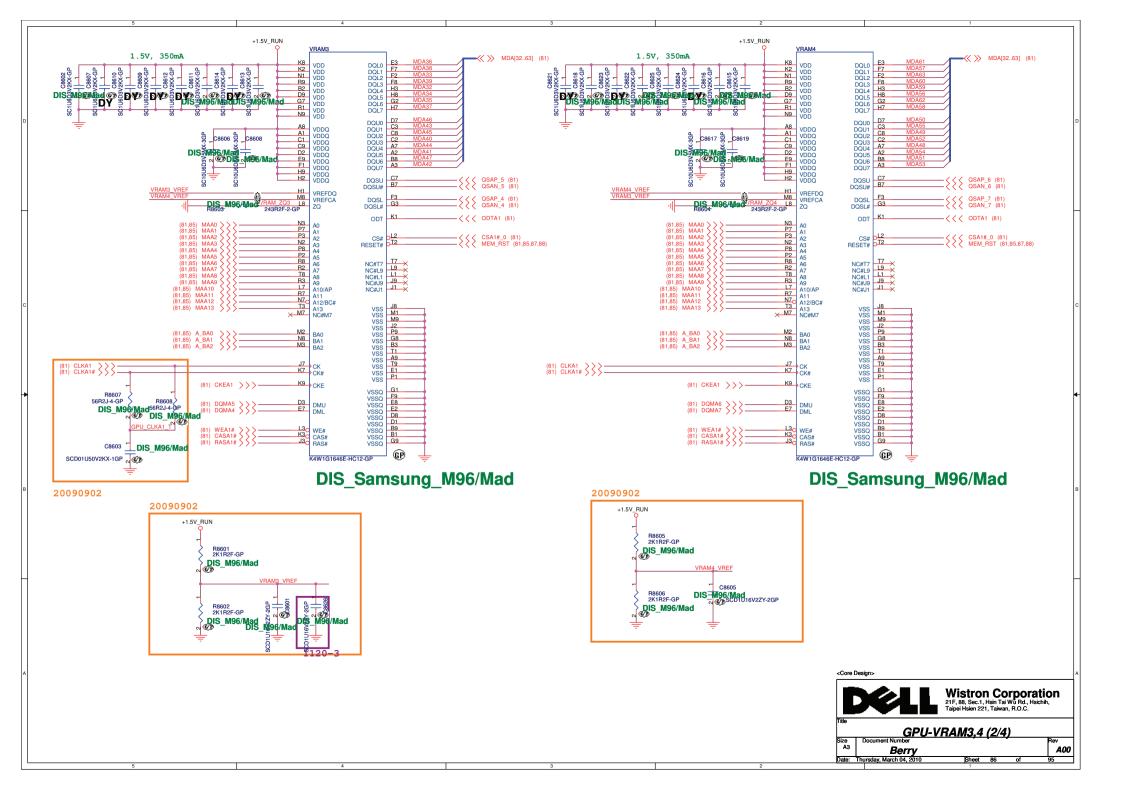


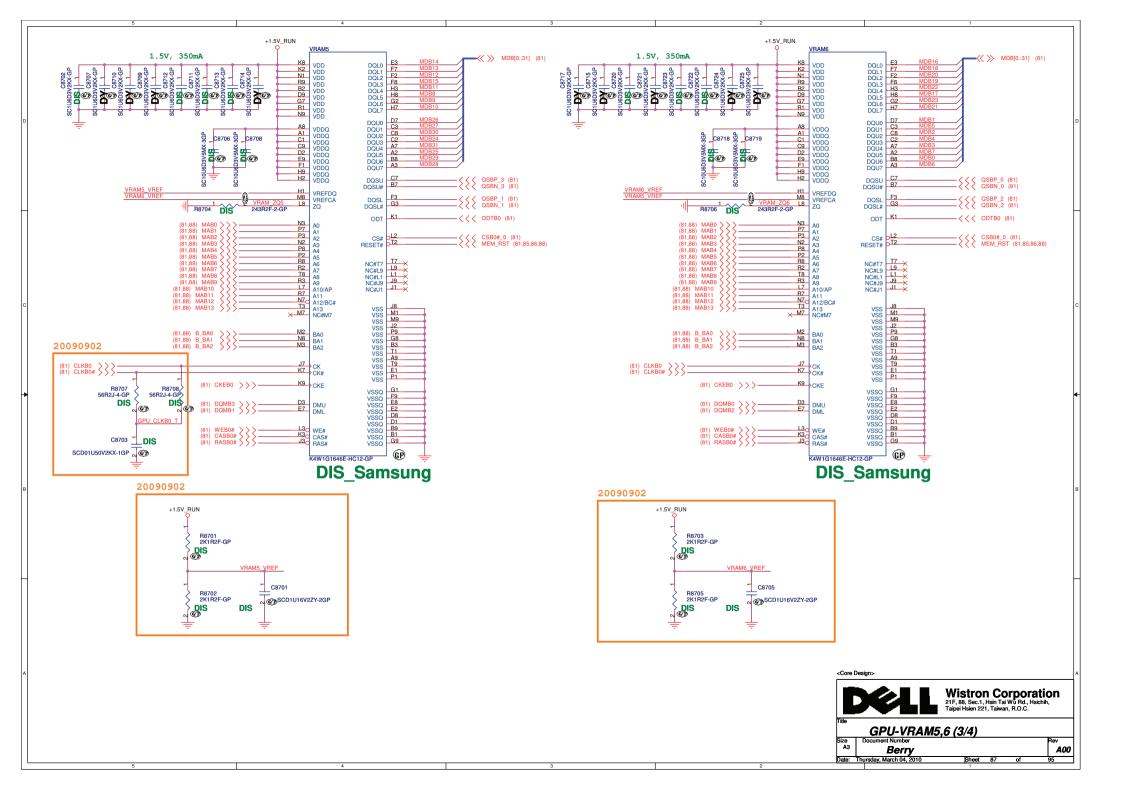


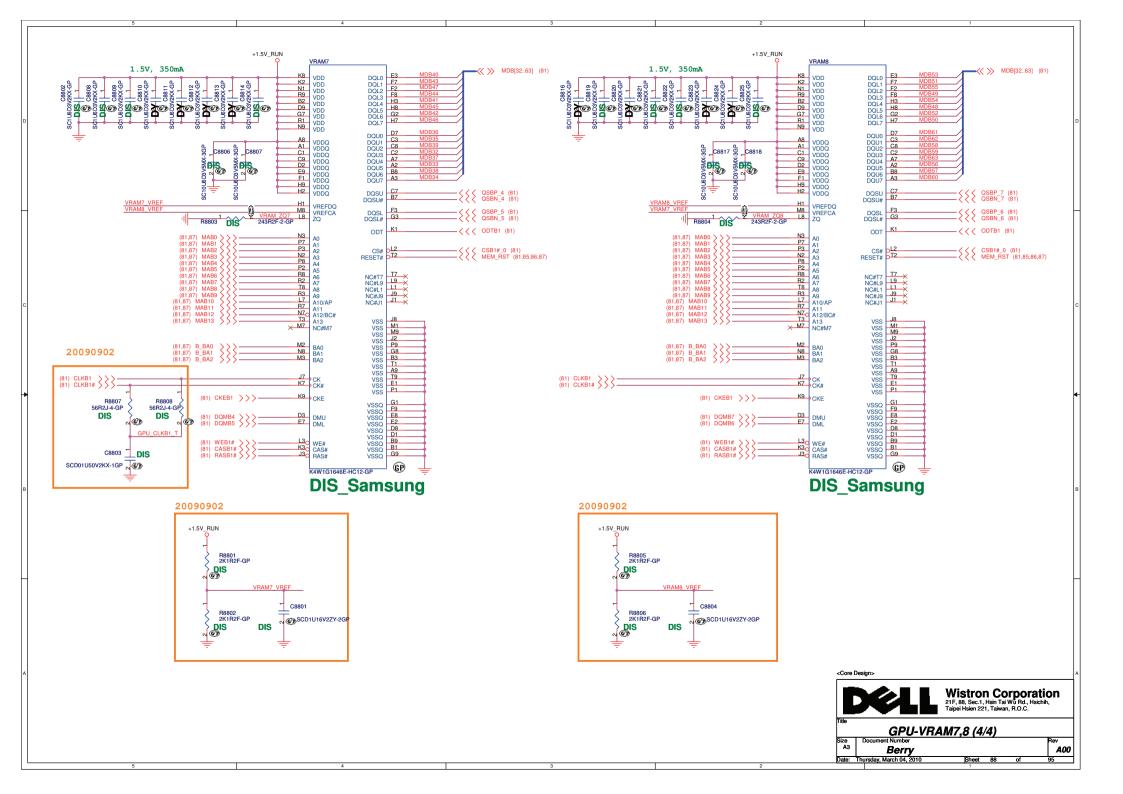






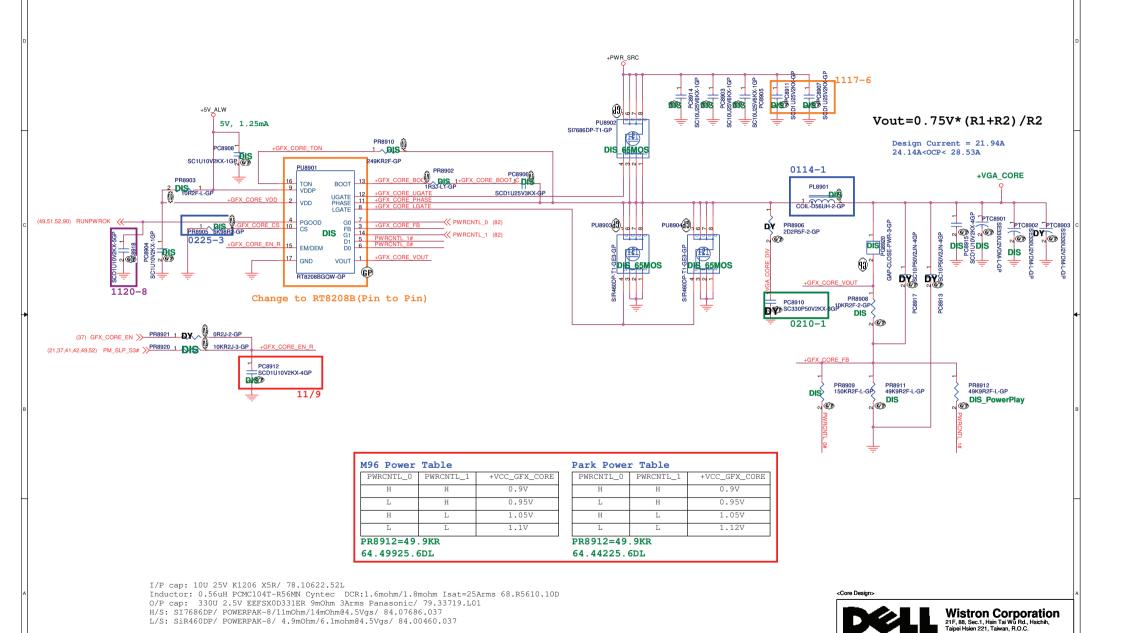






SSID = Video.PWR.Regulator

# RT8208AGQW for +VCC\_GFX\_CORE



RT8208B\_+VCC\_GFXCORE

DOCUMENT Number

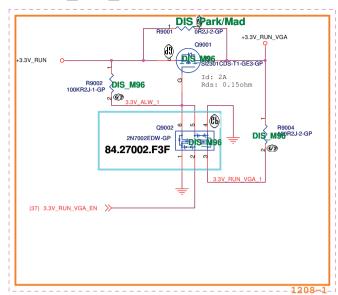
Berry AMD Discrete/UMA

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## APL5930 for +1.8V\_RUN\_VGA

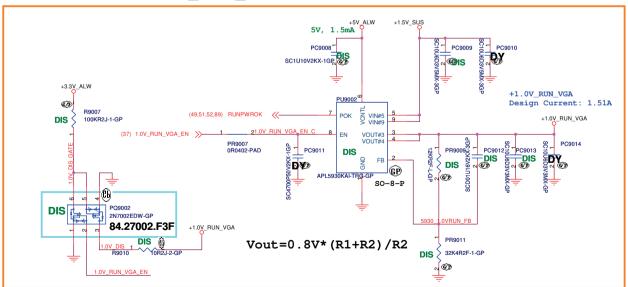
#### +1.8V\_RUN\_VGA\_P +1.8V\_RUN\_VGA +1.8V\_RUN\_VGA\_VIN +3.3V\_RUN +1.8V\_RUN\_VGA\_VIN GAP-CLOSE-PWR 5V. 1.5mA PG9003 1 DIS<sup>2</sup> PC9003 PC9004 PC9002 GAP-CLOSE-PWR DIS SC1U10V2KX-1GP GAP-CLOSE-PWR Design Current =1.13A +5V ALW GAP-CLOSE-PWR (49.51.52.89) RUNPWROK R9006 +1.8V\_RUN\_VGA\_P DIS 100KR2J-1-GP (37,52) 1.8V\_VGA\_RUN\_EN >>-DIS VOUT#8 PC9006 Vo=0.8\*(1+(R1/R2)) DIS No N APL5930KAI-TRG-GP © √ © € SO-8-P PQ9001 2N7002EDW-GP +1.8V RUN VGA 84.27002.F3F Vout=0.8V\*(R1+R2)/R2PR9006 13K3R2F-L1-GP 1.8V VGA RUN EN

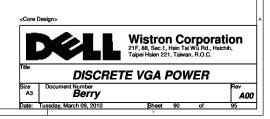
#### +3.3V\_RUN\_VGA

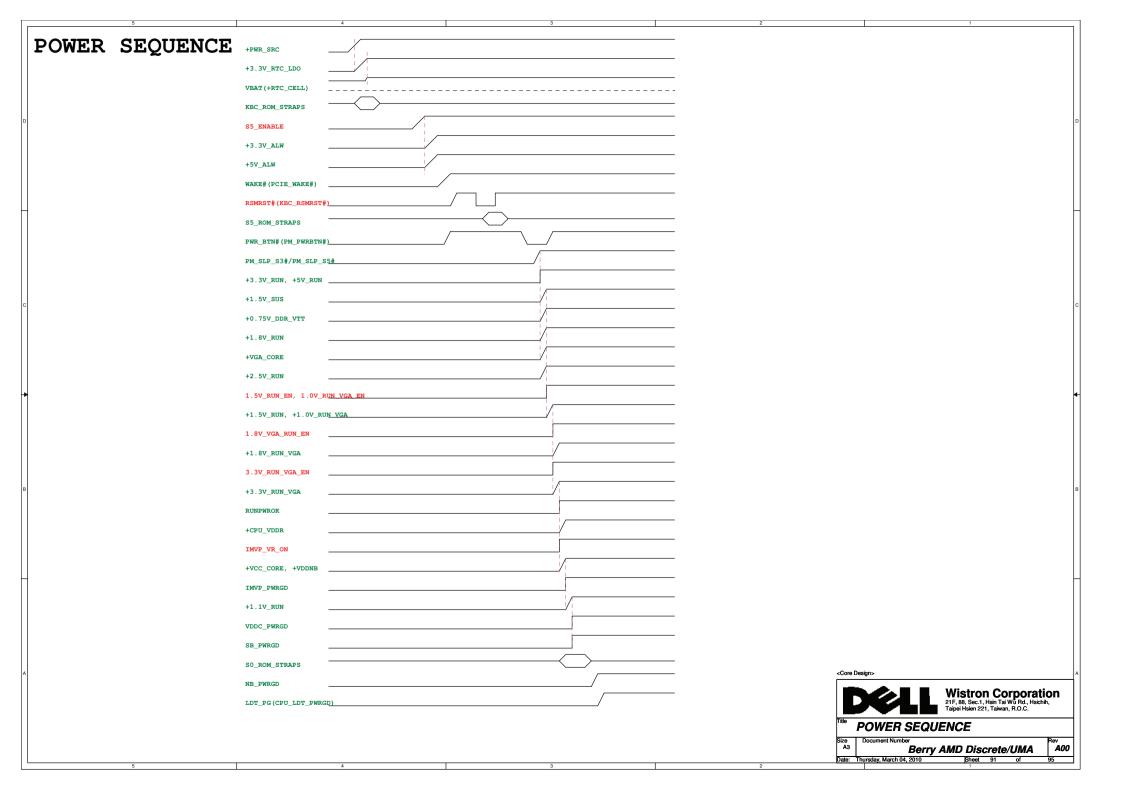


## APL5930KAI for +1.0V\_RUN\_VGA

Will be Change to +1.0V\_RUN\_VGA







### Change notes - Page 1

ERSON	DATE	ITEM	PAGE	Modify List	Issue Description	OWNER		
X01 11/6	1	10	Add C1002 10uF, C1007, EC1001 0.1uF, C1008 10pF.	Insure signal quality.	EE		]	
	2	13	Change R1314 to 4.7K.	Meet CRB.	EE		1	
	3	51	Swap PU5101 pin3, pin4.	Correct input voltage level.	EE			
	4	82	Add R8210 OR.	Reserve GPU clock input source.	EE		]	
11/9	1	30	Change C3014 to 2.2uF.	Reduce package size.	EE			
	2	69	Change C6903 to 0.1uF.	Reduce package size.	EE		]	
	3	49	Add PR4916 100KR.	To prevent leakage in S3 status.	EE			
11/10	1	18,19	Change DIMM socket Part Number.	Request by ME.	ME		]	
		2	37	Add R3754 100KR.	To detect leakage current.	EE		]
	11/11	1	10	Modify R1028 pull-up to +1.5V_RUN.	Solve leakage in S3 status.	EE		
	11/12	1	20	Change C2011 to 18pF, C2012 to 15pF.	Set accurate clock frequency.	EE		]
		2	37	Add C3717 10pF.	Stable singal level.	EE		
	3	57	Delete RN5711, RN5705.	Redundant parts.	EE		1	
	4	13	Delete R1331, R1332, R1308.	Redundant parts.	EE			
	5	77	Add Pi-filter.	Cure EMI.	EMC		]	
11/13	1	20	Change X2001 P/N.	Request by Sourcer.	Sourcer	,		
	2	7	Change R713 to 47R.	Fine tune damping.	EE			
	3	82	Add R8211 80.6R, R8220 150R.	Set a voltage divider to 1.8V level swing.	EE		]	
	4	21	Add R2133 1KR.	For UMA VRAM vendor selection.	EE			
11/16	1	22	Delete RN2203 pin 4, pin 5 connection.	Solve S5 leakage.	EE		]	
		2	51	Change PR5105 pull-up to +3.3V_RUN.	Prevent leakage.	EE		
	3	21	Add C2103, C2104 0.1uF.	For signal stability.	EE		]	
	4	37	Add C3718 0.1uF.	For signal stability.	EE			
	5	41	Add C4101, C4102 0.1uF.	For signal stability.	EE			
	6	49	Add PC4923 0.1uF.	For signal stability.	EE		]	
		7	66	Add C6601, C6602 0.1uF.	For signal stability.	EE		
		8	77	Add RN7713 150R.	Move impedance matching resistor from CRT/B to M/B.	EMC		]
		9	78	Change CARDBD1 pin 2 link to PLTRST#_LAN_WAN.	Change card reader chip to RTS5159 to solve EMI.	EMC		
	11/17	1	30	Add R3014, R3017, R3020 OR to link AGND and GND.	Issue for pop noise when system boot.	EE		]
	2	42,48,50	Merge 1.1V power solution on main board.	Save components.	EE, Pow	er		
		3	77	Modify CRTBD1 pin define.	Relief EMI.	EMC		]
		4	79	Add some decoupled capacitors.	Request by EMC.	EMC	<core d<="" td=""><td>/esign&gt;</td></core>	/esign>
		5	37	Change R3737 to 33R, stuff C3715 10pF.	Request by EMC.	EMC		Wistron Col 21F, 88, Sec. 1, Hsin Tai V Taipei Hsien 221, Taiwan,
		6	62,89	Sutff EC6203 22pF, PC8911, PC8907 0.1uF.	Request by EMC.	EMC	Title	Taipei Hsien 221, Taiwan,
		7	45,46,47	Stuff EC4502 0.1uF, PC4605, PC4609, PC4738 0.1uF.	Request by EMC.	EMC	Size	Change notes  Document Number
						1	Size A3	Berry AMD Discrete/UMA Thursday, March 04, 2010 Sheet 92

Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wü Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

### Change notes - Page 2

VERSON	DATE	ITEM	PAGE	Modify List	Issue Description	OWNER	
X01 11/17 8 9			9	Delete R904.	Remove redundant layout trace.	EE	7
11/18	1	81	Swap R8105, C8103 location.	Meet CRB.	EE		
		2	79	Add some decoupled capacitor.	By RF team request.	RF	
		3	49	Change PR4903 to 620KR.	Change to common part.	Power	
11/19	1	All	Synchronize with DJ schematic.	Schematic standardlize.	EE		
	-	2	48	Change P/N for PU4802, PU4803, PU4804, PU4805.	Rquest by Power team	Power	
		3	All	Review all capacitors tolerance.	Total review for deratig.	EE	
		4	21	Add RN2105 OR.	Reserve to fine tune signal quality.	EE	
		5	21	Change RN2101 to 4.7KR.	Fine tuned value for signal.	EA	
		6	37	Add RN3705, R3755 OR.	To isolate layout trace to DB1 connector.	EA	
		7	49	Change PC4908 to 2.2uF.	Changed by EA report.	EA	
	11/20	1	54	Modify R5408 connection.	To synchronize with DJ.	EE	
		2	57	Add D7701.	To prevent leakage from RGB monitor.	EE	
		3	86	Add C8626 0.1uF.	By EA report.	EA	
	4	37	Add R3756 10KR, C3720 0.1uF.	Synchronize with DJ.	EE		
	5	37	Delete RN3705, R3755.	For more layout space.	EE	1	
	6	13	Delete TP1303, TP1304.	For more layout space.	EE	1	
	7	49	Delete PR4905.	For more layout space.	EE		
		8	89	Add PC8918 0.1uF.	Stable signal quality.	EE	
	11/24	1	46,49	Change PU4601, PU4901 Power components.	Request by Power team.	Power	
	11/25	1	46,47,49,8	Change power components.	Request by Power team.	Power	
	11/29	1	10	Change C1008 to 10pF.	Fine tuned signal slew rate to meet specification.	EE	
		2	30	Change R3007 to 2.2KR.	By FAE suggestion.	EE	
X02	12/04	1	81	Set BOM mark R8104, R8106, R8107, R8110, R8111, R8112.	Implement co-layout Madison and M96.	EE	
		2	82,84	Add R8407, R8408 OR.	Implement co-layout Madison and M96.	EE	
		3	80	Add R8016 10KR.	Implement co-layout Madison and M96.	EE	
		4	83,84	Set BOM mark.	Implement co-layout Madison and M96.	EE	
		5	83	Add L8306, L8307, C8397, R8301, R8302, R8303.	Implement co-layout Madison and M96.	EE	
	12/05	1	37	Change R3756, C3720 connection.	Correct soft-start for EC power.	EE	
	12/08	1	90	Set BOM mark.	Implement co-layout Madison and M96.	EE	
	12/15	1	15	Delete RN1501, Add G1501~G1504.	Synchronize with DJ and supply sufficient power rail.	EE	
		2	62	Add R6207 100KR.	Insure SPI Write-Protect pin signal level.	EE <cor< td=""><td>e Design&gt;</td></cor<>	e Design>
		3	66	Change C6602 net name.	Correct signal name.	EE	Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wü Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
		4	81	Add R8122 1KR, RN8101 4.7KR.	Meet M96 schematic check list.	EE Title	Taipei Hsien 221, Taiwan, R.O.C.
		5	82	Swap CLK_VGA_27M_NSS and CLK_VGA_27M_SS connection.	Solve external RGB display tremble issue.	EE Size	Change notes Document Number Rev
						Size A3	Berry AMD Discrete/UMA Thursday, March 04, 2010 Sheet 93 of 95

### Change notes - Page 3

Change			<del></del>		<u> </u>	í	
VERSON	DATE	ITEM	PAGE	Modify List	Issue Description	OWNER	
X02	12/16	1	66	Change R6605 to OR.	Assure power button level set to low.	EE	
		2	37,76	Add net "8103_GPO".	Implement LAN DSM hardware function.	EE	
	12/17	1	37	Add U3703.	To solve SPI WP signal malfunction on EC.	EE	
	12/18	1	82	Add R8222 1MR.	Assure crystal resonant clock stable.	EE	
		2	81	Set VRAM reset circuit.	Follow M96 reset circuit and reseve BOM option.	EE	
	12/25	1	18	Change TC1801 to 330uF, 2V tolerance.	Implement common part for 1.5V power rail.	EE	
		2	46	Change PR4603 to 127KR.	Set 5V current limitation.	Power	
		3	46	Empty PR4618 and stuff PR4619.	Set Ultra-sonic mode to keep +15V_ALW voltage level.	Power	
		4	10	Set RN1006 PU to +1.5V_SUS.	Follow AMD check list and cure +1.5V_RUN leakage.	EE	
		5	62	Change R6206 to 1KR.	According to Safety request, verified OK.	Safety	
		6	51	Change PR5102 1KR, PR5106 8.2KR, PR5107 5.62KR.	Set VDDR low voltage level to 0.9V.	EE	
	12/29	1	10,37	Add Q1005, R1039, R1040.	Request by AMD to set CPU into HTC mode in DOS.	EE	
		2	47	Change PR4720 93.1KR, PR4721 24KR.	Set power OCP value.	Power	
	12/31	1	ALL	Change some resistors as short-pad or resistor array.	Save component counts.	EE	
		2	ALL	Change some capacitors with smaller value or empty.	Save component counts.	EE	
	01/04	1	15	Change R1507,R1508,R1509,R1510,R1511 to bead.	Filter power noise.	EMC	
	01/05	1	7	Combine R707,R721 as RN711.	For more layout space.	EE	
		2	81	Delete TP8101,TP8102.	Remove useless test point for more layout space.	EE	
		3	7,80	Delete R716,R8020, combine R8009,R8010 as RN8001.	Redundant part.	EE	
		4	37,39,41	R3747,R4104 short pad, delete R3722,R3904.	Redundant part.	EE	
		5	46	Change PR4620 as short pad.	Redundant part.	EE	
		6	51	Change PQ5101 with ESD protector.	Change to common part.	Power	
		7	54	Empty R5405 and Stuff R5408.	Avoid LCD white panel.	EE	
		8	62	Change R6205 to OR.	Already have one 1KR ahead.	EE	
	01/06	1	50	Add PR5004 10KR and empty PR5002.	Avoid +1.1V_ALW leakage in South Bridge.	EE	
		2	13	Change R1342 to size 0603.	Synchronous schematic w/DJ.	EE	
		3	79	Add R7921 and R7922.	Reserved RF team solution.	RF	
	01/07	1	7	Add RN712,C722,C723	Reserve for SMBus signal quality tuning.	EE	
		2	60	Change EC6007, EC6008 to 0.01uF.	According FAE Request.	IDT FAE	
		3	39	Add Q3904.	According thermal team request.	Thermal	
		4	21,18	Change location RN2105 to RN1801, add C1823,C1824.	For SMBus signal quality fine tune.	EE	
		5	39,82,83	Remove C3912, TP8301, TP8302, TP8213.	Remove dummy part for more layout space.	EE	<core d<="" td=""></core>
		6	76	Reserve C7601, C7602.	Fine tune USB signal quality.	EE	
	01/08	1	79	Reserve EC7925,EC7926,EC7927.	Reserve by EMC team.	EMC	Title
		2	77	Change RN7711 to OR, L7701,L7702,L7703 to bead 22R.	According EMC measurement result.	EMC	
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X02 01 01 01 01	DATE I 01/08  01/11  01/12  01/13  01/14  02/08	3 4 5 1 2 1 2 1 2	PAGE  18,19  37  ALL  68  66  37  10  21,37  Power	Modify List  Add C1825,C1922.  Reserve C3721,C3722.  Change capacitors value and add C3723.  Change KB1 P/N.  Change R6601,R6602,R6604,R6606 to 1KR, R6603 to 470R.  Add C3724, R3757.  Add R1041 0R.  Add C3725, C2105.	Issue Description  Reduce V_REF ripple by EA team result.  Prevent signal cross talk.  Ensure signal quality.  According ME request.  Decrease LED brightness.  To set accurate current detection in EC.  Add OR for level shift off.	OWNER  EE  EE  ME  EE  EE	-		
01	01/11 01/12 01/13 01/14	4 5 1 2 1 2 1	37 ALL 68 66 37 10 21,37	Reserve C3721, C3722.  Change capacitors value and add C3723.  Change KB1 P/N.  Change R6601, R6602, R6604, R6606 to 1KR, R6603 to 470R.  Add C3724, R3757.  Add R1041 OR.	Prevent signal cross talk.  Ensure signal quality.  According ME request.  Decrease LED brightness.  To set accurate current detection in EC.	EE EE ME EE	-		
01	01/12	5 1 2 1 2 1	ALL 68 66 37 10 21,37	Change capacitors value and add C3723.  Change KB1 P/N.  Change R6601,R6602,R6604,R6606 to 1KR, R6603 to 470R.  Add C3724, R3757.  Add R1041 OR.	Ensure signal quality.  According ME request.  Decrease LED brightness.  To set accurate current detection in EC.	EE ME EE EE	-		
01	01/12	1 2 1 2 1	68 66 37 10 21,37	Change KB1 P/N.  Change R6601,R6602,R6604,R6606 to 1KR, R6603 to 470R.  Add C3724, R3757.  Add R1041 OR.	According ME request.  Decrease LED brightness.  To set accurate current detection in EC.	ME EE EE			
01	01/12	2 1 2 1	66 37 10 21,37	Change R6601,R6602,R6604,R6606 to 1KR, R6603 to 470R.  Add C3724, R3757.  Add R1041 OR.	Decrease LED brightness.  To set accurate current detection in EC.	EE	_		
01	01/13	1 2 1	37 10 21,37	Add R1041 OR.	To set accurate current detection in EC.	EE			
01	01/13	2 1 1	10 21,37	Add R1041 OR.					
	01/14	1	21,37		Add OR for level shift off.	77			
	01/14	1		Add C3725, C2105.		EE			
01			Power		Reserve for singal quality.	EE			
	02/08	2		Modify power team componets.	Request by Power Team.	Power			
	02/08		7	Change RN712 to 22R.	Fine tuned damping resistor value.	EE			
A00 02	02/00	1	66	Reserve R6609, R6610 1KR.	Add for future LED brightness balance.	EE			
		2	68	Add keyboard back light circuit, remove R5403.	Add for keyboard with back light module.	EE			
		3	69	Change HALLSW1 footprint for co-layout.	Change for co-layout different kind of HALLSW1.	EE			
	Γ	4	77	Add AFTP7701, AFTP7702, AFTP7703.	Add AFTP test point for factory test.	EE			
02	02/10	1	Power	Update Obsolete parts.	Update obsolete parts due to policy.	Power			
		2	79	Change HBT1 part number.	Change HBT1 part number to match ME EMN file.	ME			
		3	47	Add PTC4710.	Add to solve board accoustic issue.	EE			
02	02/22	1	54	Remove co-layout pad.	As factory requst.	EE	0308-1		
		2	42	Add C4217, C4401, C4402.	Ensure signal quality.	EE			
		3	48	Delete Power Gap.	Request by Power Team.	Power			
02	02/23	1	ALL	Change to short pad.	Change most of 0-ohm resistors to short pad.	EE			
02	02/24	1	7,68,79	Reserve C724, C725, C6806, C6807, EC7928-EC7932.	As EMC team request.	EMC			
02	02/25	1	13	Add TP1309.	As factory requset to add.	Factory			
		2	7,68	Rename EMC capacitor to EC704,EC705,EC6801,EC6802.	Meet schematic standardization.	EE			
		3	49,89	Change PR4913 to 3.9R, PR8905 to 6.98KR.	PR4913 for snubber, PR8905 for OCP.	Power			
	Ī	4	21	Change R2133 to OR.	Set GPIO input level from 0.5V to 0V.	EE			
		5	79	Remove EC7928.	Layout space limitation.	EE			
02	02/26	1	39,42	Empty R3906 and Change R4202 from OR to 1KR.	It is for solving T8 shutdown issue.	EE			
03	03/03	1	60	Change SPK1 part number.	Request by ME.	ме			
03	03/05	1	20,24,37	Empty R2029,R2404,R3751.	Saving unused components.	EE			
03	03/08	1	48	Stuff PU4803 and empty PU4804.	Place the H/S and L/S MOS at the same surface.	Power			
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